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**Optimization of Cooled Shields in Insulations**

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Space Administration

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## ABSTRACT

A relatively simple method has been developed to optimize the location, temperature, and heat dissipation rate of each cooled shield inside an insulation layer. The method is based on the minimization of the entropy production rate which is proportional to the heat leak across the insulation. The results show that the maximum number of shields to be used in most practical applications is three. However, cooled shields are useful only at low values of the overall, cold wall to hot wall absolute temperature ratio. The performance of the insulation system is relatively insensitive to deviations from the optimum values of temperature and location of the cooling shields.

Design curves are presented for rapid estimates of the locations and temperatures of cooling shields in various types of insulations, and an equation is given for calculating the cooling loads for the shields.

## NOMENCLATURE

A	Area of heat flow, $\text{m}^2$
$c_p$	Specific heat of the boiloff vapor, $\text{kJ/kg}\cdot\text{K}$
D	Functional defined by Eq. (14)
F	Functional defined by Eq. (13)
$h_{fg}$	Latent heat of vaporization of the boiloff liquid, $\text{kJ/kg}$
$k$	Thermal conductivity, $\text{W/m}\cdot\text{K}$ ; with subscripts, coefficients in Eq. (1)
L	Overall thickness of insulation, $\text{m}^*$
$m, n$	Exponents in conductivity function, Eq. (1)
P	$T_S/T_C$ , temperature ratio
q	Heat flow rate, $\text{W}$
R	$T_C/T_H$ , overall temperature ratio
s	Dimensionless entropy production rate defined by Eq. (5)
$\dot{S}$	Entropy production rate, $\text{W/K}$
t	Thickness between walls with single shield between, $\text{m}^*$
T	Absolute temperature, $\text{K}$
x	Distance from cold wall, $\text{m}^*$
$x'$	Distance from cold wall in a multi-shield configuration, $\text{m}^*$
X	$x/t$ , dimensionless distance*
$X'$	$x'/L$ , dimensionless distance*
Y	Defined by Eq. (8)

Subscripts

C	Cold wall
H	Hot wall
i	i-th shield
min	Minimum
opt	Optimum
S	Shield

\*For systems with single shield  $L = t$ ,  $x = x'$ ,  $X = X'$ .

## INTRODUCTION

The search for the ultimate, energy efficient insulation system has led in the past few years to a fascinating rediscovery and application of some fundamental concepts of thermodynamics: specifically, the second law and the use of entropy production rates and availability (or exergy) for design optimization purposes. The classical approach has been to minimize the heat flow between surfaces at different temperatures.

The concept of a single vapor-cooled shield in an insulation has been treated theoretically as far back as 1959 in Scott's classic textbook on cryogenics [1] and designs employing them were described not much later [2]. Paivanas, et al., obtained a patent [3] and later reported on the use of uniformly spaced multiple shields which were cooled by the boil-off from the insulated dewar [4]. Eyssa and Okasha [5] considered only radiative heat exchange between shields and minimized the total refrigeration power required. Hilal, et al., [6,7] used a similar minimization of refrigeration power as the design basis. Related works were reported by Bejan, et al., [8-11].

Recently, Bejan [12] proposed a new point of view, based on the second law of thermodynamics, which considers thermal insulations as dissipators of useful mechanical power (i.e. the availability or exergy) or, alternately, as generators of irreversibility or entropy. Thus, in this method, optimization of an insulation corresponds to minimization of either the entropy production rate or the irreversibility, or the decrease of availability. Various applications of this concept to insulation systems have been documented subsequently [13,14].

Our work grew out of an examination of Cunningham's paper [13] who utilized a numerical technique to find optimum temperatures at given locations for one and two shields for a thermal conductivity function of the form

$k_1 T^{0.6}$ . Although several equations seemed to be incorrectly printed we have found two of the design curves to be essentially correct. Thus, our purpose was

1. To develop a simple optimization technique;
2. To generalize the results to a broader class of insulations; and
3. To develop simple design methods for cooled shields.

The essentials of this report were already published [15].

## ANALYSIS

We accept the previously developed concept that to optimize an insulation system is equivalent to minimizing the entropy production rate. In addition, we assume one-dimensional heat flow and that the heat capacity of the boil-off gas is adequate to do the cooling for all shields and does not impose a restriction on the optimization. In contrast to Rejan [9,11] who has developed a constrained optimization based on the heat capacity of the boiloff we employ the argument that in all practical systems the boil-off is generated by cooling of some equipment in addition to the heat leakage across the insulation.

Parallel heat paths, e.g. supports, have not been considered. However, each path can be optimized separately using its own thermal conductivity function. Then a design decision has to be made whether the two structures should be independently cooled at their respective optimum conditions.

We examine the general situation of an insulation where equivalent thermal conductivity,  $k$ , can be expressed as a two-term function of the absolute temperature

$$k = k_1 T^m + k_2 T^n \quad (1)$$

where, typically, the first term represents actual conduction with  $m \geq 1$  and the second term represents radiation with  $n \geq 3$ . In the following,  $m$  and  $n$  can be any value except -1.

The heat flow across a layer of insulation can be expressed in terms of Fourier's law

$$q dx = Ak dT \quad (2)$$

Substituting  $k$  from Eq. (1) and integrating across a layer from one end at 1, to the other at 2, yields

$$q = \frac{A}{x_2 - x_1} \left[ \frac{k_1}{m+1} (T_2^{m+1} - T_1^{m+1}) + \frac{k_2}{n+1} (T_2^{n+1} - T_1^{n+1}) \right]. \quad (3)$$

Now consider the insulation with a cooled shield at  $T_S$  located at  $x$  between a hot surface at  $T_H$  and a cold one at  $T_C$ , separated by the insulation thickness,  $t$ , as shown in Fig. 1a. The entropy production rate for the insulation can be determined from the heat flows and temperatures as follows

$$\dot{S} = - \frac{q_H}{T_H} + \frac{q_C}{T_C} + \frac{q_S}{T_S} \quad (4)$$

where  $q_S = q_H - q_C$ .

The heat flow terms can be expressed in the form of Eq. (3) and the resulting expression can be non-dimensionalized using the following terms

$$s \equiv \frac{St}{Ak_H} \text{ where } k_H = k \text{ at } T_H, \quad (5)$$

$$p \equiv \frac{T_S}{T_C}, \quad (6)$$

$$r \equiv \frac{T_C}{T_H}, \quad (7)$$

$$\gamma \equiv \frac{k_2(m+1)}{k_1(n+1)} T_H^{n-m}, \quad (8)$$

and

$$x \equiv \frac{x}{t}. \quad (9)$$

The resulting equation is

$$\begin{aligned}
 & s(m+1)(1 + \gamma \frac{n+1}{m+1}) \\
 & = \frac{1}{1-X} \{[(PR)^m + 1 - (PR)^m - 1 + (PR)^{-1}] \\
 & + \gamma[(PR)^{n+1} - (PR)^n - 1 + (PR)^{-1}]\} \\
 & + \frac{1}{X} \{R^m[P^{m+1} - P^m - 1 + P^{-1}] \\
 & + \gamma R^n[P^{n+1} - P^n - 1 + P^{-1}]\} \tag{10}
 \end{aligned}$$

Since  $R$ , the overall temperature ratio, is generally known,  $s$  is a function of  $P$  and  $X$ , and its extreme value can be found by differentiating it with respect to each variable separately and setting the results equal to zero. This procedure yields two equations to be solved simultaneously:  $\partial s / \partial P = 0$  and  $\partial s / \partial X = 0$ . Because of the regular form of the expressions, one of the final two equations contains only a single unknown as follows:

$$\begin{aligned}
 & \frac{R^m F(m, P) + \gamma R^n F(n, P)}{[R^{m-1} D(m, P) + \gamma R^{n-1} D(n, P)]^2} \\
 & = \frac{F(m, PR) + \gamma F(n, PR)}{[D(m, PR) + \gamma D(n, PR)]^2} \tag{11}
 \end{aligned}$$

$$\frac{X}{1-X} = - \frac{R^{m-1} D(m, P) + \gamma R^{n-1} D(n, P)}{D(m, PR) + \gamma D(n, PR)} \tag{12}$$

where the following functionals were used:

$$F(b, B) \equiv R^{b+1} - B^b - 1 + B^{-1} \quad (13)$$

$$D(b, B) \equiv (b + 1) B^b - b B^{b-1} - B^{-2}. \quad (14)$$

Thus, to find the optimum temperature and location for a shield, Eq. (11) can be solved for  $P$ , and then  $X$  can be calculated from Eq. (12). The heat to be removed by the shield,  $q_S = q_H - q_C$ , can be found, as before, from Eq. (3). In dimensionless form the equation becomes

$$\begin{aligned} \frac{q_S t}{A k_H T_H} (m+1) \left(1 + \gamma \frac{n+1}{m+1}\right) \\ = \frac{1 - (PR)^{m+1} + \gamma [1 - (PR)^{n+1}]}{1 - X} \\ - \frac{(PR)^{m+1} - R^{m+1} + \gamma [(PR)^{n+1} - R^{n+1}]}{X}. \end{aligned} \quad (15)$$

For multiple shields  $t_i$  represents the distance between the two surfaces surrounding the  $i$ -th shield on either side,  $T_{H,i}$  and  $T_{C,i}$  are the temperatures of these two surfaces,  $X_i = x_i/t_i$  is the location of the shield relative to  $t_i$ , and  $x'_i$  is the location of the shield relative to the cold wall as shown in Fig. 1b. To determine the optimum temperatures and locations for multiple shields, first we assumed a temperature for the first shield next to the cold wall, then we used Eqs. (11) and (12) to find the temperature and location of the second shield. This process was repeated for the rest of the shields and the hot wall. Thus, each shield was optimized consecutively with respect to the two surfaces on either side. With given values of the overall temperature ratio,  $R$ , and of the number of shields, the process requires iterative solution.

To put the results into proper perspective, the entropy production rates can be compared to the thermodynamically minimum rate obtainable through spatially continuous cooling. According to Bejan [12], this rate is

$$\dot{S}_{min} = \frac{A}{t} \left[ \int_{T_C}^{T_H} (k)^{1/2} T^{-1} dT \right]^2. \quad (16)$$

This expression was evaluated analytically for the single-term functions of  $k$ , i.e. for  $\gamma = 0$ , and numerically otherwise.

## RESULTS AND DISCUSSION

The first set of curves, Figs 2 through 9, show the relative entropy production rates for various thermal conductivity functions and for up to four optimally cooled shields as functions of the overall temperature ratio  $R \equiv T_C/T_H$ . The curves show that the entropy production rate increases with decreasing values of the temperature ratio,  $R$ , and with increasing values of the exponent,  $m$  and  $n$ . Adding shields, of course, reduces the entropy production rate; but for most of the practical temperature range, say  $0.01 < R < 0.4$ , only three shields contribute to significant decreases and adding a fourth shield can be considered unnecessary. No shields are useful at high values of  $R$ ; but this "high" range is strongly dependent on the exponent of the temperature. The curves developed with  $k = k_1 T^{0.6}$  for one and two shields were very close to those given by Cunningham [13], converted appropriately.

Study of the results of two-term conductivities reveals that the curves fall between those obtained for each of the two terms alone. If  $\gamma$  is small the first term,  $T^m$ , dominates; whereas if  $\gamma$  is large ( $>10$ ), the second term,  $T^n$ , controls. Thus, general conclusions can be drawn from examining the results of the single-term conductivities.

The second set of curves, Figs. 10 through 31, show the optimum temperature ratios,  $T_S/T_H$ , and optimum locations,  $x'/L$ , of cooled shields as functions of the overall temperature ratio,  $T_C/T_H$ , for various thermal conductivity functions and with different number of cooled shields.

Figures 10 and 11 show the optimum single shield temperature ratios,  $PR = T_S/T_H$ , and locations,  $X = x/L$ , for five conductivity functions. Both of these functions generally decrease with decreasing  $R$ . The other figures in this set show shield temperatures and locations for systems with up to three

shields and for both single-term and two-term conductivities. The results are strongly non-linear. For example, for  $k_1 T^3$  and  $R = 0.01$ , the optimum temperature ratios for three shields are about 0.09, 0.3, and 0.6 and the optimum locations are about 0.05, 0.2, and 0.5. As is to be expected, our unconstrained optimization yields a somewhat better performance per shield than Bejan's [9,11] constrained method.

The sensitivities of the entropy production rates to deviations from the optimum values of PR and X are demonstrated in the last set of curves, Figs. 32 through 35, for single shields. The sensitivity increases with the value of the exponents, m and n, but the curves are relatively flat near the minima. A  $\pm 20$  percent change from optimum, for example, has negligible effect. Thus, the system is relatively tolerant of deviations from the optimum design conditions.

Calculations with two different conductivities on the two sides of a cooled shield show that using the better insulator on both sides always yields the optimum condition. However, if for some reason two types of insulations have to be used, then the better insulator should be placed on the warm side of the shield.

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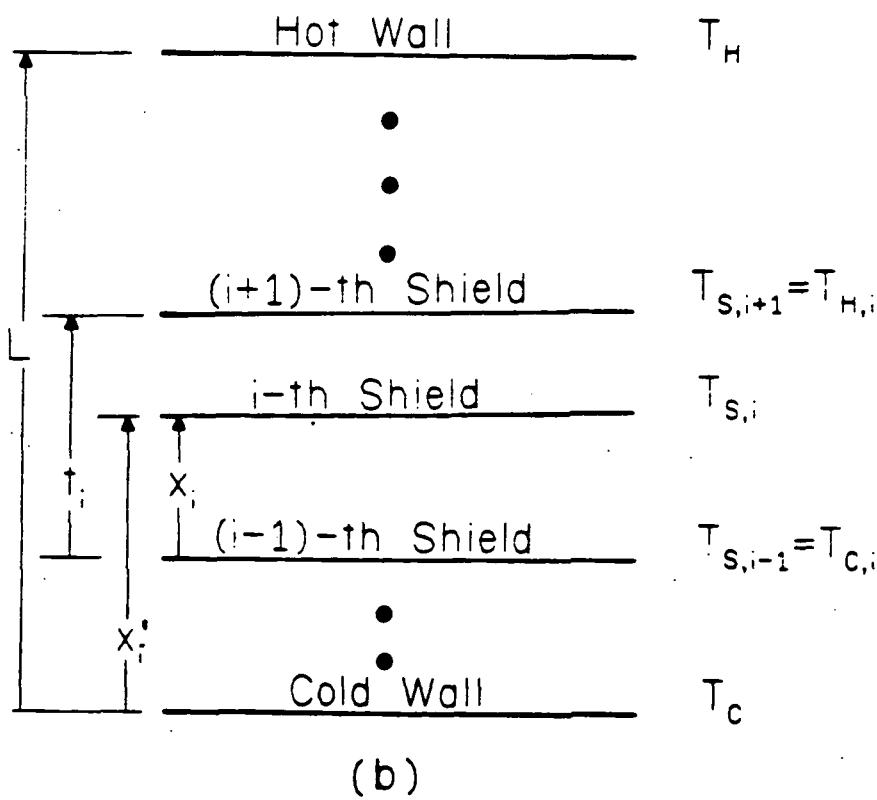
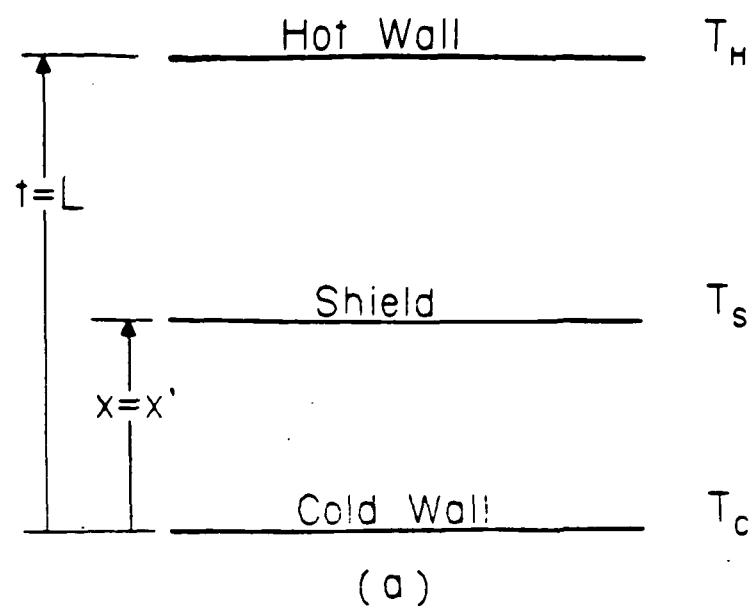


Figure 1 Schematic of the Nomenclature for (a) Single and (b) Multiple Shields

Curve Set 1: Figures 2 through 9

The effect of optimally cooled shields on  
the entropy production rate for various thermal conductivities.

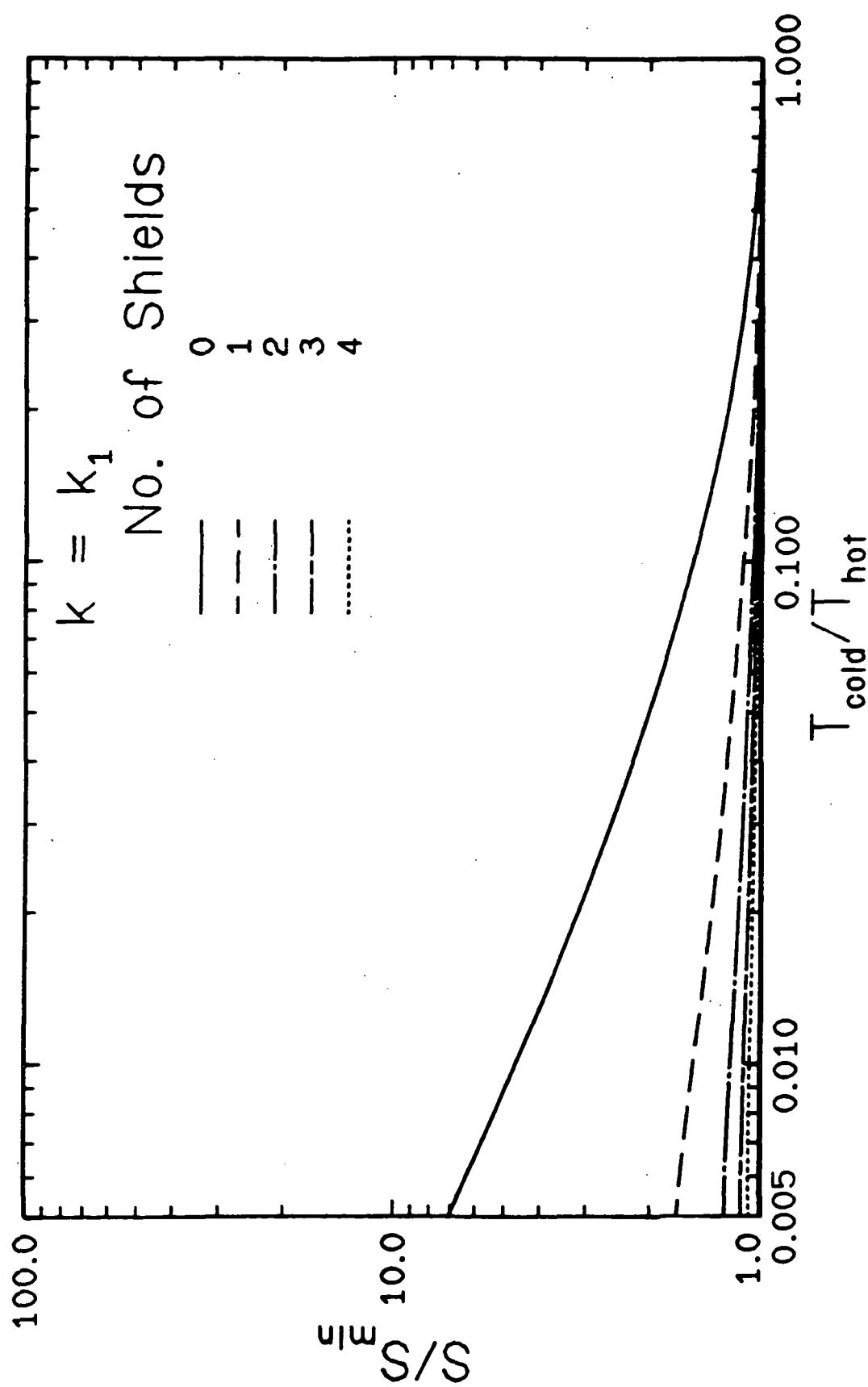


Figure 2

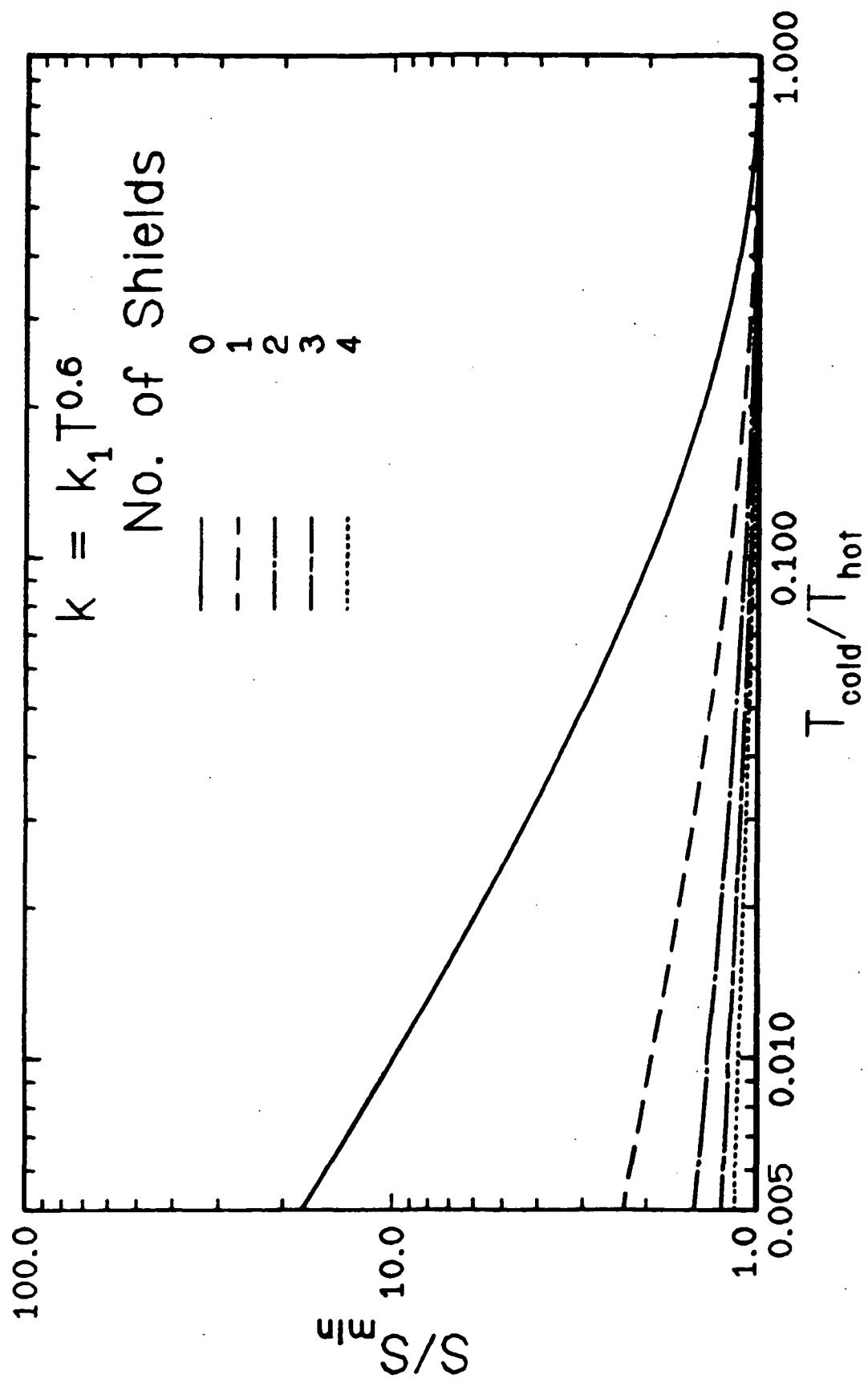


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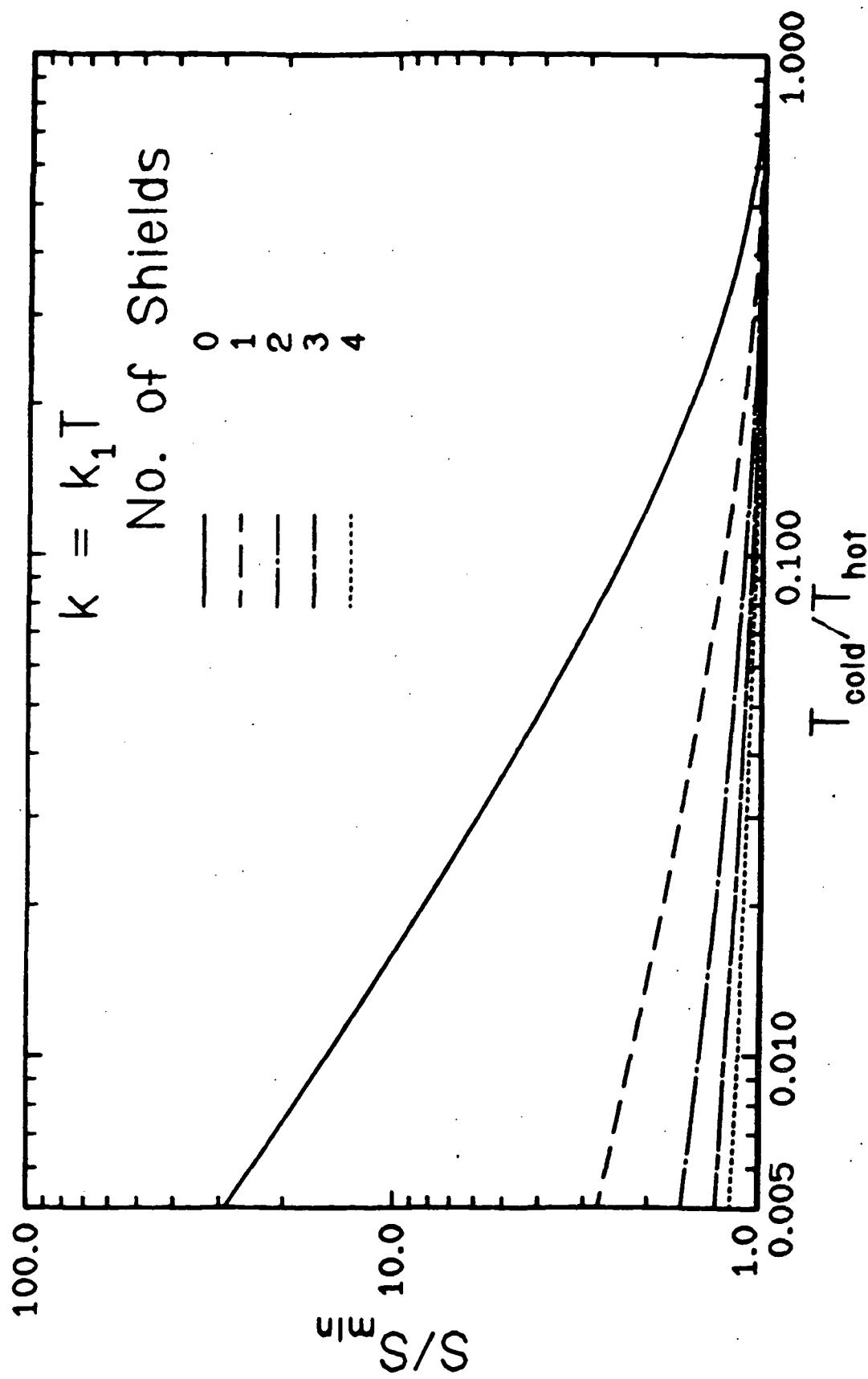


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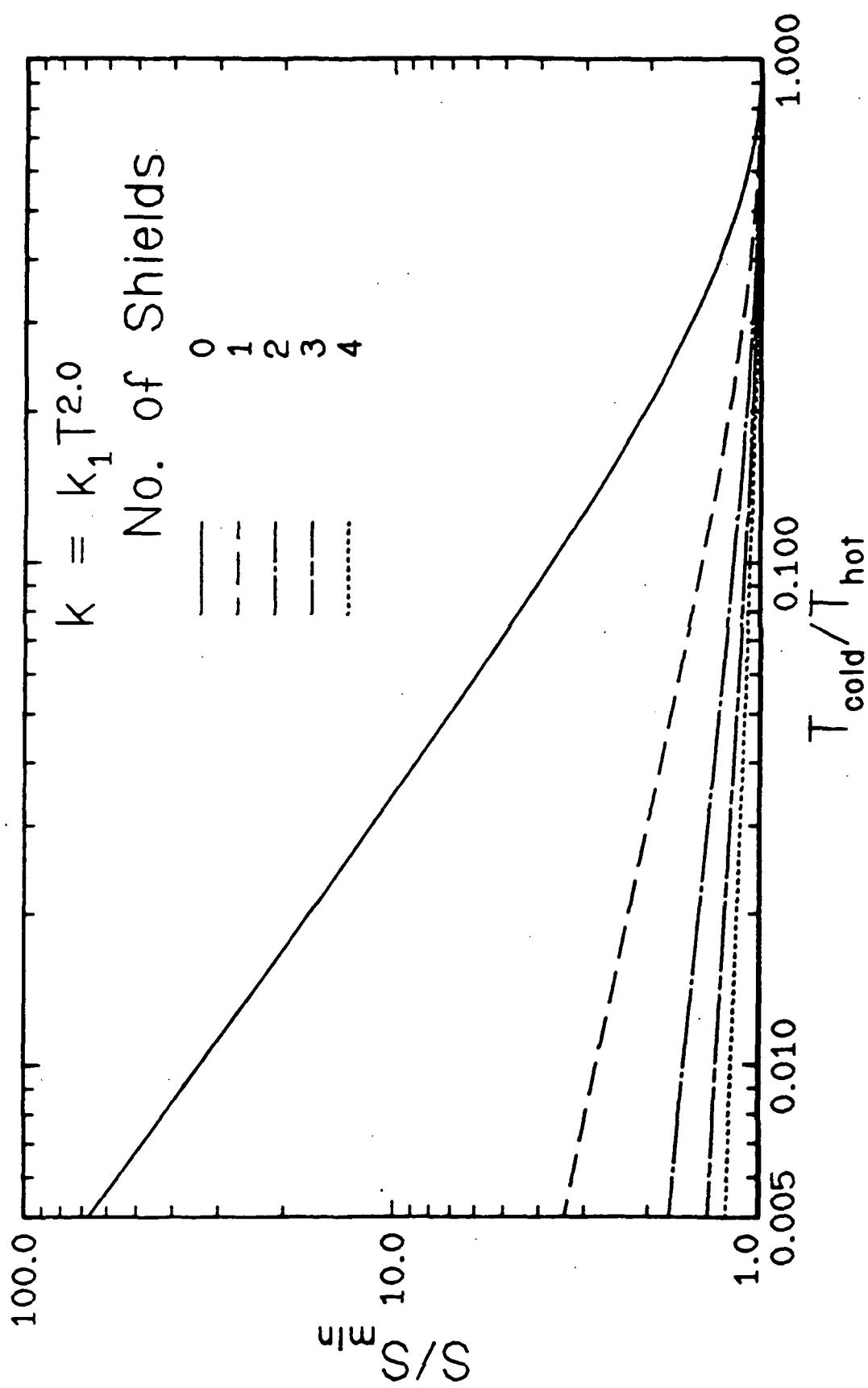


Figure 5

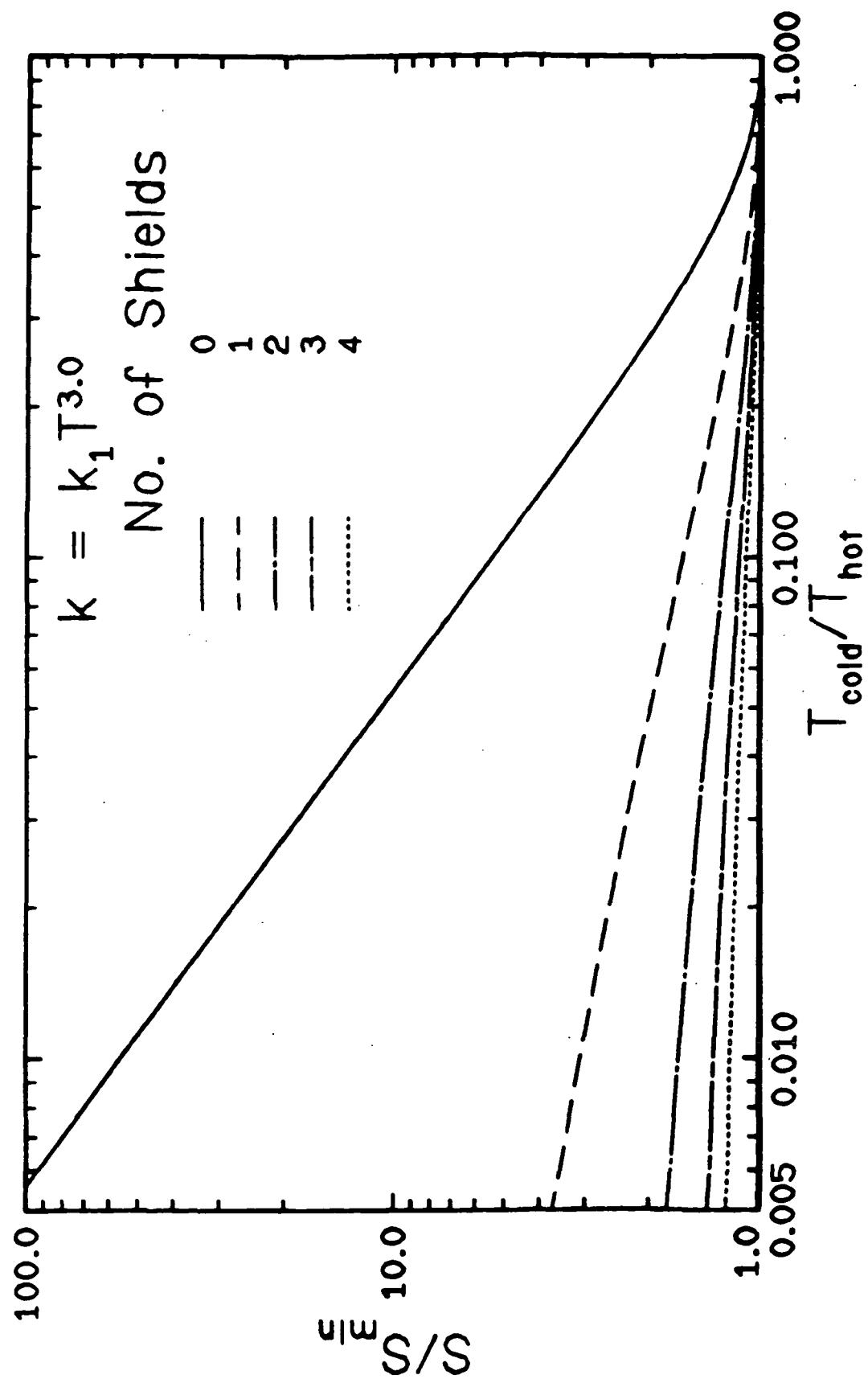
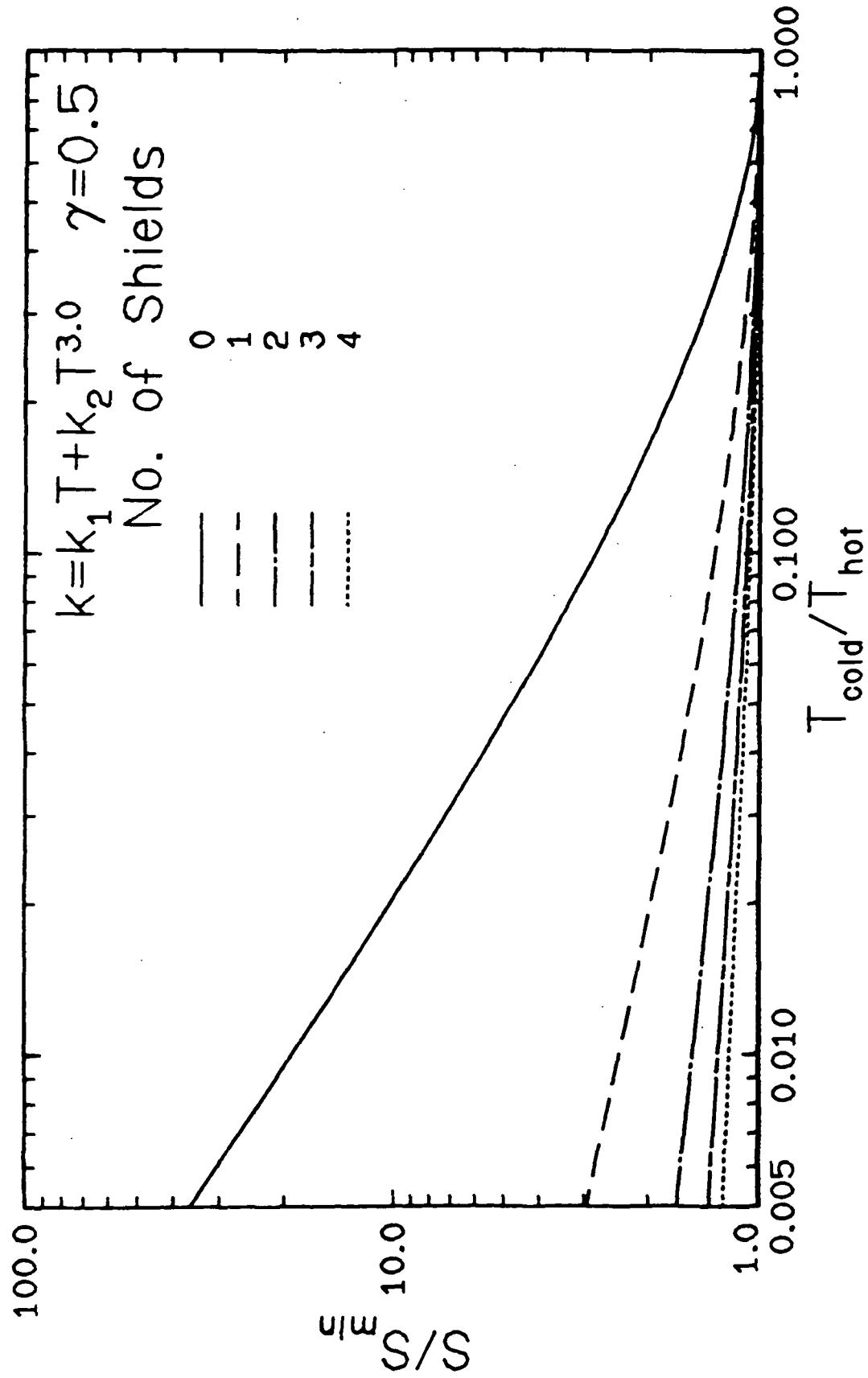


Figure 6



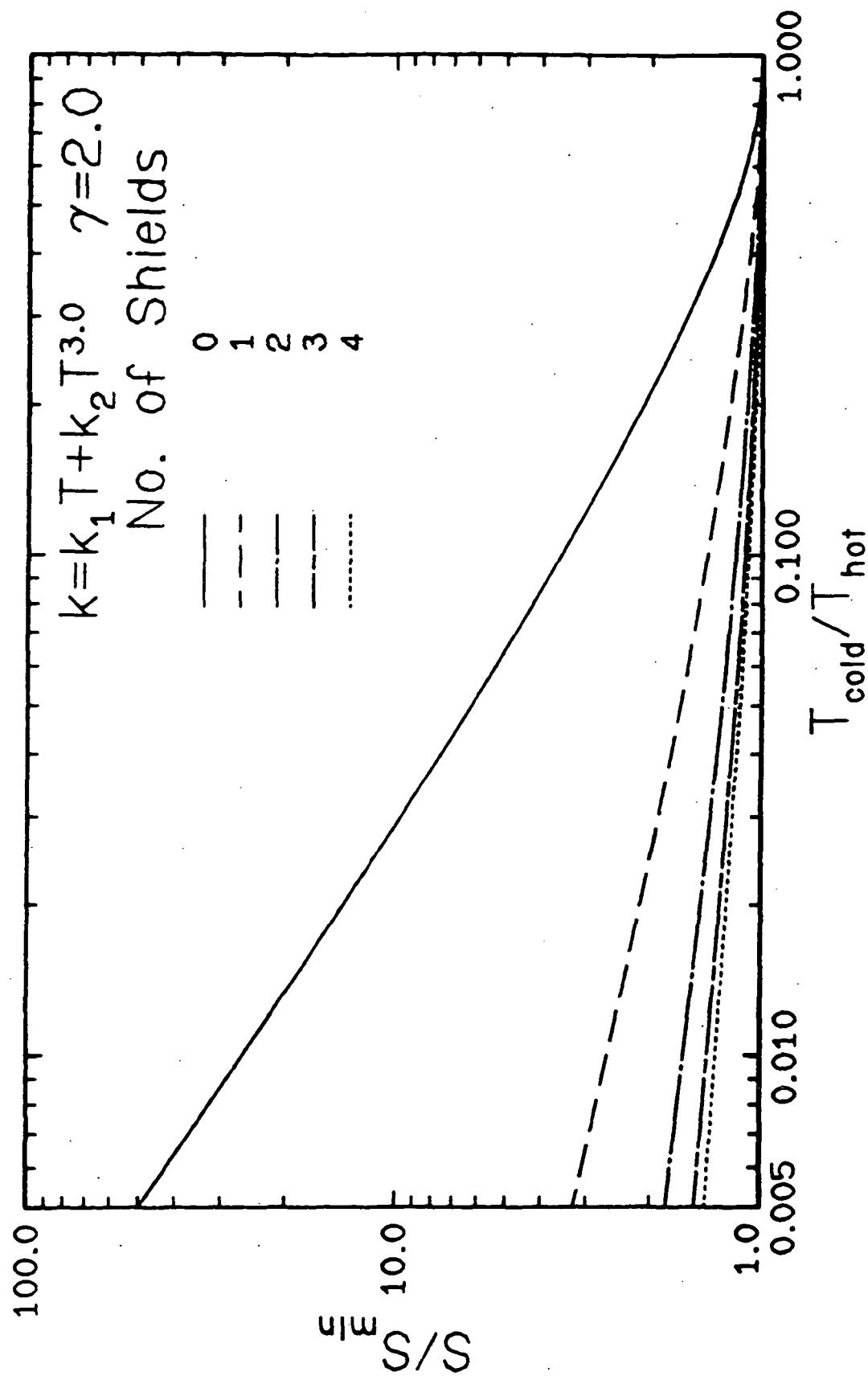


Figure 8

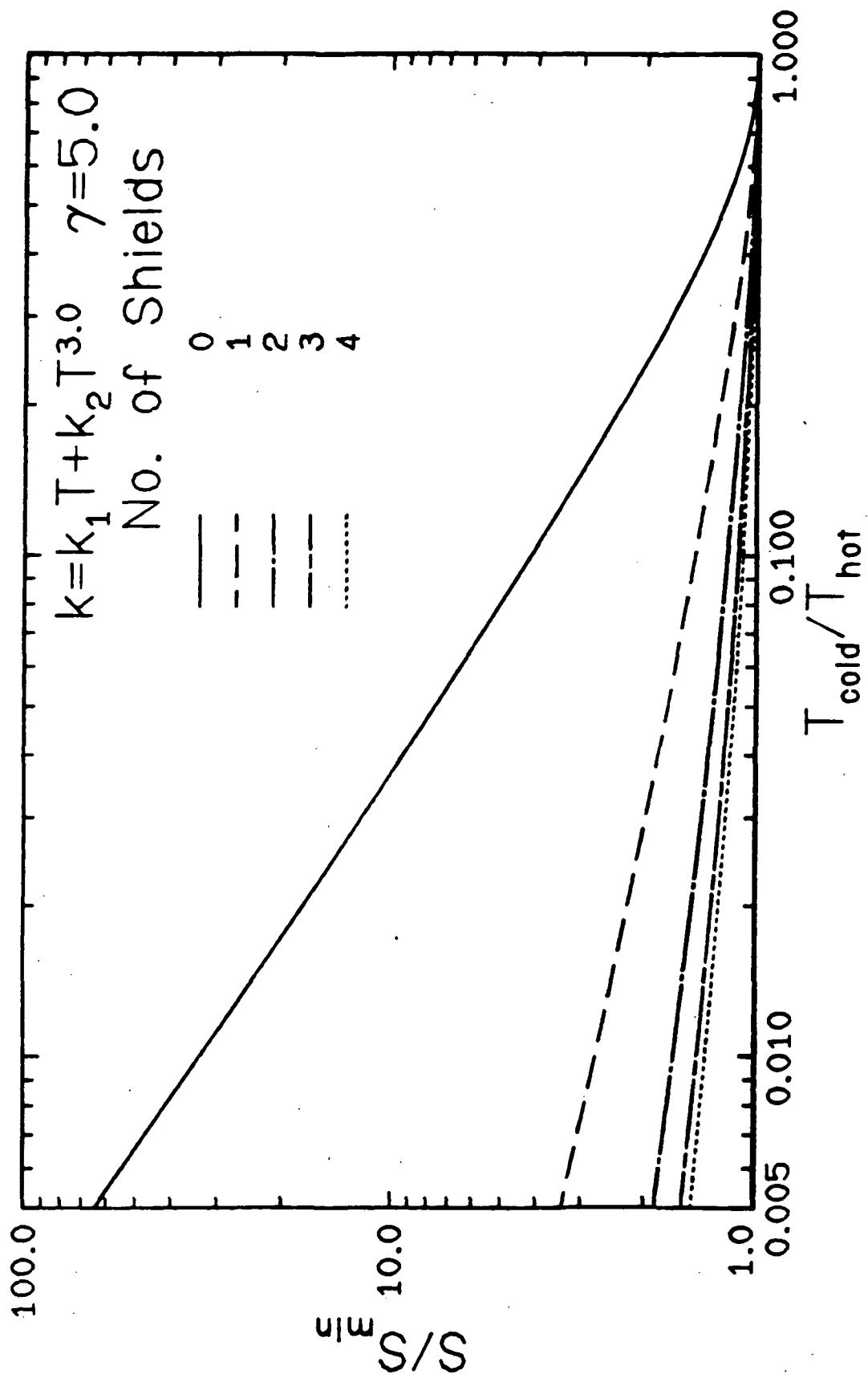


Figure 9

**Curve Set 2: Figures 10 through 31**

**Optimal shield temperatures and locations for various thermal conductivity functions with different number of shields.**

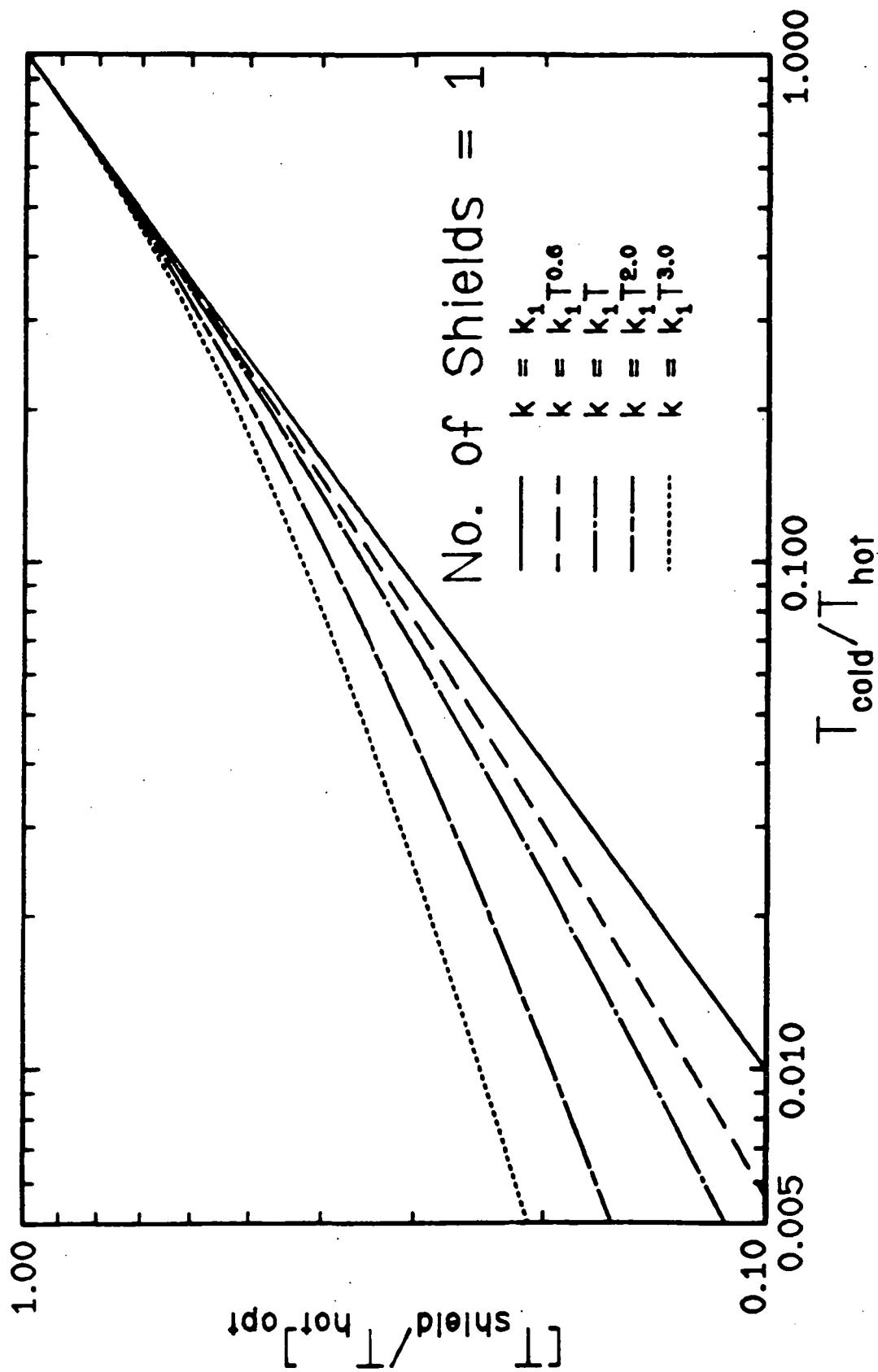


Figure 10

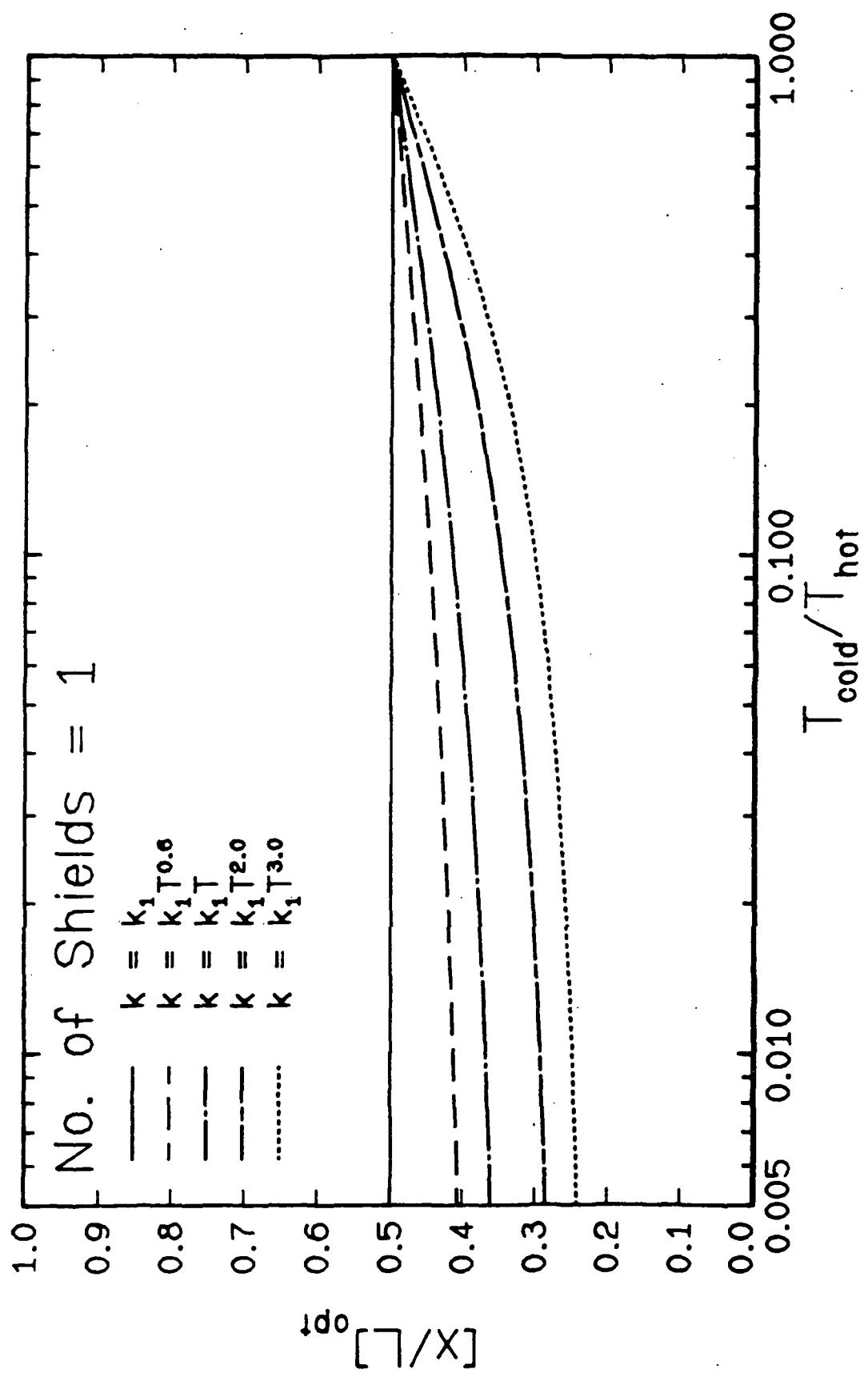


Figure 11

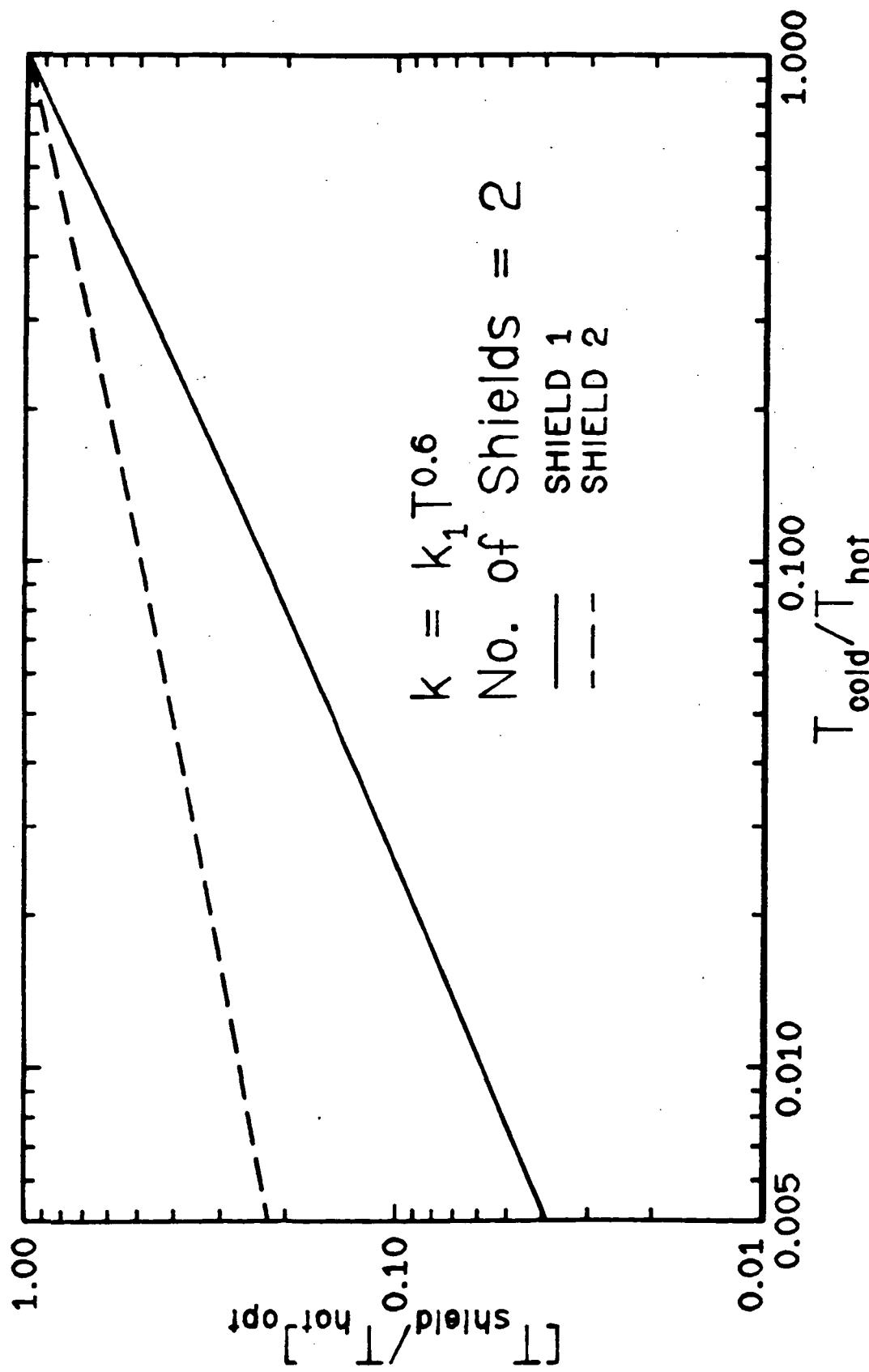


Figure 12

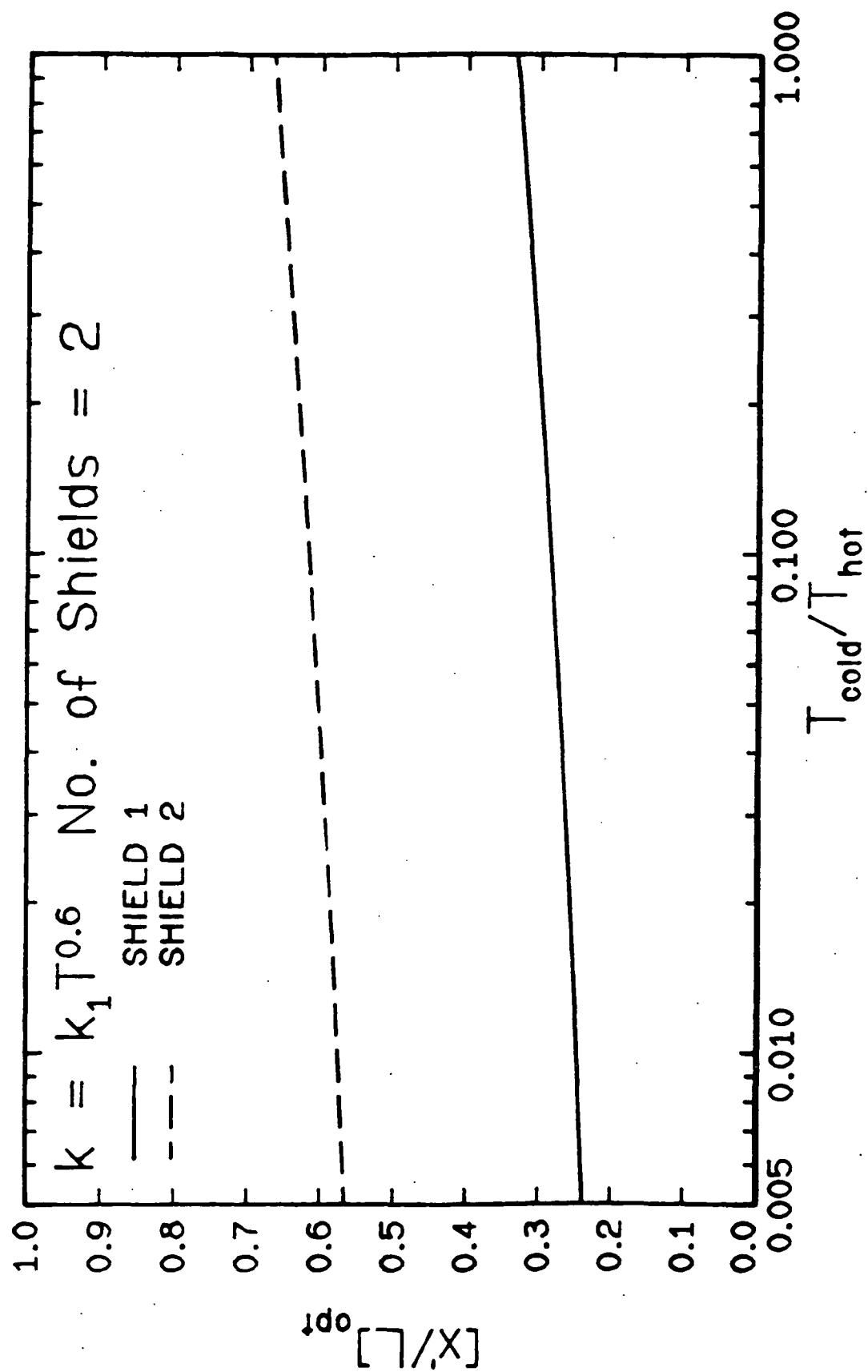


Figure 13

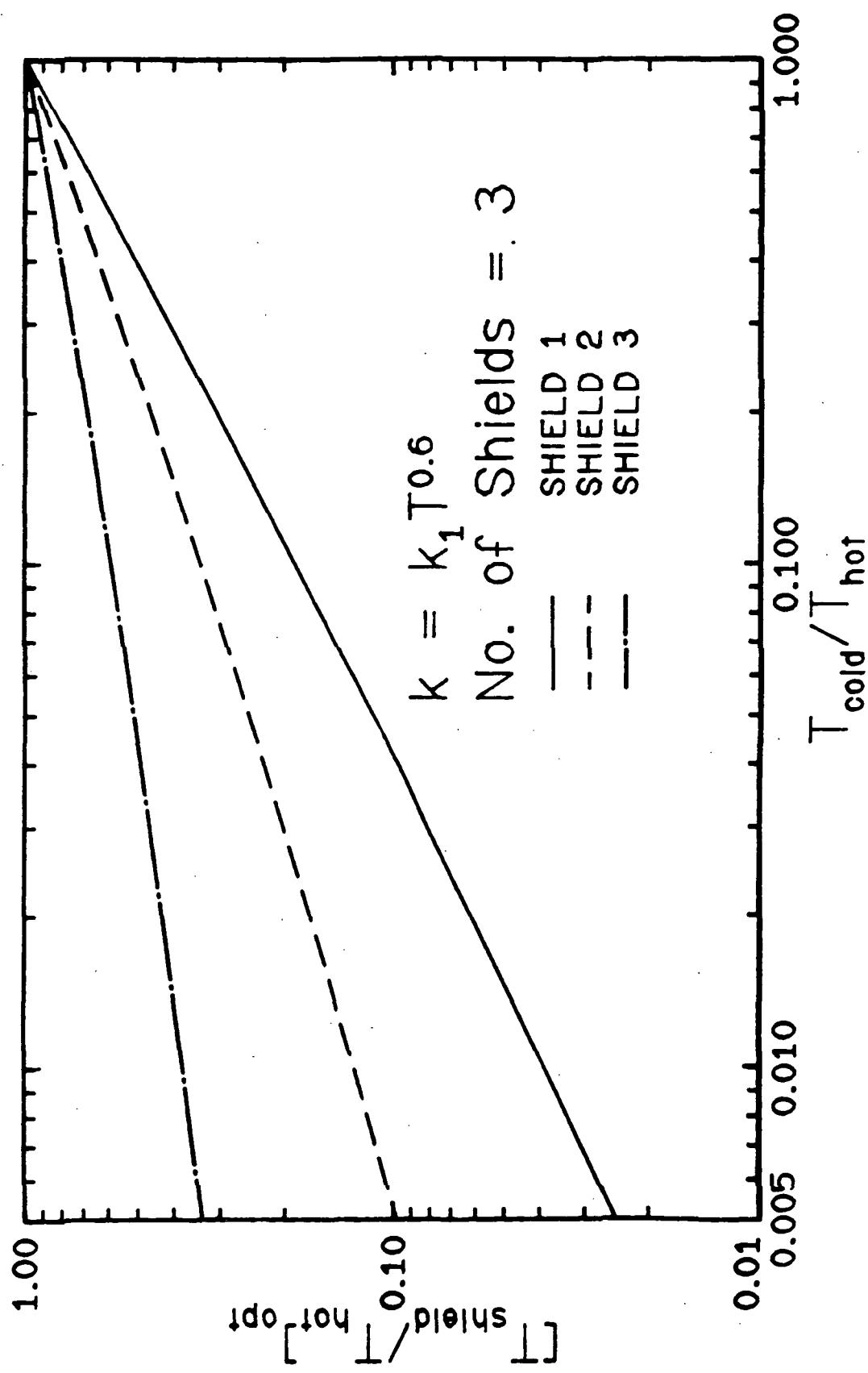


Figure 14

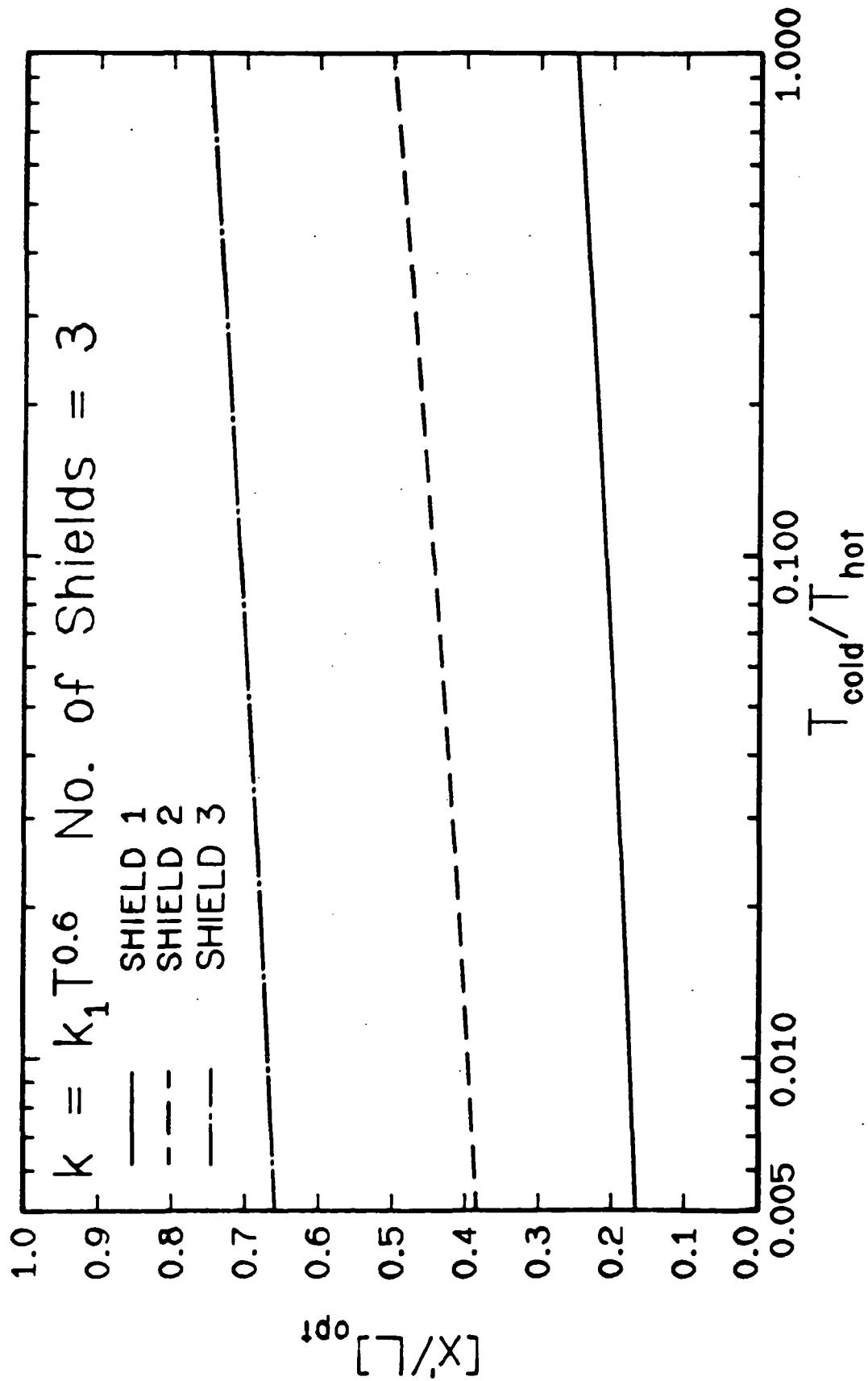


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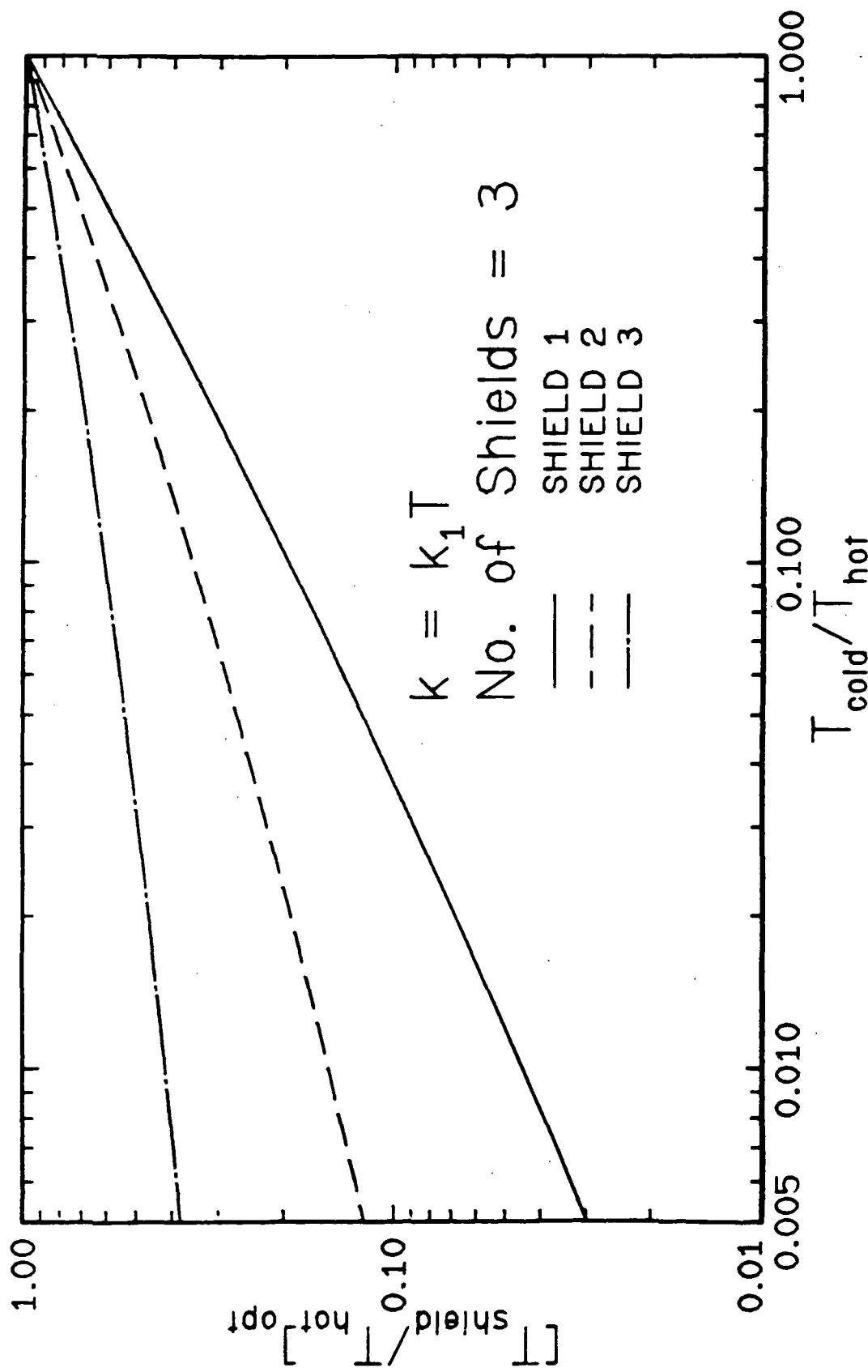


Figure 16

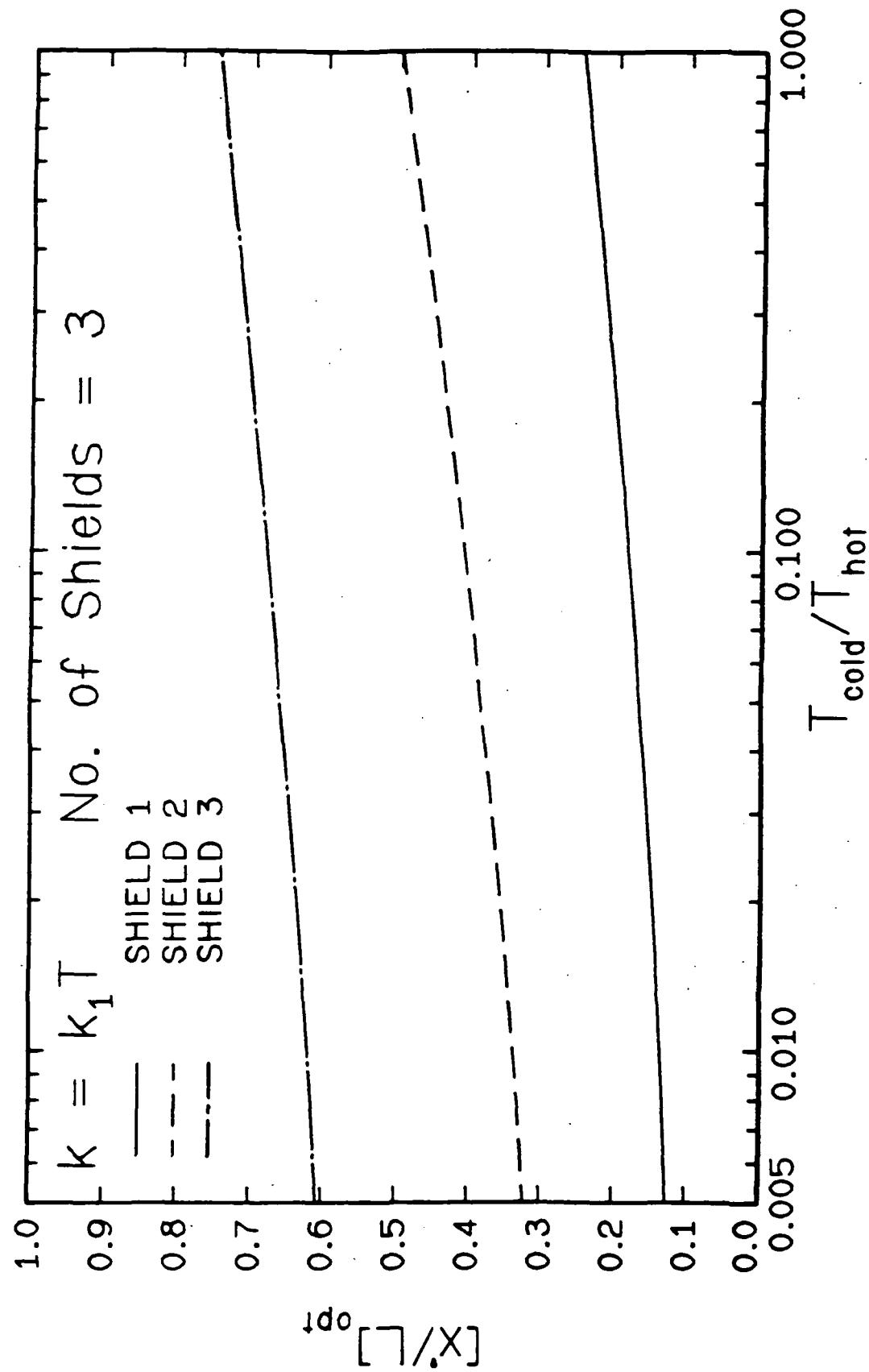


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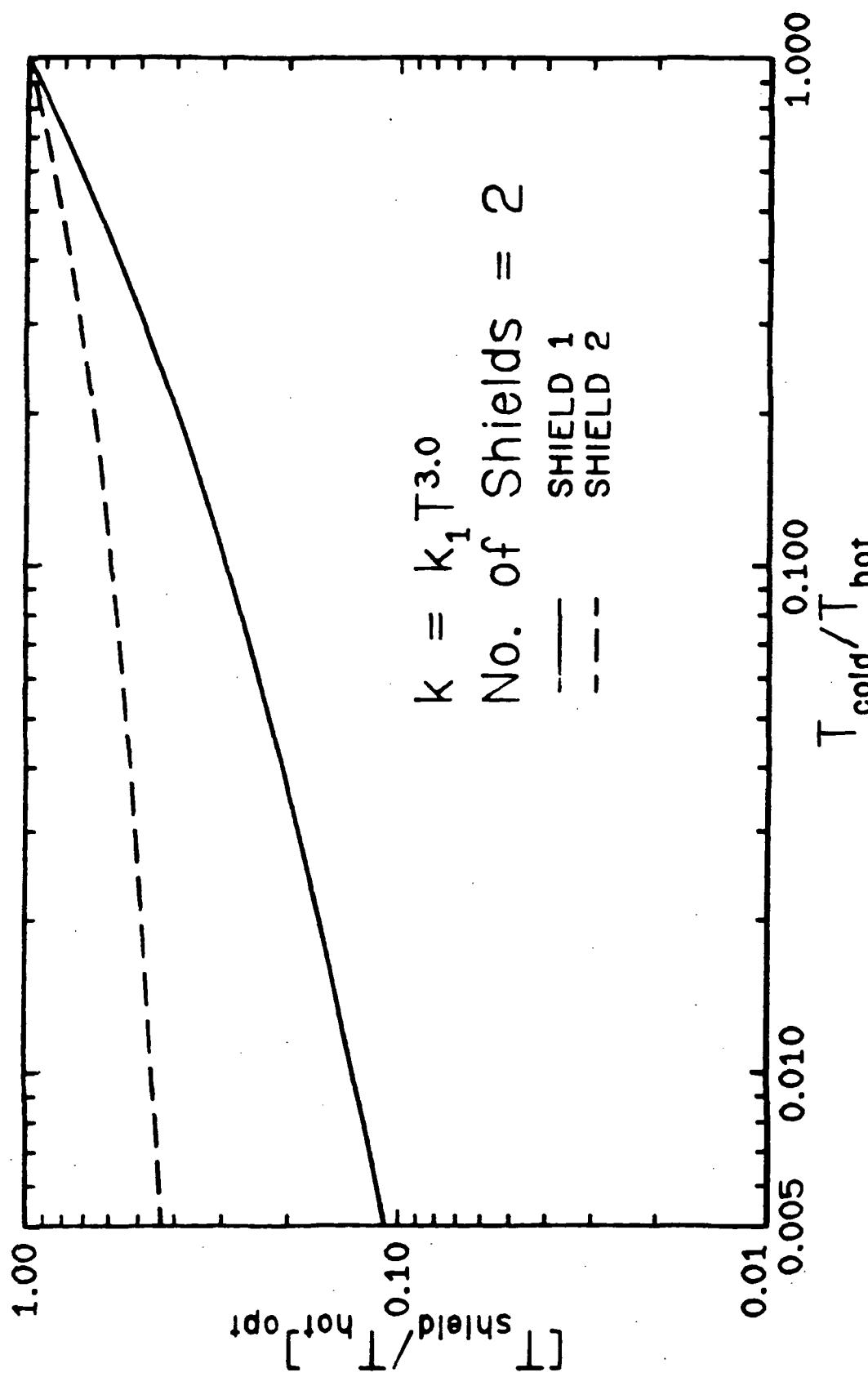


figure 18

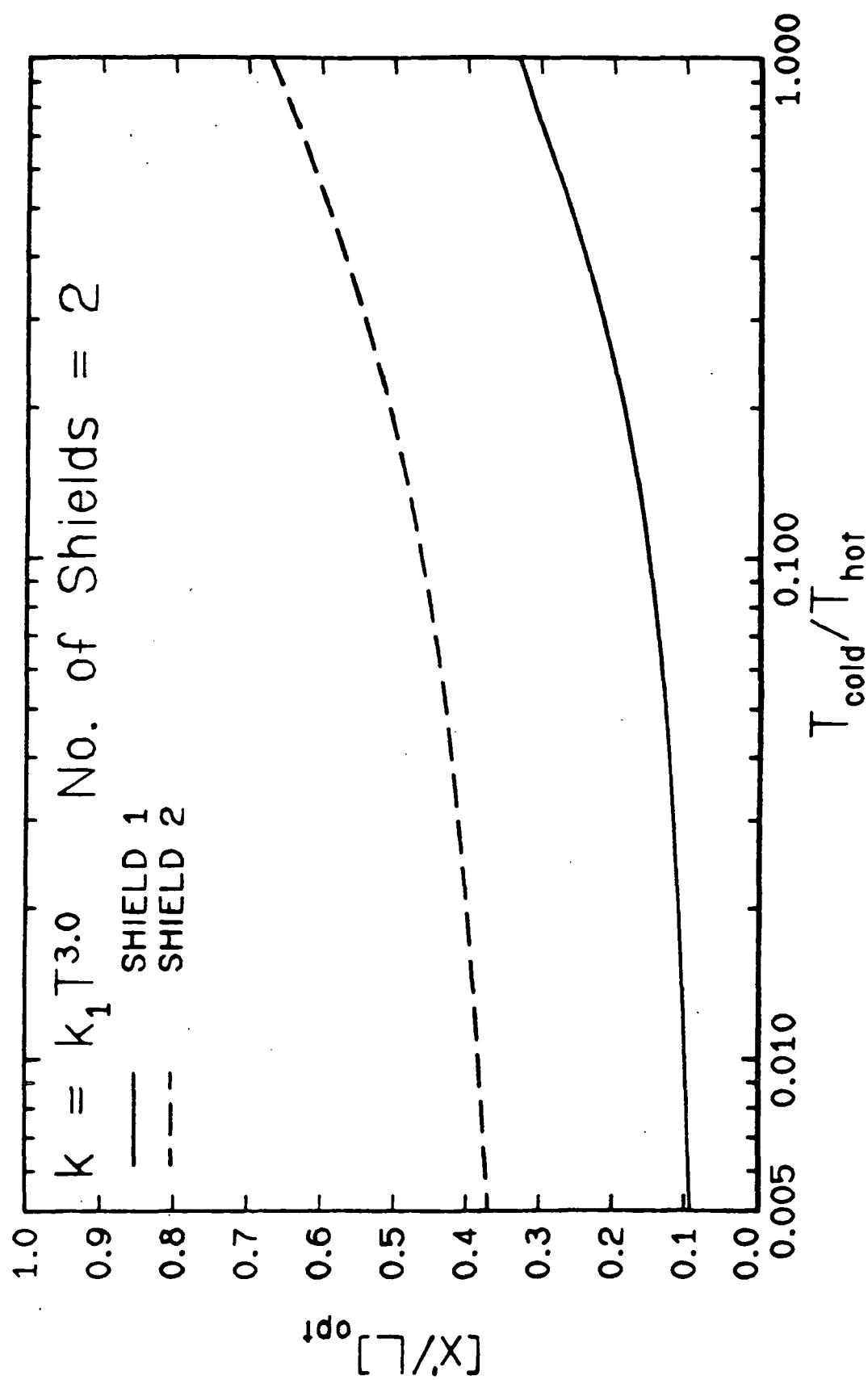


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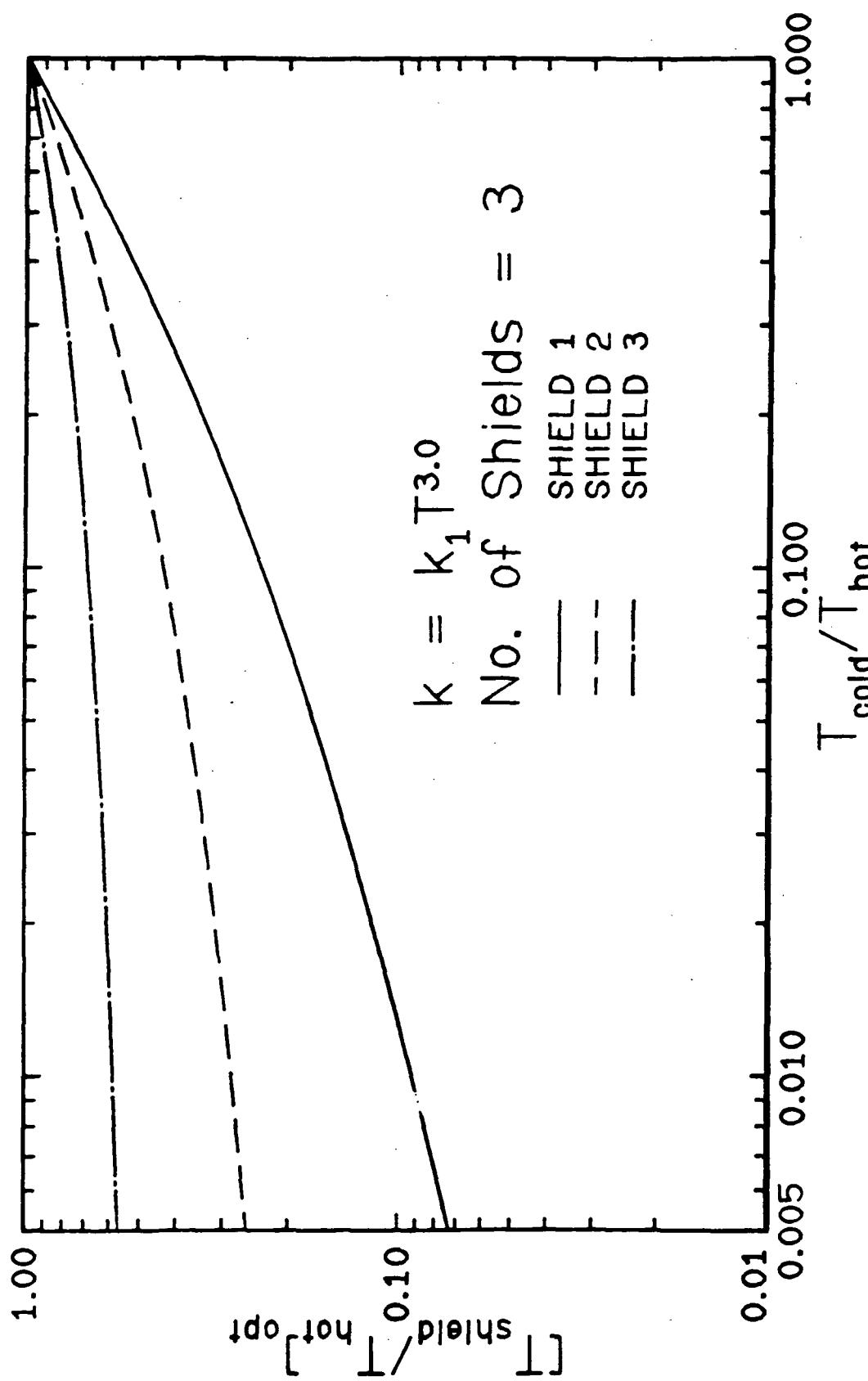


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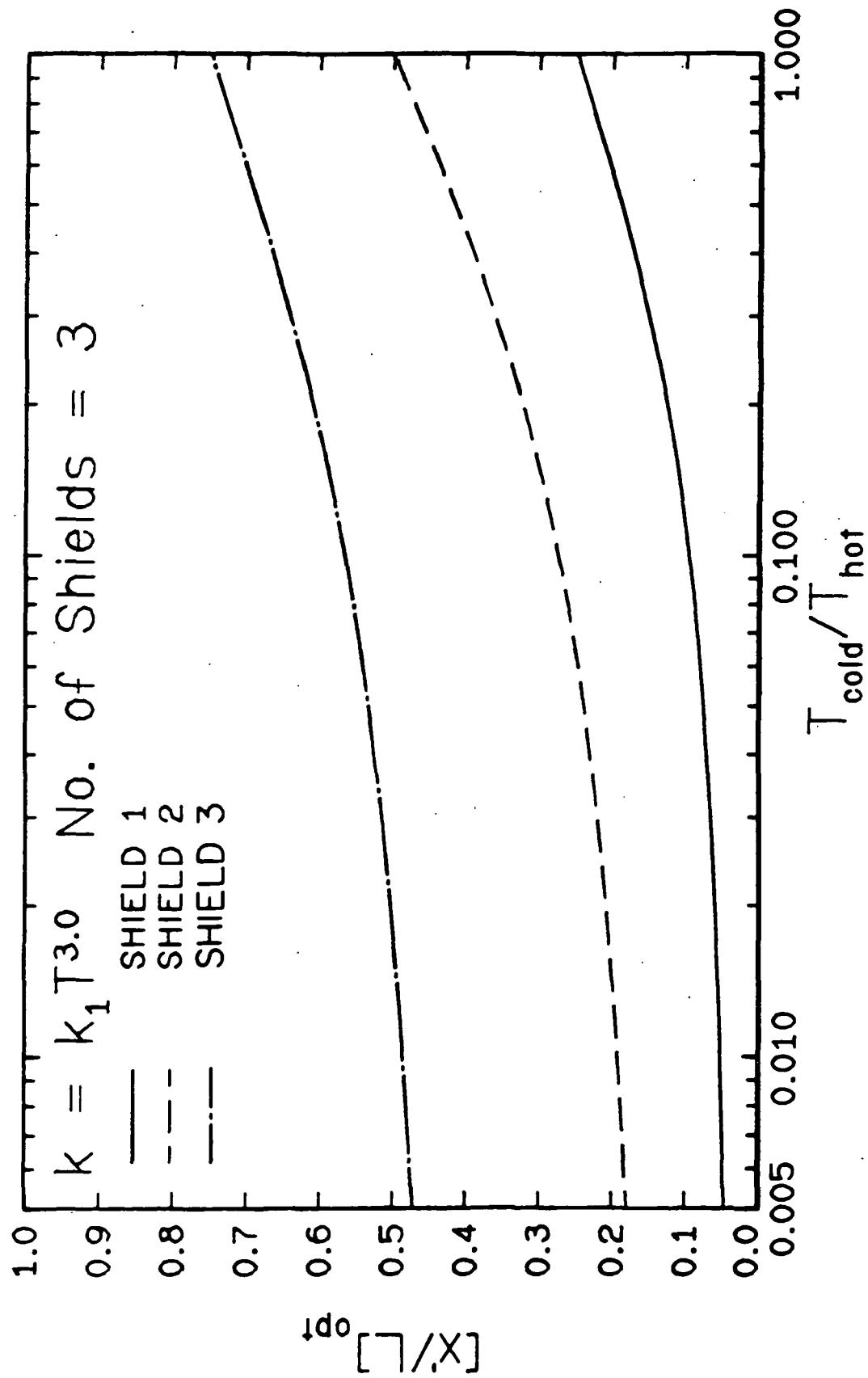


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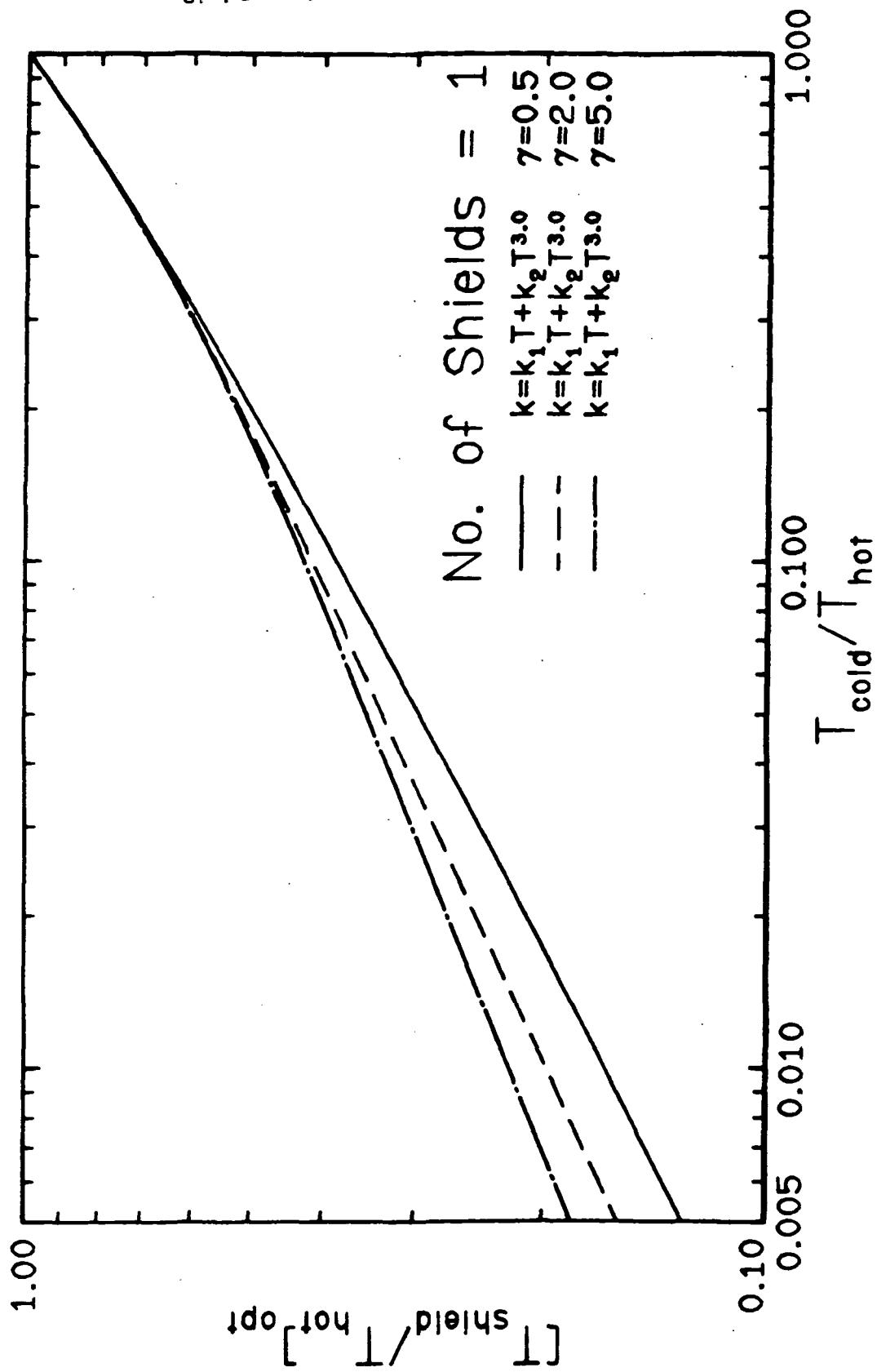


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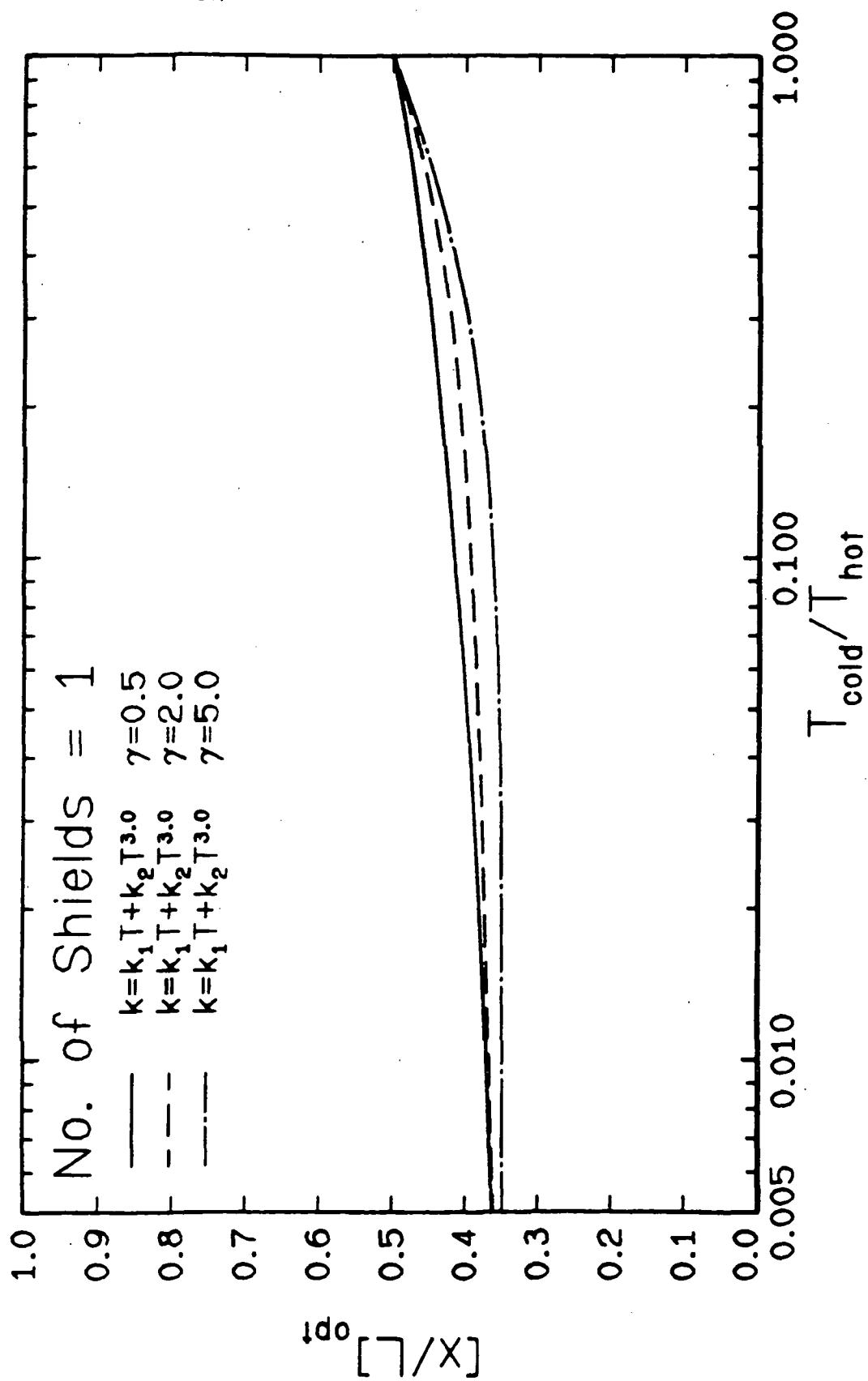


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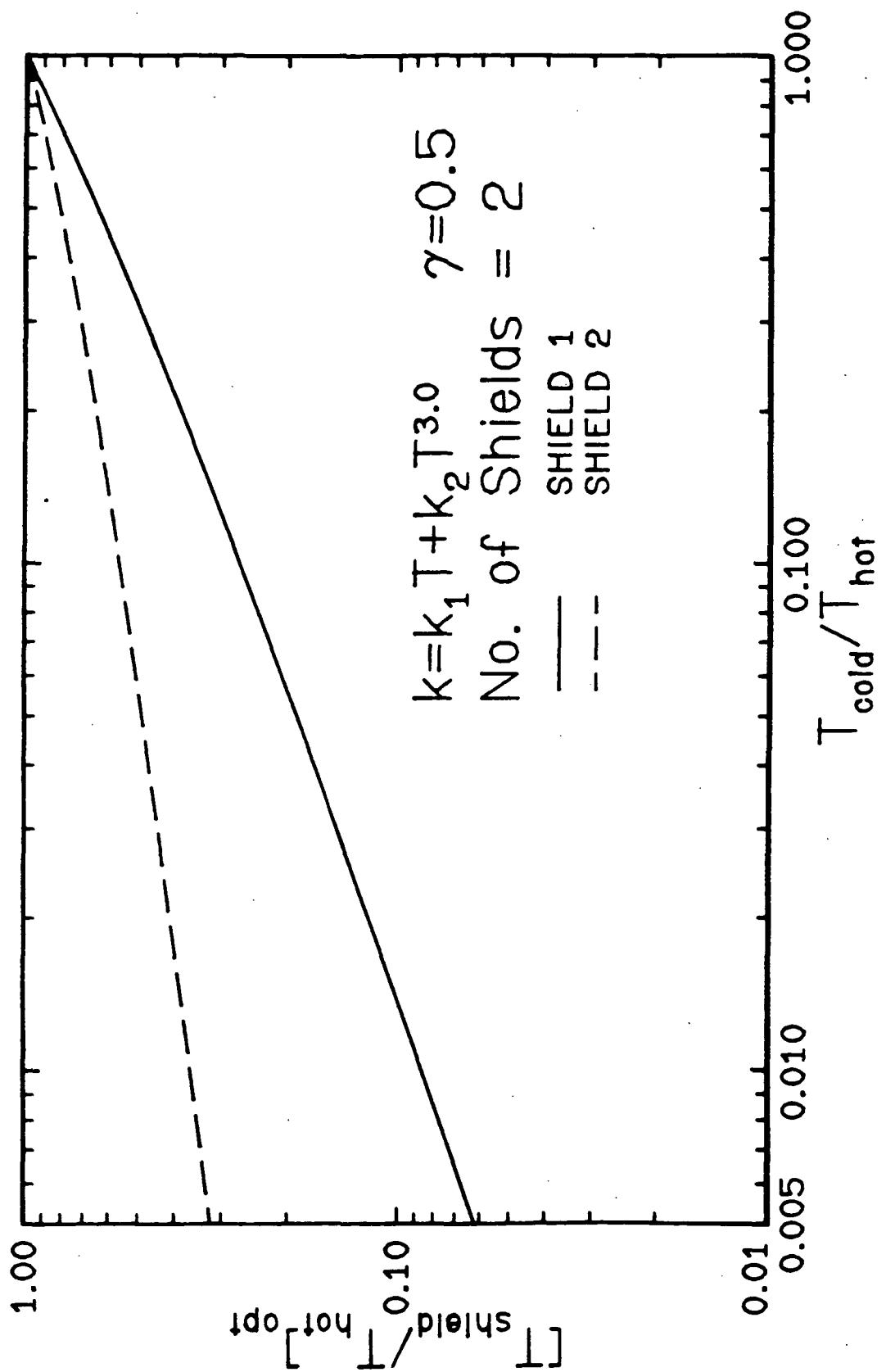


Figure 24

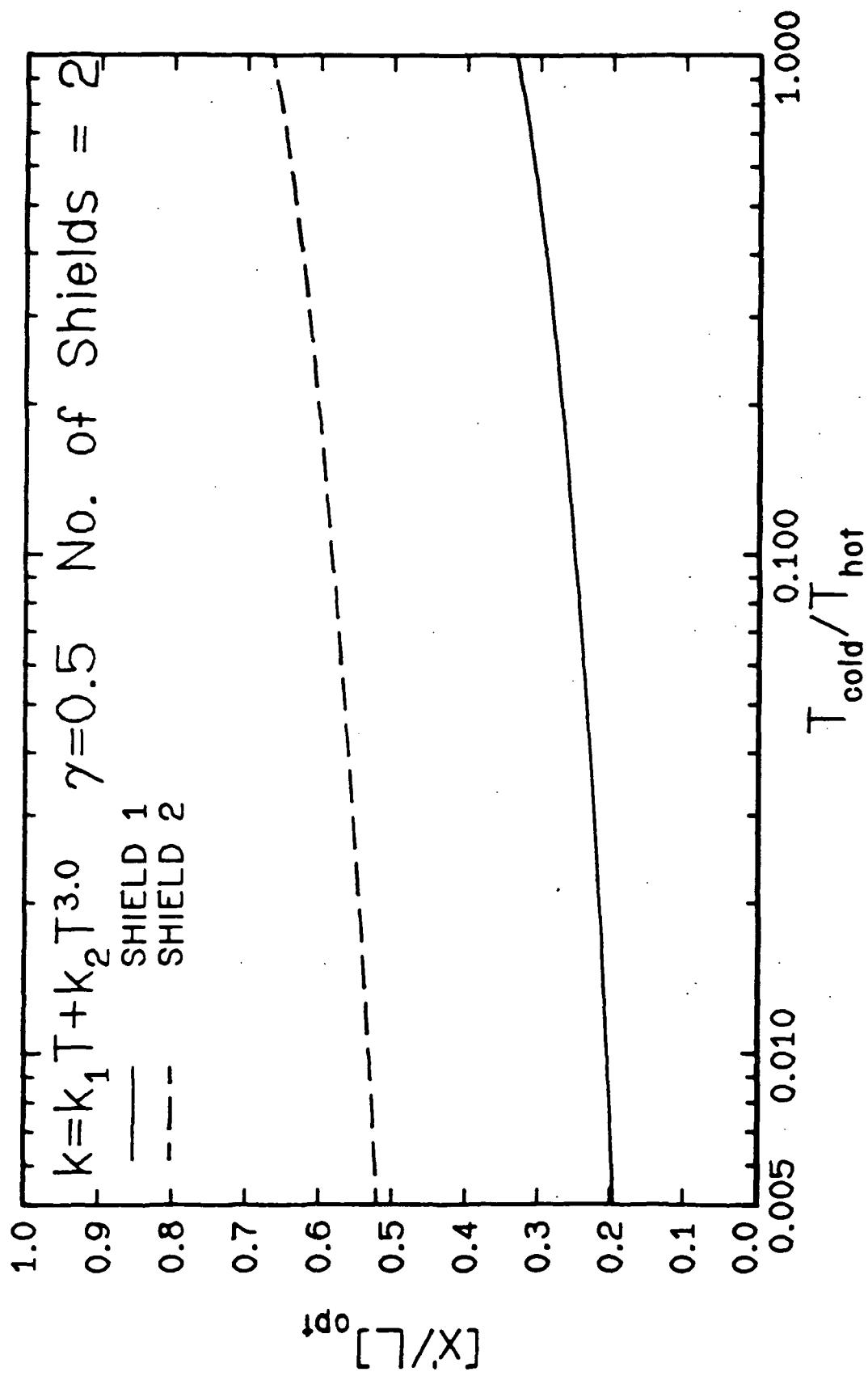


Figure 25

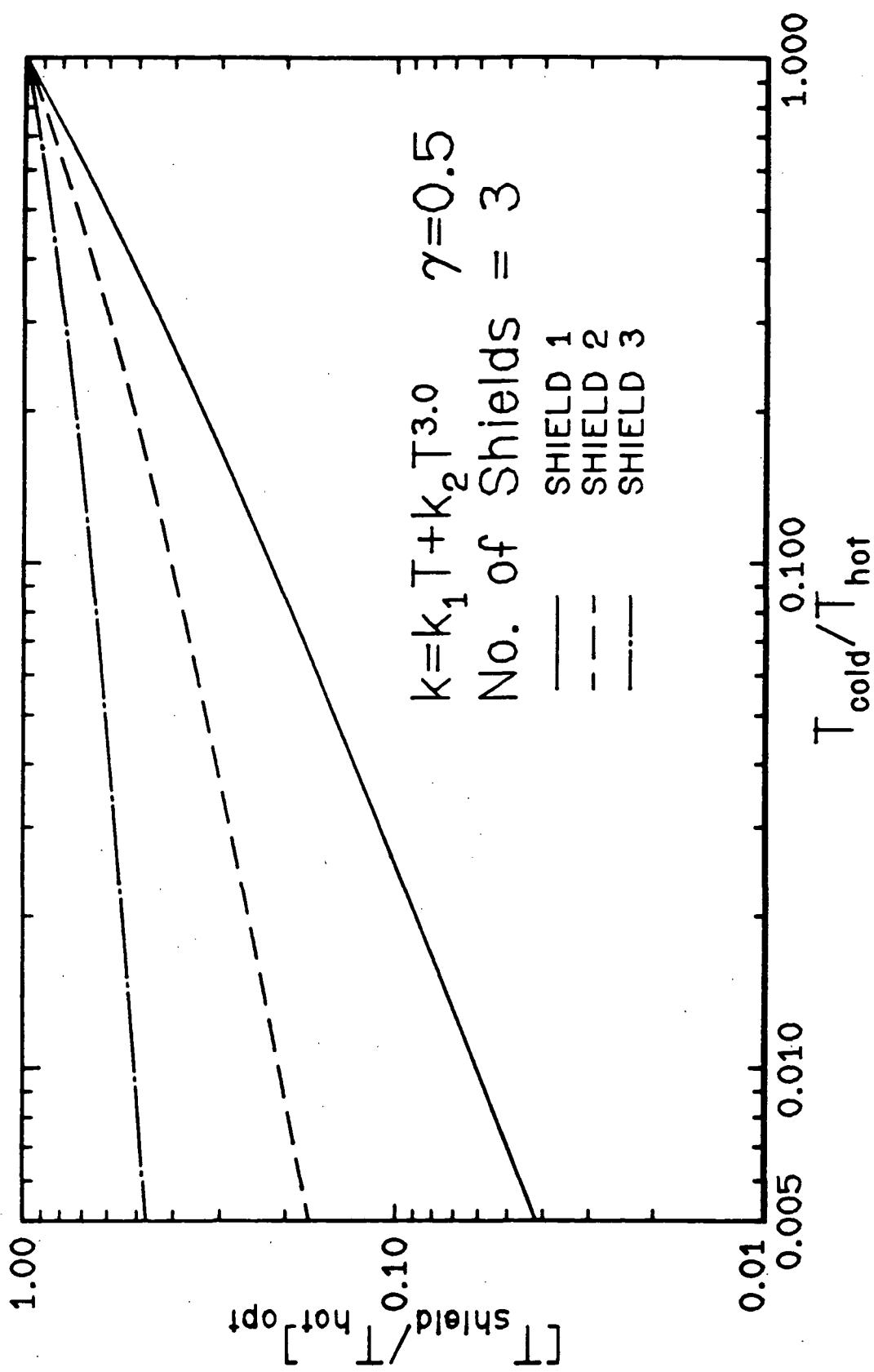


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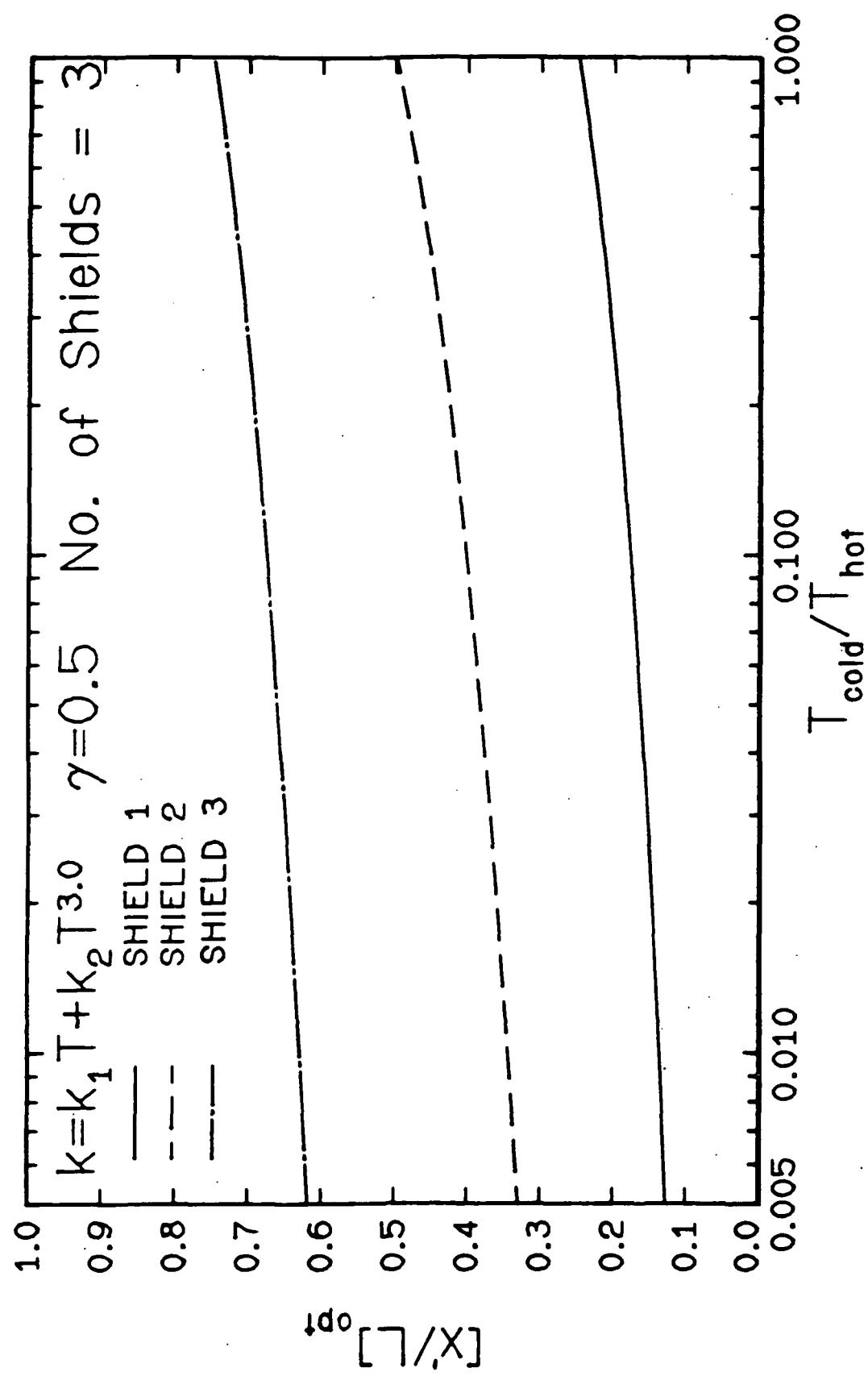


Figure 27

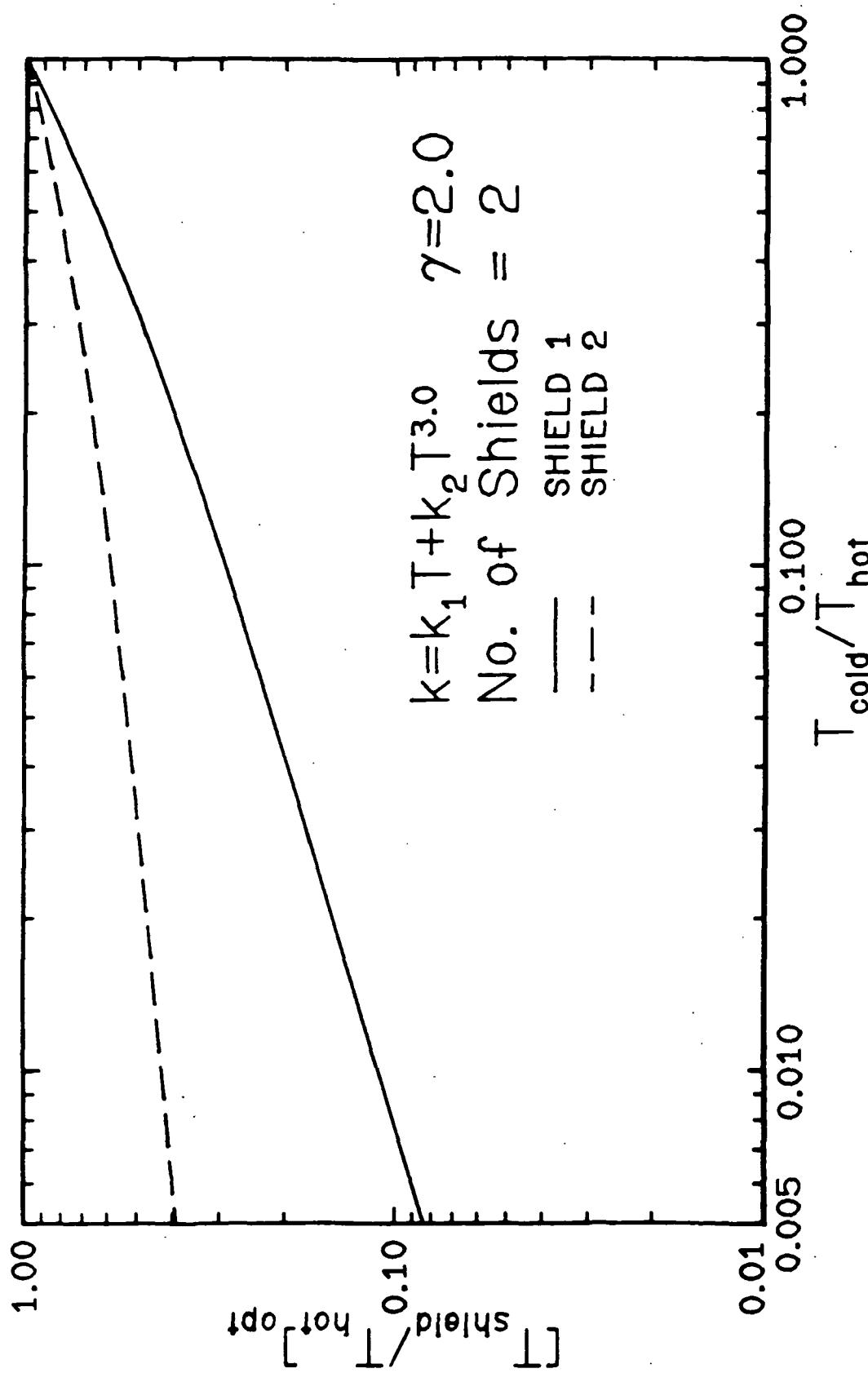


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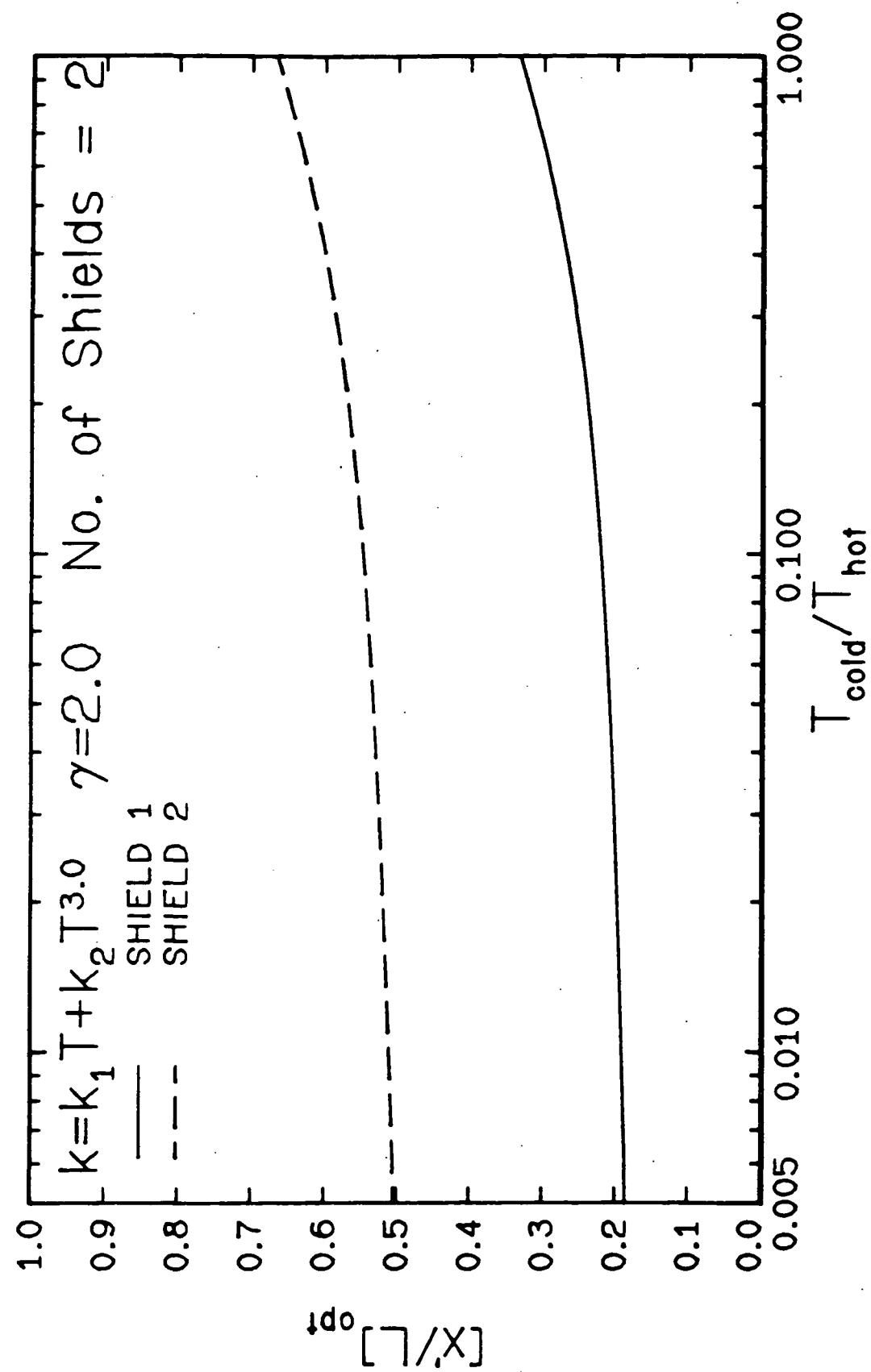


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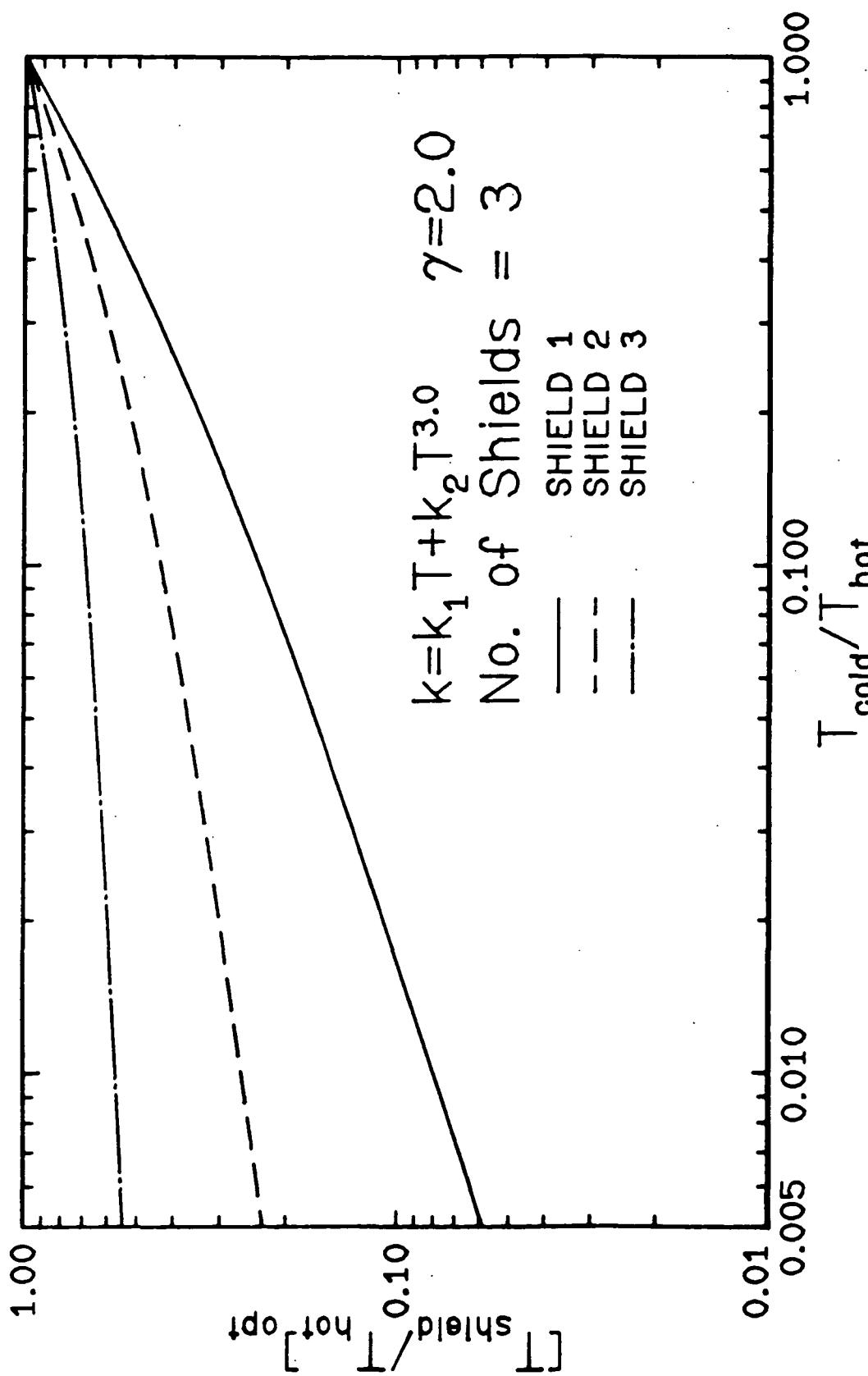


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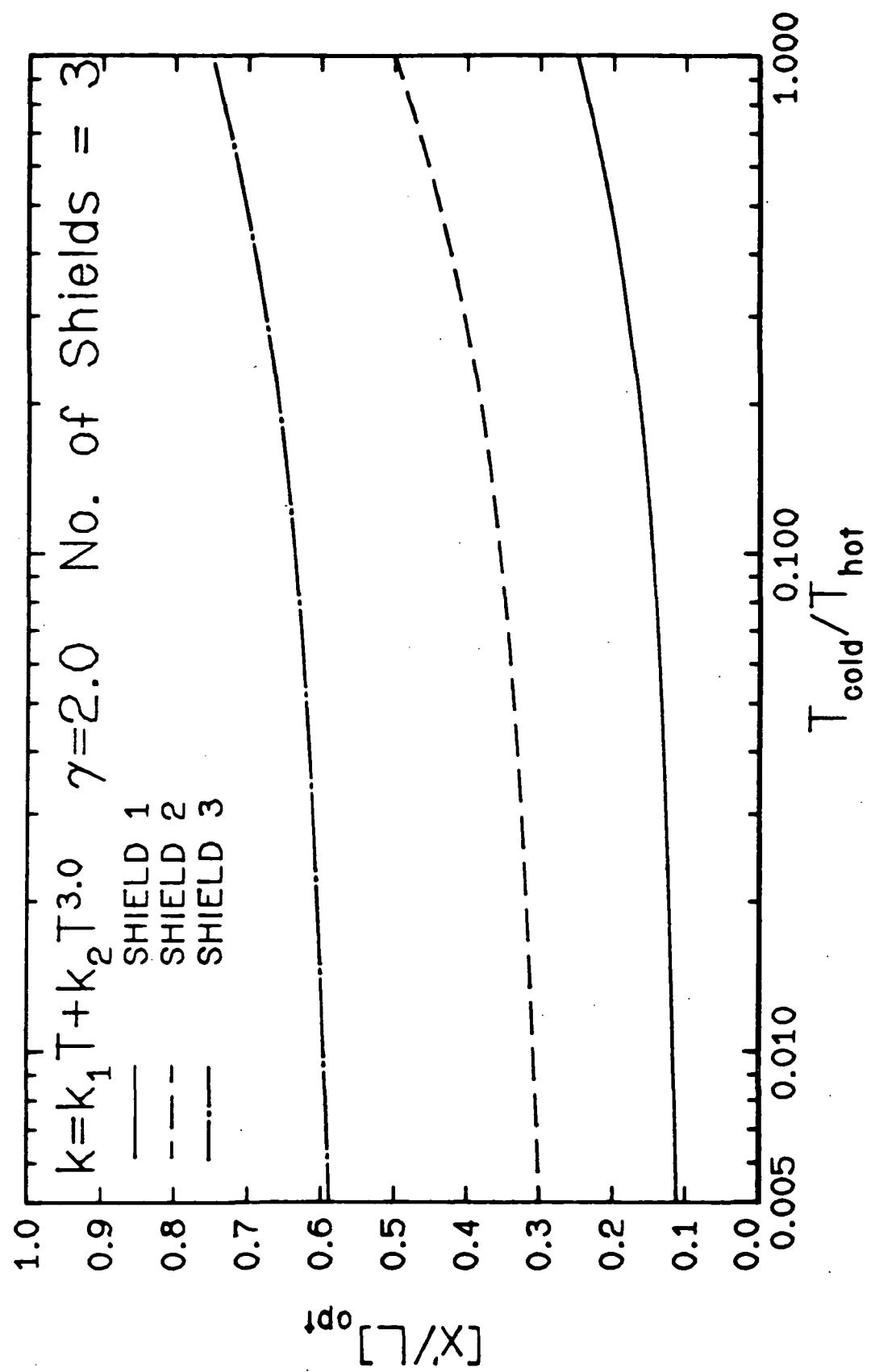


Figure 31

Curve Set 3: Figures 32 through 35

System sensitivity to deviations from the optimum shield  
temperatures and locations for two overall temperature ratios  
with one cooled shield

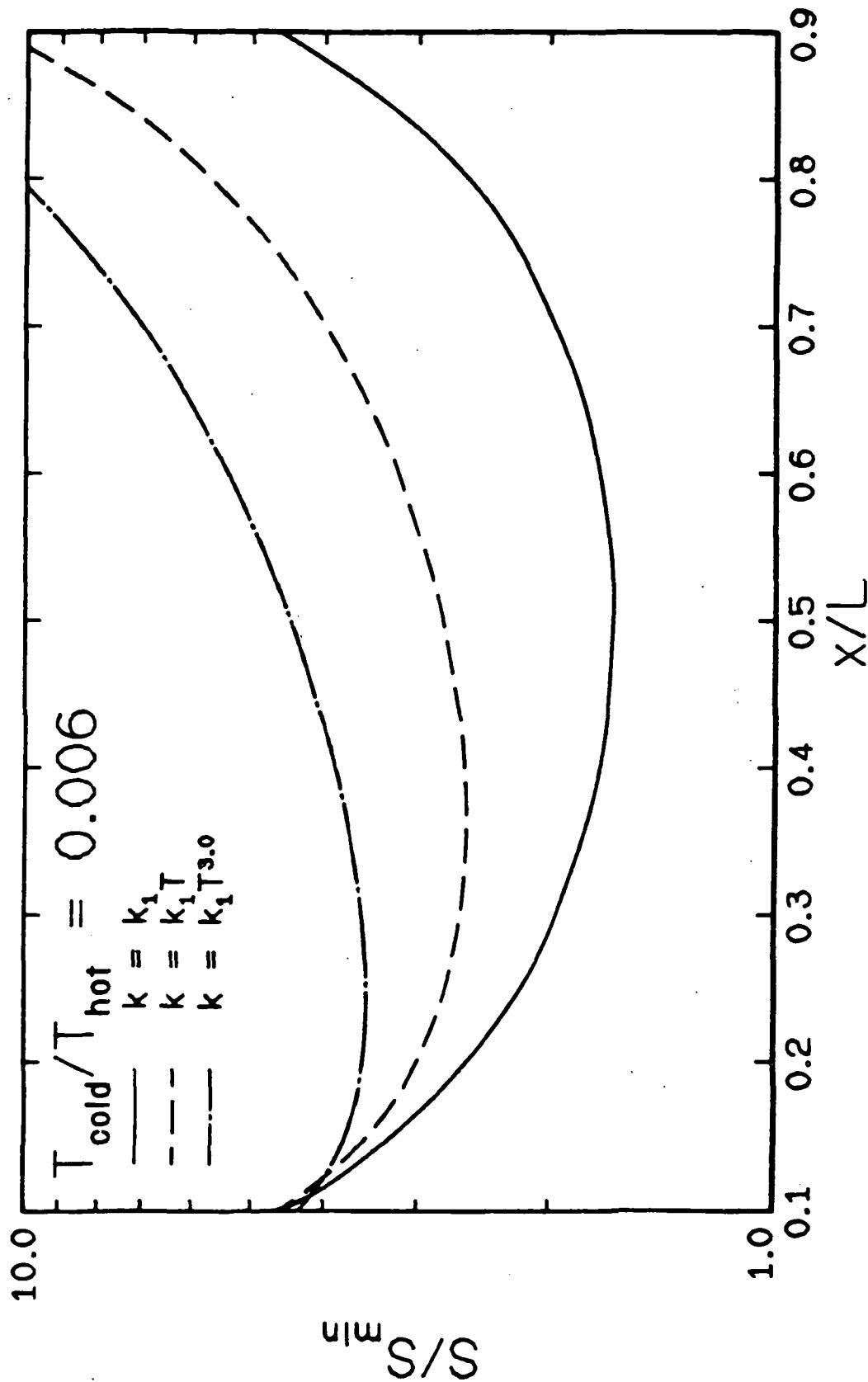


Figure 32

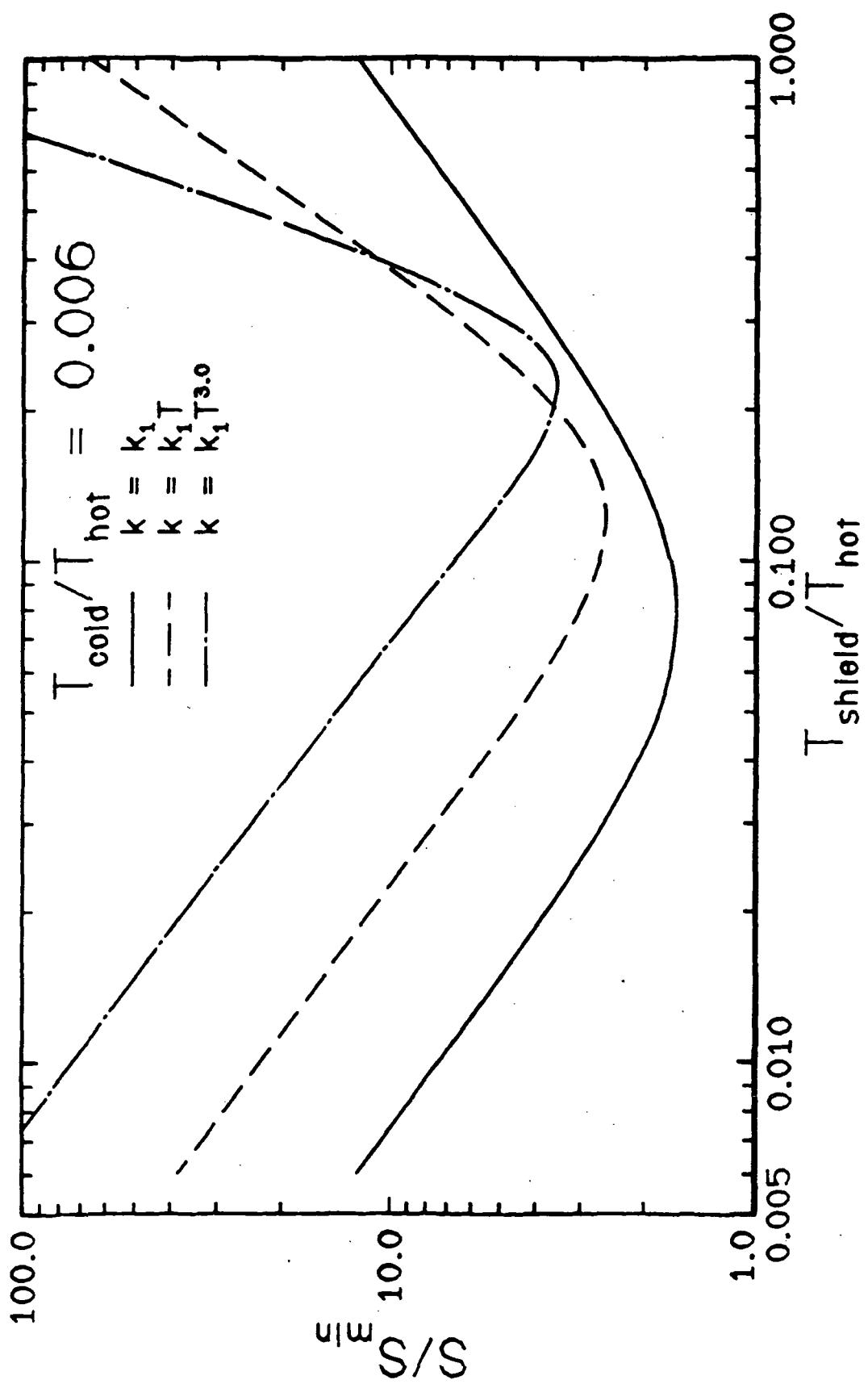


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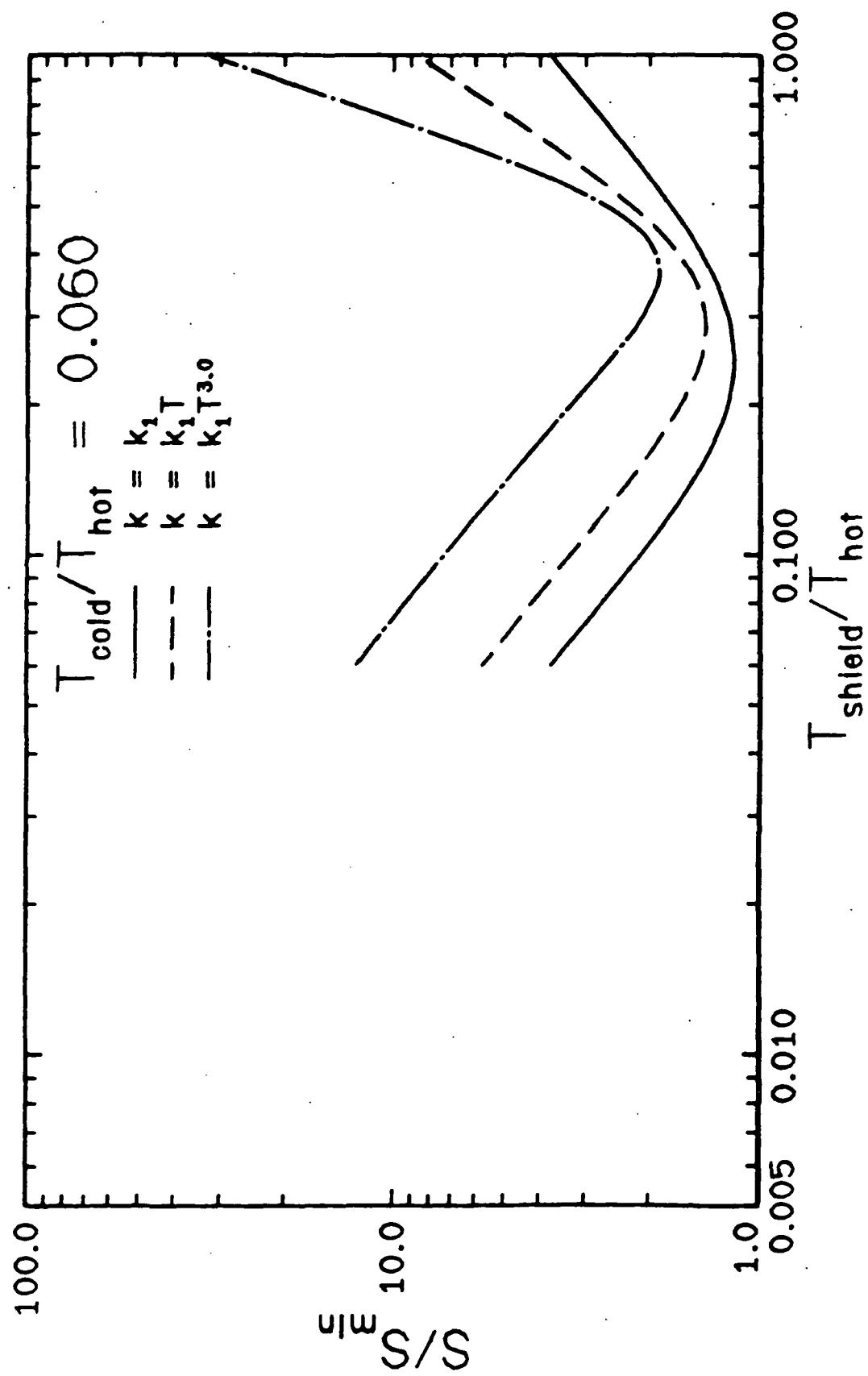


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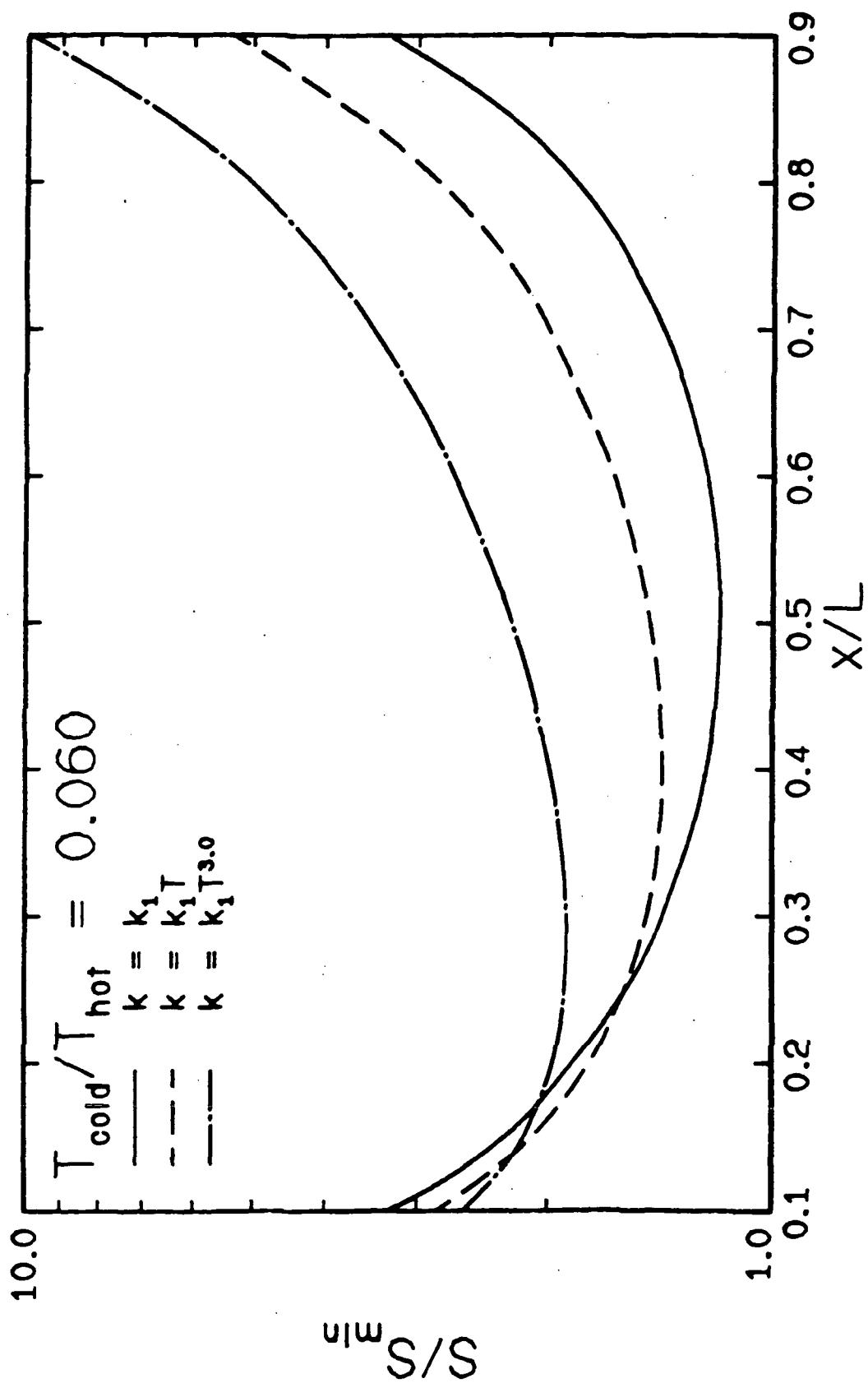


Figure 35

APPENDIX  
COMPUTER PROGRAMS

### SEPARS and SHIELD

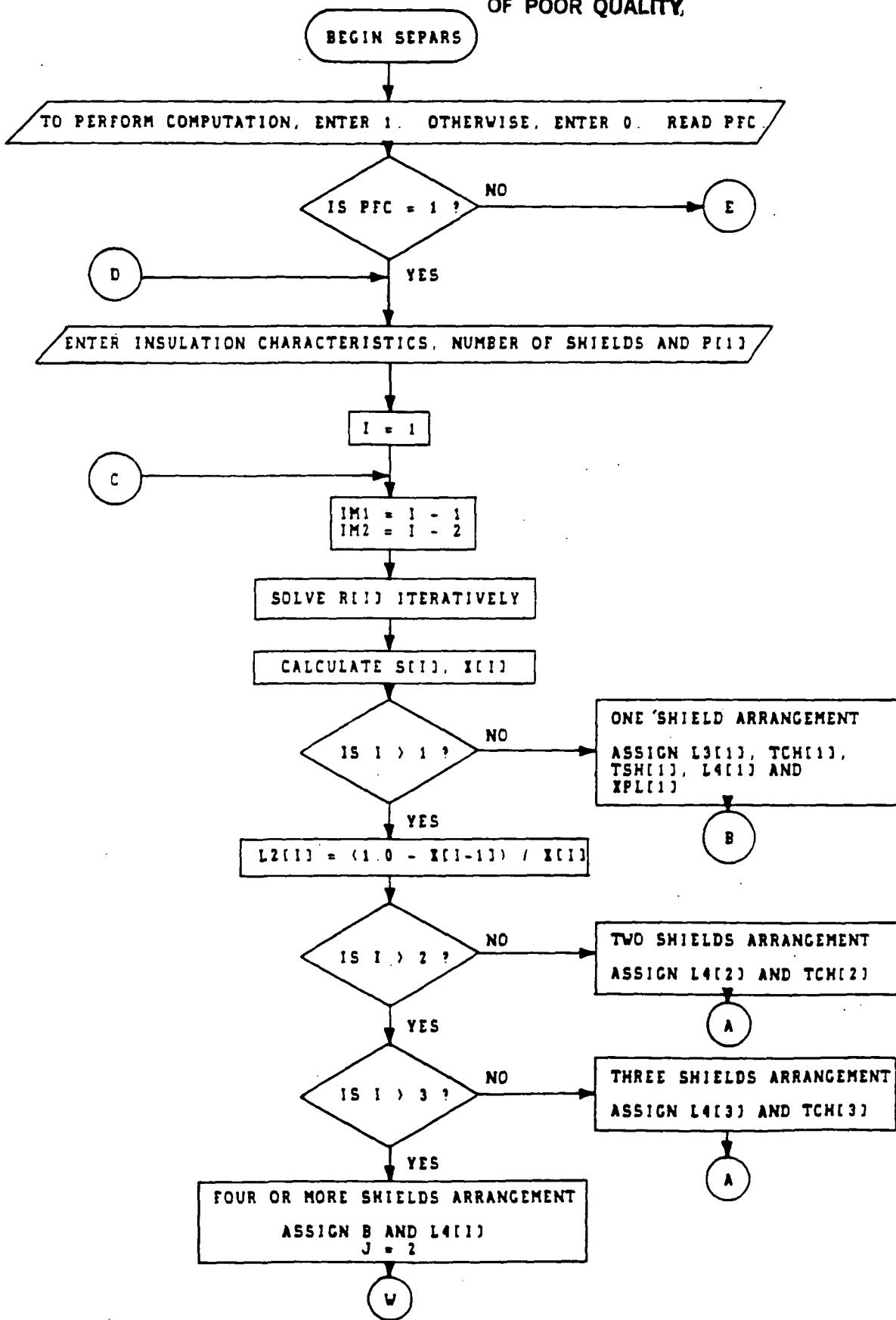
These two programs are essentially identical, but SEPARS is written in PASCAL whereas SHIELD is in BASIC.

To allow for consecutive calculations of different systems, the program always recycles to the starting point. Consequently, the first input requested is either a 1, if a calculation is to be performed, or a 0, if no more work is to be done.

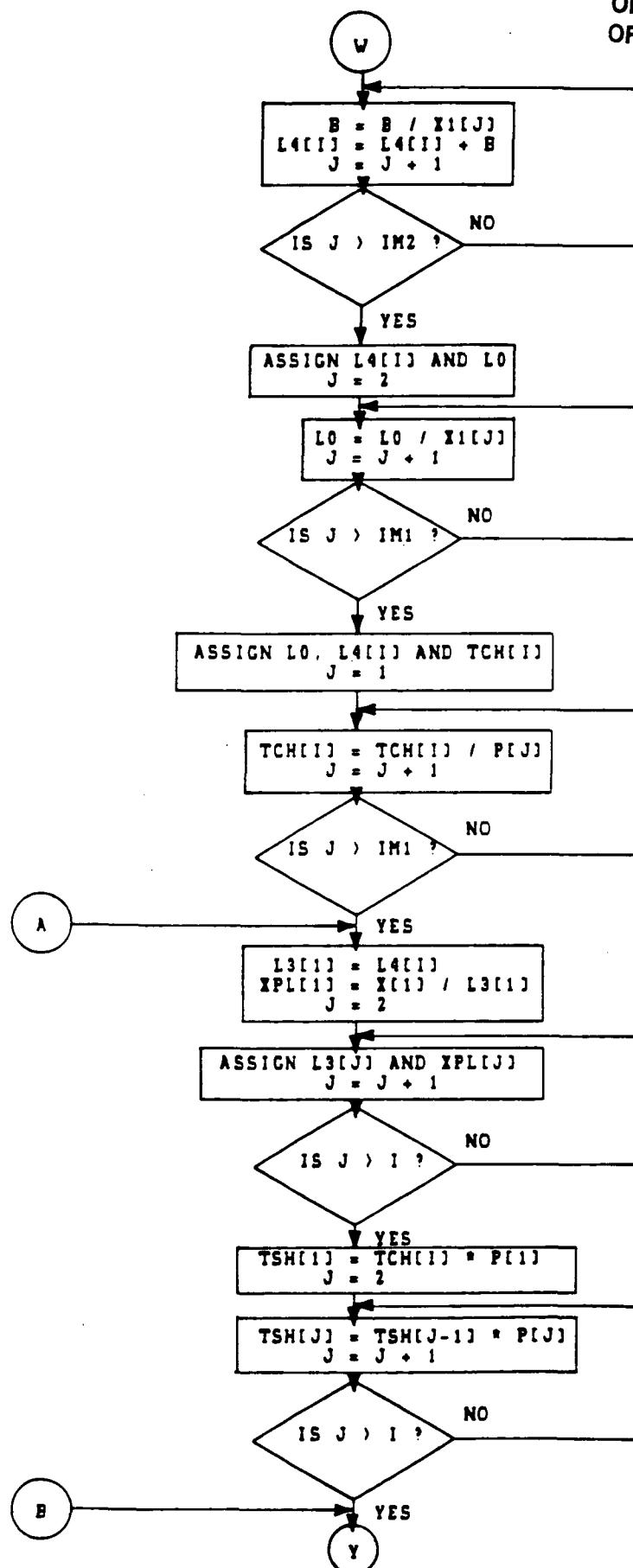
Next the program requests input of the insulation's characteristics, specifically, the two exponents of the temperatures in the two-term conductivity function, the maximum number of cooled shields (<10) to evaluate, the value of  $\gamma$ , and the temperature ratio of the first shield to the cold wall,  $P(1) = T_{S1}/T_C$ . The program calculates and presents the characteristics of all optimal systems of cooled shields from one shield to the maximum number specified in the input.

The flow chart and a program sample follows.

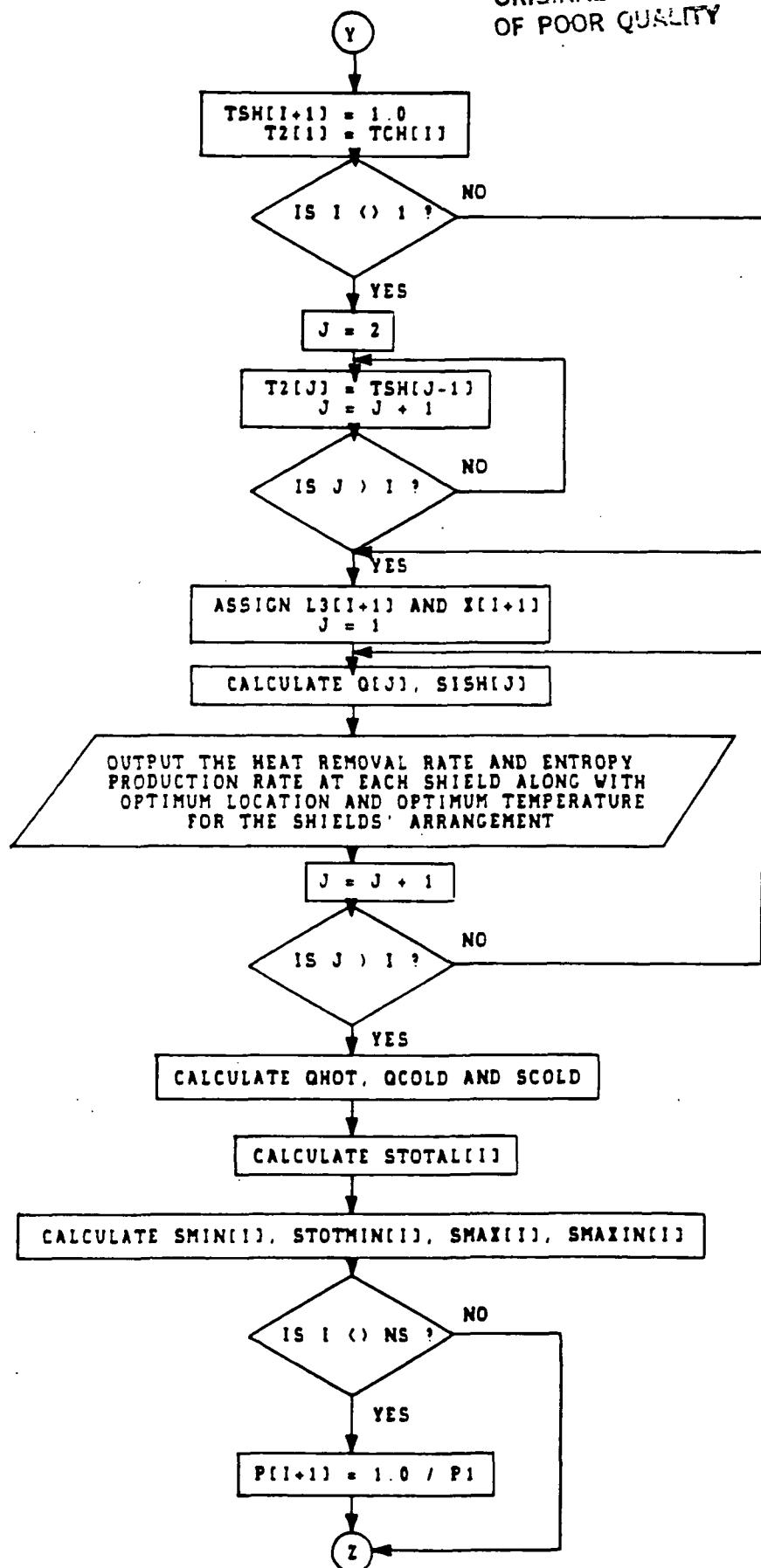
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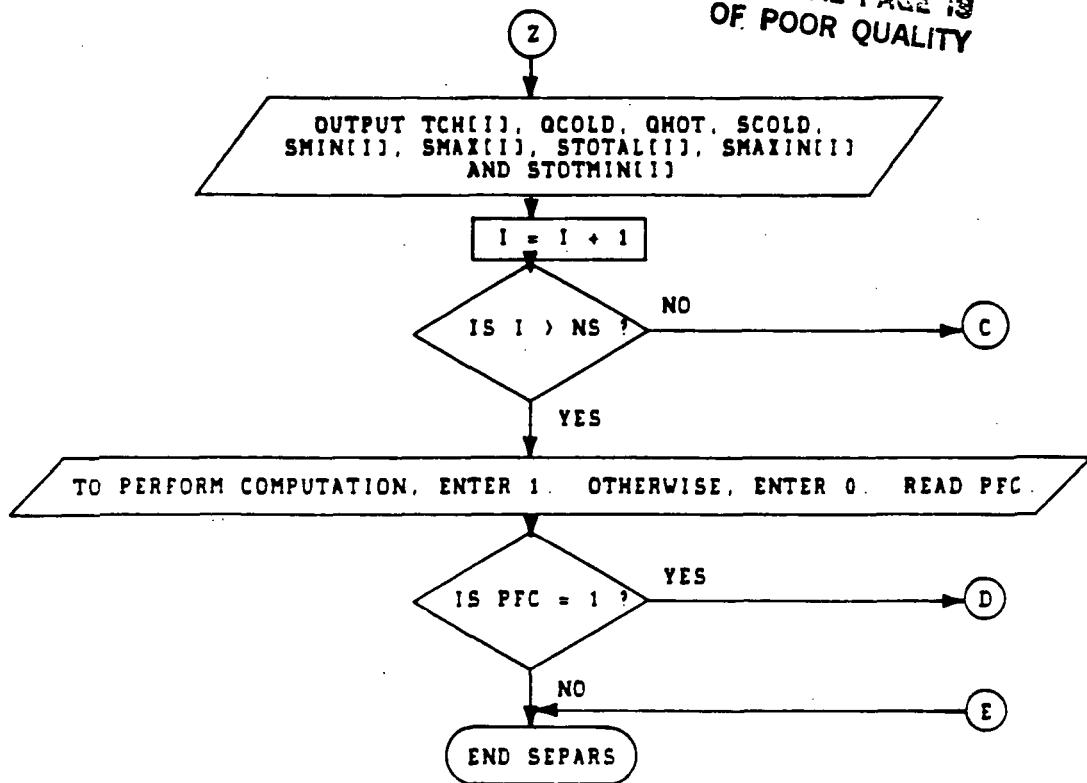
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PROGRAM SHIELDS (INPUT, OUTPUT, JMK).

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75      B      : REAL.          (* DUMMY VARIABLE *)
76      CC     : REAL.          (* DUMMY VARIABLE *)
77      COUNT  : INTEGER.      (* NUMBER OF ITERATIONS NEEDED TO DETERMINE R[1] *)
78      DD     : REAL.          (* DUMMY VARIABLE *)
79      E,G1   : REAL.          (* DUMMY VARIABLES *)
80      GAMA   : REAL.          (* (K1*(N-1))/(K1*(N+1)) * THOT**(N-N) , ALWAYS = 0 *)
81      (* WHERE THOT IS THE HOT WALL TEMPERATURE (K) *)
82      I,IM1,IM2,J : INTEGER. (* INDICES FOR LOOPS *)
83      JNK   : TEXT.          (* OUTPUT FILE TO BE USED IF DESIRED *)
84      L0    : REAL.          (* DUMMY VARIABLE *)
85      M     : REAL.          (* 1ST POWER IN THE THERMAL CONDUCTIVITY EQUATION *)
86      MP1   : REAL.          (* EQUALS N+1 *)
87      N     : REAL.          (* 2ND POWER IN THE THERMAL CONDUCTIVITY EQUATION *)
88      NP1   : REAL.          (* EQUALS N-1 *)
89      NS    : INTEGER.      (* NUMBER OF SHIELDS *)
90      PFC   : INTEGER.      (* PROGRAM FLOW CONTROLLER *)
91      PI    : REAL.          (* I-TH SHIELD / LOCAL HOT TEMPERATURE RATIO, ALWAYS < 1 *)
92      QCOLD : REAL.          (* HEAT OUT AT COLD WALL *)
93      QHOT  : REAL.          (* HEAT IN AT HOT WALL *)
94      SCOLD : REAL.          (* ENTROPY PRODUCTION RATE AT COLD WALL *)
95      U,V   : REAL.          (* DUMMY VARIABLES *)
96      W1,W2,W3 : REAL.      (* DUMMY VARIABLES *)
97      Z1,Z2 : REAL.          (* DUMMY VARIABLES *)
98
99
100
101
102 PROCEDURE INPUTH. (* INPUT OF DATA HEADING *)
103 BEGIN
104   WRITELN;
105   WRITELN(* ENTER ----) M N NS GAMA P[1] ----*),
106   WRITELN(*),
107   WRITELN(* WHERE M ----- 1ST POWER IN THE THERMAL CONDUCTIVITY EQUATION),
108   WRITELN(* N ----- 2ND POWER IN THE THERMAL CONDUCTIVITY EQUATION),
109   WRITELN(* NS ----- NUMBER OF SHIELDS),
110   WRITELN(* GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION),
111   WRITELN(* >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION),
112   WRITELN(* P[1] -- 1ST SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1),
113   WRITELN(*),
114 END. (* INPUT OF DATA HEADING *)
115
116
117
118 PROCEDURE PFCN. (* PFCN *)
119 BEGIN
120   WRITELN;
121   WRITELN(* TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.),
122   WRITELN(*),
123 END. (* PFCN *)
124
125
126
127 PROCEDURE SINGLESPACE.
128 BEGIN (* SINGLE SPACE IN OUTPUT *)
129   WRITELN(*),
130 END. (* SINGLE SPACE IN OUTPUT *)
131
132
133
134 FUNCTION PWR(X,E) REAL;
135 VAR
136   A      : REAL.          (* COMPUTE XX**E *)
137 BEGIN
138   A = E*LN(X),
139   PWR = EXP(A)
140 END. (* COMPUTE XX**E *)
141
142
143
144 FUNCTION D(E,XX) REAL;
145 BEGIN (* FUNCTIONAL D *)
146   D = (E+1.0)*PWR(XX,E) - E/(PWR(XX,(1.0-E)) - (1.0/SQR(XX)))
147 END. (* FUNCTIONAL D *)
148
149
150

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151  FUNCTION F(E,XX:REAL):REAL;
152  BEGIN          (* FUNCTIONAL F *)
153  F:=(PWR(XX,(E+1.0))-PWR(XX,E)-1.0)*(1.0/XX)
154  END.          (* FUNCTIONAL F *)
155
156
157  FUNCTION SIMPSON(TCHB:REAL):REAL;
158  TYPE
159  ARR:ARRAY[1..101] OF REAL;
160
161  VAR
162  C,Y          ARR;
163  DELTAT        REAL;
164  H             REAL;
165  K,L           INTEGER;
166
167  BEGIN          (* COMPUTE MINIMUM ENTROPY PRODUCTION RATE USING SIMPSON'S NUMERICAL INTEGRATION SCHEME *)
168  DELTAT:=(1.0-TCHB)/100.0;
169  FOR L:=1 TO 101 DO
170  BEGIN
171  C[L]:=TCHB+DELTAT*(L-1);
172  Y[L]:=PWR((PWR(C[L],H)+GAMA*NPI/MPI)*PWR(C[L],H)),0.5)/C[L];
173  END;
174  H:=Y[1]+Y[101];
175  FOR K:=2 TO 100 DO
176  BEGIN
177  IF K=(K DIV 2)*2 THEN
178  H:=H+4.0*Y[K];
179  ELSE
180  H:=H+2.0*Y[K];
181  END;
182  SIMPSON:=(5.0*(H/DELTAT)/3.0)*H;
183  END.          (* COMPUTE MINIMUM ENTROPY PRODUCTION RATE USING SIMPSON'S NUMERICAL INTEGRATION SCHEME *)
184
185
186
187
188
189
190
191
192  (* MAIN PROGRAM BODY *)
193
194  BEGIN
195  PECH;
196  READLN;
197  READ(PFC);
198  WHILE PFC=1 DO
199  BEGIN
200
201  (* THIS BLOCK IS USED TO INPUT THE INSULATION THERMAL CONDUCTIVITY, NUMBER *)
202  (* OF SHIELDS AND 1ST. SHIELD / COLD WALL TEMPERATURE RATIO *)
203
204  INPUTH;
205  READLN;
206  READ(M,N,NS,GAMA,P1);
207  SINGLESPACE;
208  IF GAMA=0.0 THEN
209  WRITELN(' THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**0.5*(H-1.0)');
210  ELSE
211  BEGIN
212  WRITELN(' THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**0.5*(H-1.0) + K2*T**0.5*(H-1.0)');
213  WRITELN(' [K1*(N+1)]/[K1*(N+1)]*THOT**0.5*(H-M) = 1.0, GAMA = 0.0');
214  END;
215  SINGLESPACE;
216  SINGLESPACE;
217
218
219  MPI:=M+1.0;
220  NPI:=N+1.0;
221  FOR I:=1 TO NS DO
222  BEGIN
223  IM1:=I-1;
224  IM2:=I-2;
225  B113:=0.000001;
226  CC:=0.1;
227  DD:=1.0;
228  COUNT:=0;
229

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230      (* THIS BLOCK CALCULATES R[] ITERATIVELY *)
231
232      REPEAT
233          P1 = P[1]*R[1];
234          W1 = PWR(R[1],M)*F(M,P[1]) + GAMA*PWR(R[1],N)*F(N,P[1]);
235          W2 = SQR(PWR(R[1],(M-1,0))*D(M,P[1]) + GAMA*PWR(R[1],(N-1,0))*D(N,P[1]));
236          W3 = SQR(D(M,P1)*GAMA*D(N,P1))/(F(M,P1)*GAMA*F(N,P1));
237          C = (W2/W1)*W3;
238          G1 = C*DD;
239          IF G1<0.0 THEN GOTO 100;
240          IF G1>0 THEN GOTO 200;
241          CC = (-0.1)*CC;
242          IF ABS(CC)<0.000001 THEN GOTO 300;
243          DD = -DD;
244          100 R[1] = R[1]+CC;
245          IF (R[1]>0.999999) OR (R[1]<0.000001) THEN
246              BEGIN
247                  R[1] = R[1]-0.9*CC;
248                  CC = 0.1*CC;
249              END;
250          200 COUNT = COUNT+1;
251      UNTIL (G1>0.0) OR (ABS(CC)<0.000001);
252
253
254      U = (PWR(R[1],(M-1,0))*D(M,P[1]) + GAMA*PWR(R[1],(N-1,0))*D(N,P[1]));
255      I[1] = U/(D(M,P1)*GAMA*D(N,P1));
256      X[1] = I[1]/(1.0-I[1]);
257      V = (F(M,P1)*GAMA*F(N,P1))/(1.0-X[1]);
258      S[1] = V*(PWR(R[1],M)*F(M,P[1]) + GAMA*PWR(R[1],N)*F(N,P[1]))/X[1];
259      S[1] = S[1]/(1.0+GAMA*MP1/MP1);
260
261      (* IN THIS BLOCK VARIABLES ARE ASSIGNED FOR DIFFERENT SHIELD CONFIGURATIONS *)
262
263      IF I[1] THEN
264          BEGIN
265              L2[1] = (1.0-I[1-1])/X[1];
266              IF I[1/2] THEN
267                  IF I[1/3] THEN
268                      BEGIN
269                          B = 1.0;
270                          L4[1] = 0.0;
271                          FOR J = 2 TO IM2 DO
272                              BEGIN
273                                  B = B/X[1];
274                                  L4[1] = L4[1]+B;
275                              END;
276                          L4[1] = L4[1]*(1.0-X[1])+1.0;
277                          L0 = 1.0-X[1];
278                          FOR J = 2 TO IM1 DO L0 = L0/X[1];
279                          L0 = L0/X[1];
280                          L4[1] = L4[1]+L0;
281                          TCH[1] = R[1];
282                          FOR J = 1 TO IM1 DO TCH[1] = TCH[1]/P[J];
283                      END;
284                  ELSE
285                      BEGIN
286                          L4[3] = 1.0*(1.0-I[1])*(1.0-X[2])/(X[2]*X[3]);
287                          TCH[3] = R[3]/(P[1]*P[2]);
288                      END;
289                  ELSE
290                      BEGIN
291                          L4[2] = X[1]+(1.0-I[1])/X[2];
292                          TCH[2] = R[2]/P[1];
293                      END;
294                  L3[1] = L4[1];
295                  XPL[1] = X[1]/L3[1];
296                  FOR J = 2 TO 1 DO
297                      BEGIN
298                          L3[2] = L3[2-1]/L2[2];
299                          XPL[2] = XPL[2-1]*X[2]/L3[2];
300                      END;
301                  TSH[1] = TCH[1]*P[1];
302                  FOR J = 2 TO 1 DO TSH[1] = TSH[1]*P[J];
303              END;
304          ELSE

```

```

305      BEGIN
306          L3[1] = 1.0.
307          TCH[1] = R[1];
308          TSH[1] = TCH[1]*P[1];
309          L4[1] = 1.0;
310          XPL[1] = X[1]
311      END.
312      TSH[1+1] = 1.0;
313      T2[1] = TCH[1];
314
315
316      SINGLESPACE.
317      WRITELN('      NUMBER OF SHIELDS      = ',I,2);
318      WRITELN('      NUMBER OF ITERATIONS = ',COUNT);
319      SINGLESPACE.
320      SINGLESPACE.
321      WRITELN('      HEAT REMOVAL      ENTROPY PRODUCTION      OPTIMUM      OPTIMUM');
322      WRITELN('      RATE          RATE          LOCATION      TEMPERATURE');
323      WRITELN('      -----      -----      -----      -----');
324      SINGLESPACE.
325      IF (<)0 THEN
326          FOR J = 2 TO I DO T2[J] = TSH[J-1];
327          L3[1+1] = L3[1];
328          X[1+1] = 1.0-X[1];
329
330          (* IN THIS BLOCK DIMENSIONLESS HEAT REMOVAL AND ENTROPY PRODUCTION RATES *)
331          (* ARE CALCULATED FOR EACH SHIELD *)
332
333      FOR J = 1 TO I DO
334          BEGIN
335              Z1 = ((PWR(TSH[J-1],NP1)-PWR(TSH[J],NP1))*L3[J+1]/X[J+1]-(PWR(TSH[J],NP1)-PWR(T2[J],NP1))*L3[J]/X[J])/NP1;
336              Z2 = ((PWR(TSH[J+1],NP1)-PWR(TSH[J],NP1))*L3[J+1]/X[J+1]-(PWR(TSH[J],NP1)-PWR(T2[J],NP1))*L3[J]/X[J])/NP1;
337              Q[J] = (Z1+GAMA*Z2)/(1.0+GAMA*NP1/NP1);
338              SISH[J] = Q[J]/TSH[J];
339              WRITELN('      SHIELD ',J,2,'  ',5,0,Q[J],9,5,'  ',11,SISH[J],9,5,'  ',9,XPL[J],9,5,'  ',5,TSH[J],9,5);
340          END.
341
342          (* FINALLY, OTHER QUANTITIES OF INTEREST ARE CALCULATED IN THIS BLOCK *)
343
344      SINGLESPACE.
345      QHOT = ((1.0-PWR(TSH[1],NP1)+GAMA-GAMA*PWR(TSH[1],NP1))*L3[1]/(X[1]+1)*NP1)/(1.0+GAMA*NP1/NP1);
346      QCOLD = (PWR(TSH[1],NP1)-PWR(TCH[1],NP1)+GAMA*PWR(TSH[1],NP1)-GAMA*PWR(TCH[1],NP1))*L3[1]/(X[1]*NP1);
347      QCOLD = QCOLD/(1.0+GAMA*NP1/NP1);
348      SCOLD = QCOLD/TCH[1];
349      STOTAL[1] = SCOLD-QHOT;
350      FOR J = 1 TO I DO STOTAL[1] = STOTAL[1]+SISH[J];
351      SMIN[1] = SIMPSON(TCH[1]);
352      STOTMIN[1] = STOTAL[1]/SMIN[1];
353      SMAI[1] = ((1.0-PWR(TCH[1],NP1)+GAMA-GAMA*PWR(TCH[1],NP1))*(1.0/TCH[1]-1.0)/NP1)/(1.0+GAMA*NP1/NP1);
354      SMAI[1] = SMAI[1]/SMIN[1];
355
356
357      IF (<)0.5 THEN P[1+1] = 1.0/P[1];
358      SINGLESPACE.
359      WRITELN('      COLD WALL / HOT WALL TEMPERATURE RATIO      = ',TCH[1],14,6);
360      WRITELN('      HEAT OUT AT COLD WALL      = ',QCOLD,14,6);
361      WRITELN('      HEAT IN AT HOT WALL      = ',QHOT,14,6);
362      WRITELN('      ENTROPY PRODUCTION RATE AT COLD WALL      = ',SCOLD,14,6);
363      WRITELN('      ENTROPY PRODUCTION RATE AT HOT WALL      = ',-QHOT,14,6);
364      WRITELN('      MINIMUM ENTROPY PRODUCTION RATE      = ',SMIN[1],14,6);
365      WRITELN('      MAXIMUM ENTROPY PRODUCTION RATE      = ',SMAI[1],14,6);
366      WRITELN('      TOTAL ENTROPY PROD. RATE WITH ',I,2,' SHIELDS      = ',STOTAL[1],14,6);
367      WRITELN('      MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO      = ',SMAI[1],14,6);
368      WRITELN('      TOTAL / MINIMUM ENTROPY PRODUCTION RATIO      = ',STOTMIN[1],14,6);
369      SINGLESPACE.
370      SINGLESPACE.
371      SINGLESPACE.
372
373      END.
374      PFCN;
375      READLN;
376      READ(PFC);
377      END
378      END
379  /EOP

```

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----&gt; M N NS GAMA P[1] &lt;----

WHERE: M ----- 1ST. POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 N ----- 2ND. POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 NS ----- NUMBER OF SHIELDS  
 GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION  
 >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION  
 P[1] -- 1ST. SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1

? 1.0 3.0 1 2.5 15.0

THERMAL CONDUCTIVITY OF THE INSULATION IS  $K = K1*T**1.0 + K2*T**3.0$   
 $[K2*(M+1)]/[K1*(N+1)]*THOT**(N-M) = 2.50$

NUMBER OF SHIELDS = 1

NUMBER OF ITERATIONS = 35

HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.43837	1.85659	0.36744	0.23611
COLD WALL / HOT WALL TEMPERATURE RATIO	= 0.015741		
HEAT OUT AT COLD WALL	= 0.014350		
HEAT IN AT HOT WALL	= 0.452719		
ENTROPY PRODUCTION RATE AT COLD WALL	= 0.911631		
ENTROPY PRODUCTION RATE AT HOT WALL	= -0.452719		
MINIMUM ENTROPY PRODUCTION RATE	= 1.000503		
MAXIMUM ENTROPY PRODUCTION RATE	= 18.236148		
TOTAL ENTROPY PROD. RATE WITH 1 SHIELDS	= 2.315503		
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO =	18.226982		
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO =	2.314340		

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----&gt; M N NS GAMA P[1] &lt;----

WHERE: M ----- 1ST. POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 N ----- 2ND. POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 NS ----- NUMBER OF SHIELDS  
 GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION  
 >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION  
 P[1] -- 1ST. SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1

? 1.0 .090 2 0.0 25.0

THERMAL CONDUCTIVITY OF THE INSULATION IS  $K = K1*T**1.0$

NUMBER OF SHIELDS = 1

NUMBER OF ITERATIONS = 23

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HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.75466	7.03151	0.35870	0.10732

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.004293
HEAT OUT AT COLD WALL	=	0.016030
HEAT IN AT HOT WALL	=	0.770687
ENTROPY PRODUCTION RATE AT COLD WALL	=	3.734070
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.770687
MINIMUM ENTROPY PRODUCTION RATE	=	3.504633
MAXIMUM ENTROPY PRODUCTION RATE	=	115.966533
TOTAL ENTROPY PROD. RATE WITH 1 SHIELDS	=	9.994893
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	33.089491
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	2.851908

NUMBER OF SHIELDS = 2  
NUMBER OF ITERATIONS = 36

HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.05470	2.71297	0.17465	0.02016
SHIELD 2 0.88421	4.70678	0.48690	0.18786

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.000806
HEAT OUT AT COLD WALL	=	0.001162
HEAT IN AT HOT WALL	=	0.940073
ENTROPY PRODUCTION RATE AT COLD WALL	=	1.440716
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.940073
MINIMUM ENTROPY PRODUCTION RATE	=	3.921467
MAXIMUM ENTROPY PRODUCTION RATE	=	619.477774
TOTAL ENTROPY PROD. RATE WITH 2 SHIELDS	=	7.920388
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	157.970919
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	2.019751

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0

0.175 CP SECs. 124158 CM USED.

## PROGRAM SHIELD

```
1 00010 REM THIS IS A "BASIC" PROGRAM TO CALCULATE OPTIMUM TEMPERATURES.
2 00020 REM LOCATIONS, AND COOLING LOADS FOR COOLED SHIELDS IN A CRYOGENIC
3 00030 REM INSULATION SYSTEM WHOSE THERMAL CONDUCTIVITY FOLLOWS THE RELATION
4 00040 REM  $K=C1*T^M0 + C2*T^M1$ 
5 00045 REM MODIFIED IN LATE NOV. 1982.
6 00050 REM
7 00060 REM DEFINITION OF SYMBOLS USED
8 00070 REM
9 00080 REM COLD-SIDE WALL TEMPERATURE TO
10 00090 REM WARM-SIDE WALL TEMPERATURE T9
11 00100 REM SPACING BETWEEN SHIELDS AT I+1 AND I-1 L1(I)
12 00110 REM OVERALL THICKNESS OF INSULATION L
13 00120 REM LOCAL SPACING RATIO, L1(I)/L1(I-1), L2(I)
14 00130 REM OVERALL SPACING RATIO, L/L1(I), L4(I)
15 00140 REM (DISTANCE FROM COLD WALL)/L LS(I)
16 00150 REM I-TH SHIELD TEMPERATURE T(I)
17 00160 REM I-TH SHIELD POSITION RATIO X(I)
18 00170 REM I-TH SHIELD TEMPERATURE RATIO P(I) (ALWAYS >1)
19 00180 REM I-TH COLD-WARM TEMPERATURE RATIO R(I) (ALWAYS <1)
20 00190 REM I-TH DIMENSIONLESS ENTROPY PRODUCTION RATE S(I)
21 00195 REM I-TH DIMENSIONLESS HEAT REMOVAL RATE Q(I)
22 00210 REM TOTAL DIMENSIONLESS ENTROPY PROD. RATE S2(I)
23 00220 REM MINIMUM ENTROPY PRODUCTION RATE S0(I)
24 00230 REM ENTROPY PROD. RATE WITHOUT SHIELDS S9(I)
25 00240 REM ENTROPY PROD. RATE RATIOS S1=S2/S0 AND S4=S9/S0
26 00250 REM NUMBER OF SHIELDS M (= OR 10)
27 00260 REM
28 00265 DIM C(10),X(10)
29 00270 PRINT " "
30 00280 PRINT "INPUT 1 IF MORE WORK IS TO BE DONE, 0 IF FINISHED"
31 00290 INPUT A
32 00300 IF A=0 THEN 01350
33 00310 PRINT "INPUT M0,NO,M,CALMA & P(I)"
34 00320 INPUT M0,NO,M,C0,P(I)
35 00325 DEF FND(Y)=(M0+1)*Y^M0-M0/(Y^(1-M0))-1/(Y^Y)
36 00330 DEF FNE(Y)=(NO+1)*Y^NO-NO/(Y^(1-NO))-1/(Y^Y)
37 00335 DEF FNG(Y)=Y^(NO+1)-Y^M0+1/Y-1
38 00340 DEF FNC(Y)=Y^(NO+1)-Y^NO+1/Y-1
39 00350 PRINT " EXPONENT M0=",M0," EXPONENT NO=",NO," CALMA=",C0
40 00355 M1=M0+1
41 00358 N1=NO+1
42 00360 FOR I=1 TO M
43 00370 I1=I-1
44 00380 I2=I-2
45 00390 R(I)=.000001
46 00400 C=1
47 00410 D=1
48 00420 P1=P(I)*R(I)
49 00430 W1=(R(I))^(M0+FNC(P(I))+C0*R(I)^(M0+FNC(P(I))))
50 00435 W2=((R(I))^(M0-1)*FND(P(I))+C0*R(I)^(M0-1)*FNE(P(I)))^2
51 00438 W3=((FND(P(I))+C0*FNE(P(I)))^2)/(FNC(P(I))+C0*FNG(P(I)))
52 00439 C=W2/W1+W3
53 00440 G1=C*D
54 00450 IF G1>0 THEN 00500
55 00460 IF G1<0 THEN 00570
56 00470 C=-1/C
57 00480 IF ABS(C)<.000001 THEN 00570
58 00490 D=-D
59 00500 R(I)=R(I)+C
60 00510 IF R(I)>0 999999 THEN 00540
61 00520 IF R(I)<0 .000001 THEN 00540
62 00530 GOTO 00420
63 00540 R(I)=R(I)-.9*C
64 00550 C=.1*C
65 00560 GOTO 00420
66 00570 U=(R(I))^(NO-1)*FND(P(I))+C0*R(I)^(NO-1)*FNE(P(I))
67 00575 X1(I)=U/(FND(P(I))+C0*FNE(P(I)))
68 00580 X(I)=X1(I)/(1+X1(I))
69 00590 V=(FNC(P(I))+C0*FNG(P(I)))/(1-X(I))
70 00595 S(I)=V*(R(I))^(M0+FNC(P(I))+C0*R(I)^(M0+FNC(P(I)))/X(I))
71 00596 S(I)=S(I)/(1+C0*M1/M1)/M1
72 00600 IF I>1 THEN 00470
73 00610 L3(I)=1
74 00620 R0(I)=R(I)
```

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75 00630 T1(I)=R0(I)*P(I)
76 00640 L4(I)=1
77 00650 LS(I)=E(I)
78 00660 GOTO 01030
79 00670 L2(I)=(1-X(I-1))/X(I)
80 00680 IF I>2 THEN 00720
81 00690 L4(2)=X(1)+(1-X(1))/X(2)
82 00700 R0(2)=R(2)/P(1)
83 00710 GOTO 00930
84 00720 IF I>3 THEN 00740
85 00730 L4(3)=1+(1-X(1))*(1-X(2))/(X(2)*X(3))
86 00740 R0(3)=R(3)/(P(1)*P(2))
87 00750 GOTO 00930
88 00760 B=1
89 00770 L4(I)=0
90 00780 FOR J=2 TO I2
91 00790 B=B*X(I,J)
92 00800 L4(I)=L4(I)+B
93 00810 NEXT J
94 00820 L4(I)=L4(I)*(1-X(I))+1
95 00830 LO=1-X(I)
96 00840 FOR J=2 TO I1
97 00850 EO=LO*X(I,J)
98 00860 NEXT J
99 00870 EO=LO*X(I)
100 00880 L4(I)=L4(I)+EO
101 00890 R0(I)=R(I)
102 00900 FOR J=1 TO I1
103 00910 R0(I)=R0(I)/P(J)
104 00920 NEXT J
105 00930 L3(I)=L4(I)
106 00940 LS(I)=X(I)/L3(I)
107 00950 FOR J=1 TO I
108 00960 L3(J)=L3(I-1)/L2(J)
109 00970 LS(J)=LS(I-1)+X(J)/L3(J)
110 00980 NEXT J
111 00990 T1(I)=R0(I)*P(I)
112 01000 FOR J=1 TO I
113 01010 T1(J)=T1(I-1)*P(J)
114 01020 NEXT J
115 01030 T1(I+1)=1
116 01040 PRINT" "
117 01050 PRINT" I=";I
118 01060 PRINT" "
119 01070 T2(I)=R0(I)
120 01080 FOR J=2 TO I
121 01090 T2(J)=T2(I-1)
122 01100 NEXT J
123 01110 L3(I+1)=L3(I)
124 01120 T(I+1)=1-X(I)
125 01130 FOR J=1 TO I
WIDE LINE
126 01140 Z1=((T1(I+1)*M1-T1(I)*M1)*L3(I+1))/X(I+1)-(T1(I)*M1-T1(I)*M1)*L3(I)/X(I))/M1
WIDE LINE
127 01150 Z2=((T1(I+1)*M1-T1(I)*M1)*L3(I+1))/X(I+1)-(T1(I)*M1-T1(I)*M1)*L3(I)/X(I))/M1
128 01160 G(J)=Z1+G0*Z2/((1+G0*M1)/M1)
129 01170 S1(J)=Q(J)/T1(I)
130 01180 PRINT" J=";J;" Q=";Q(J);"; S1=";S1(J);"; LS=";LS(J);"; T/T9=";T1(I)
131 01190 NEXT J
132 01152 Q9=(1-T1(I)*M1+G0-G0*T1(I)*M1)*L3(I)/(X(I+1)*M1)
133 01153 Q9=Q9/(1+G0*M1/M1)
134 01154 Q0=(T1(I)*M1-R0(I))*M1+G0*T1(I)*M1-G0=R0(I)*M1*L3(I)/(X(I)*M1)
135 01155 Q0=Q0/(1+G0*M1/M1)
136 01156 S0=Q0/R0(I)
137 01160 S2(I)=S0-Q9
138 01162 REM CALCULATING DATA TO GET SMIN
139 01163 D=(1-R0(I))/100
140 01164 FOR L=1 TO 101
141 01165 C(L)=R0(I)*D*(L-1)
142 01166 Y(L)=C(L)*M0+G0*M1/M1*C(L)*M0+0 S/C(L)
143 01167 NEXT L
144 01170 FOR J=1 TO I
145 01180 S2(I)=S2(I)+S1(J)
146 01190 NEXT J
147 01201 REM OBTAIN SMIN USING SIMPSON'S RULE
148 01202 H=Y(I)+Y(101)

```

```
149 01203 FOR K=2 TO 100
150 01204 IF K/2=INT(K/2) THEN 01207
151 01205 H=H+2*Y(K)
152 01206 GO TO 01208
153 01207 H=H+4*Y(K)
154 01208 NEXT K
155 01210 S0(I)=((D/3*H)^2)/(1+G0*N1/M1)
156 01220 S3(I)=S2(I)/S0(I)
157 01230 S9(I)=((1-R0(I)*M1+G0*R0(I)*N1)*(1/R0(I)-1)/M1)/(1+G0*N1/M1)
158 01240 S4(I)=S9(I)/S0(I)
159 01250 IF I=M THEN 01270
160 01260 P(I,:)=1/P1
161 01270 PRINT"
162 01280 PRINT" P=";P(I);" R=";R(I);" X=";X(I);" X1=";X1(I);" S=";S(I)
163 01290 PRINT" L2=";L2(I);" L4=";L4(I)
164 01291 PRINT"
165 01292 PRINT" COLD WALL/HOT WALL TEMPERATURE RATIO, T0/T9=";R0(I)
166 01293 PRINT" HEAT OUT AT COLD WALL=";R0(I) ".00" HEAT IN AT WARM WALL=";R0(I) ".09"
167 01295 PRINT" ENTROPY PRODUCTION RATE AT COLD WALL=";S0(I)
168 01297 PRINT" ENTROPY PRODUCTION RATE AT WARM WALL=";S9(I)
169 01300 PRINT" MINIMUM ENTROPY PRODUCTION RATE, S0=";S0(I)
170 01301 PRINT" ENTROPY PRODUCTION RATE FOR I, SHIELDS, S2=";S2(I)
171 01304 PRINT" MAXIMUM ENTROPY PRODUCTION RATE, S9=";S9(I)
172 01310 PRINT" ENTROPY PRODUCTION RATE RATIOS, S3=S2/S0 AND S4=S9/S0"
173 01320 PRINT" S3=";S3(I);" S4=";S4(I)
174 01330 NEXT I
175 01340 GOTO 00270
176 01350 END
177 'ECP
```

## NEWRAF

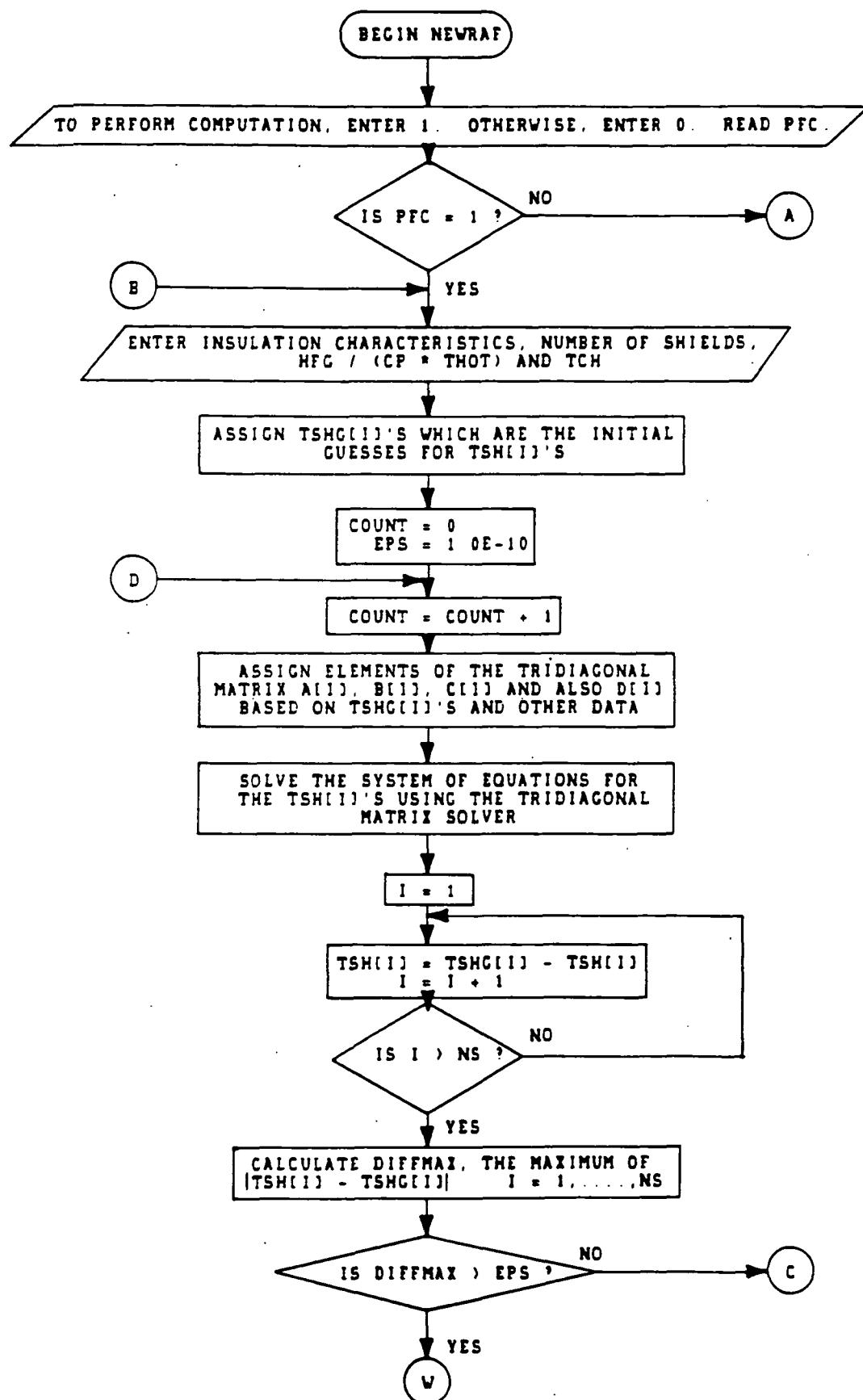
This program solves the original, complete, constrained optimization equations developed in Ref. [9] without the simplifying assumption suggested there which eliminated the dimensionless parameter,  $h_{fg}/C_p T_H$ . Only single-term thermal conductivity functions were considered in this analysis.

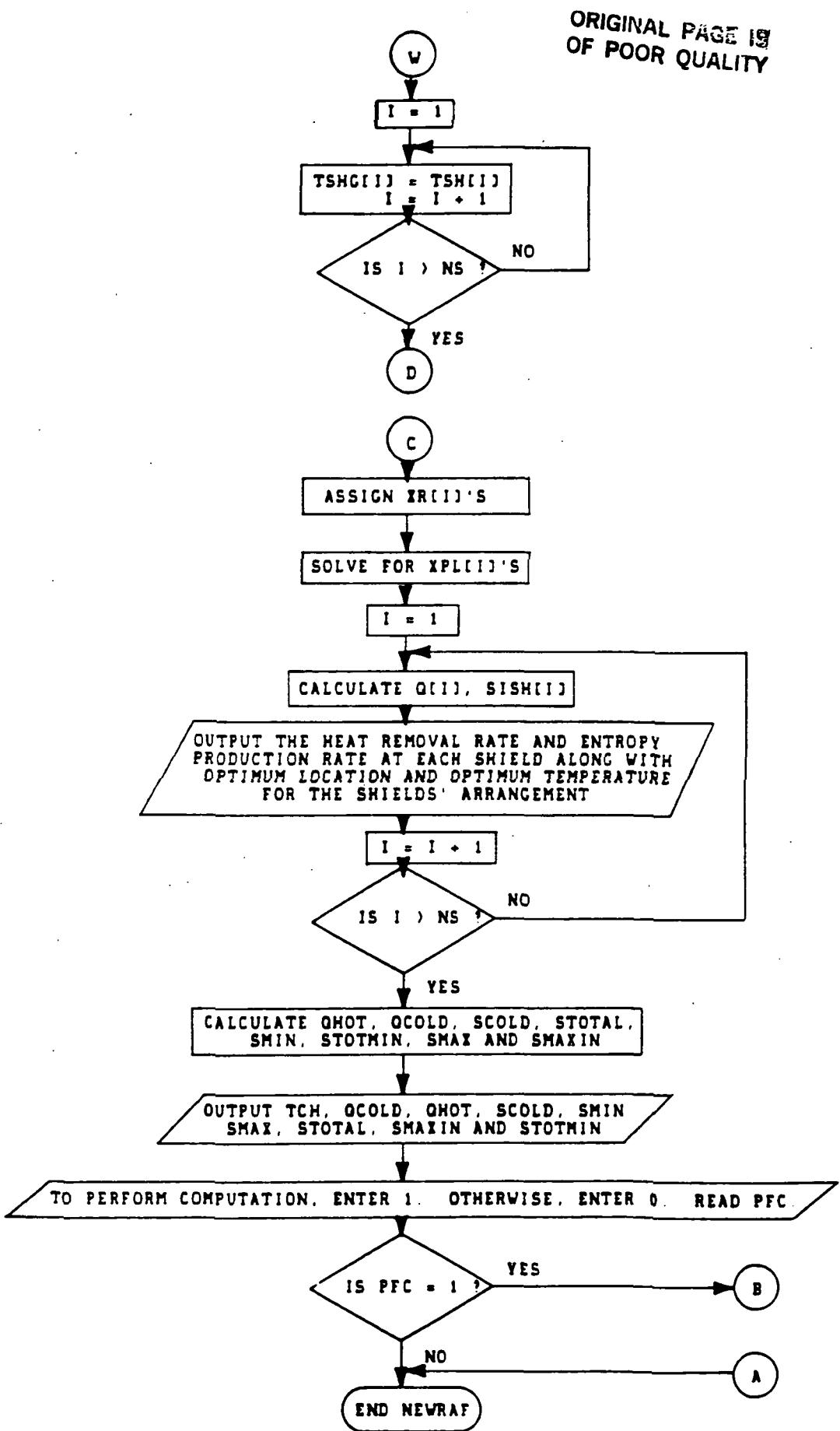
This program also recycles to the starting point. Consequently, the first input is either a 1, if a calculation is to be performed, or a 0, if no more work is to be done.

Next the program requests input of the insulation's characteristics, specifically, the exponent of temperature in the thermal conductivity function, the number of cooled shields, the dimensionless parameter  $h_{fg}/C_p T_H$  for the boiloff from the insulated container, and  $R = T_C/T_H$ .

The output specifies the optimal characteristics of the given number of shields with the constraint that the cooling capacity is limited to the boiloff of the liquid due only to the heat leak through the insulation itself.

The flow chart and a program sample follows.





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80      BOLD      : REAL.          (* DUMMY VARIABLE USED IN SOLVING THE TRIDIAGONAL MATRIX *)
81      COUNT     : INTEGER.       (* NUMBER OF ITERATIONS NEEDED TO DETERMINE TSH(I,I)'S *)
82      DELTAT0,DEN : REAL.          (* DUMMY VARIABLES *)
83      DIFF,DIFFMAX : REAL.         (* DUMMY VARIABLES USED IN CHECKING CONVERGENCE *)
84      DIV,DMAX,DMIN : REAL.        (* DUMMY VARIABLES USED IN SOLVING THE TRIDIAGONAL MATRIX *)
85      EPS       : REAL.          (* A SMALL VALUE USED TO OBSERVE IF CONVERGENCE IS OBTAINED *)
86      GI,GIM1,GIP1 : REAL.        (* DUMMY VARIABLES *)
87      GOLD      : REAL.          (* DUMMY VARIABLE USED IN SOLVING THE TRIDIAGONAL MATRIX *)
88      I,I       : INTEGER.       (* INDICES FOR LOOPS *)
89      ITERIN    : INTEGER.       (* INDEX USED TO TERMINATE ITERATIONS *)
90      M       : REAL.          (* POWER OF THE THERMAL CONDUCTIVITY EQUATION *)
91      MM1      : REAL.          (* EQUALS M-1 *)
92      MP1      : REAL.          (* EQUALS M+1 *)
93      NS       : INTEGER.       (* NUMBER OF SHIELDS *)
94      NSPI     : INTEGER.       (* EQUALS NS+1 *)
95      PFC      : INTEGER.       (* PROGRAM FLOW CONTROLLER *)
96      TCH      : REAL.          (* COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 ) *)
97      TIL,TIM1 : REAL.          (* DUMMY VARIABLES *)
98      QCOLD    : REAL.          (* HEAT OUT AT COLD WALL *)
99      QHOT    : REAL.          (* HEAT IN AT HOT WALL *)
00      QCOLD    : REAL.          (* ENTROPY PRODUCTION RATE AT COLD WALL *)
01      ITOTAL   : REAL.          (* SUM OF TSH(I,I)'S, SHOULD EQUAL 1 AFTER SUCCESSFUL COMPUTATION *)
02
03
04
05
06 PROCEDURE INPUT();
07 BEGIN          (* INPUT OF DATA HEADING *)
08   WRITELN;
09   WRITELN;      ENTER ----) M NS BETA TCH <----);
10   WRITELN;      WHERE M ---- POWER IN THE THERMAL CONDUCTIVITY EQUATION';
11   WRITELN;      NS ---- NUMBER OF SHIELDS';
12   WRITELN;      BETA -- HFG / (CP*THOT');
13   WRITELN;      HFG -- HEAT OF VAPORIZATION [J/KG];
14   WRITELN;      CP ---- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K];
15   WRITELN;      THOT -- HOT WALL TEMPERATURE [K];
16   WRITELN;      TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 );
17   WRITELN;      (* INPUT OF DATA HEADING *)
18 END;
19
20
21
22 PROCEDURE PFC();
23 BEGIN          (* PFC *)
24   WRITELN;
25   WRITELN;      TO PERFORM COMPUTATION, ENTER 1, OTHERWISE, ENTER 0 );
26   WRITELN;
27 END;          (* PFC *)
28
29
30
31
32 PROCEDURE SINGLESPACE();
33 BEGIN          (* SINGLE SPACE IN OUTPUT *)
34   WRITELN(' ');
35 END;          (* SINGLE SPACE IN OUTPUT *)
36
37
38
39 FUNCTION PWR(X,E REAL) REAL;
40 VAR
41   A      : REAL;
42 BEGIN          (* COMPUTE X**E *)
43   A :=LN(X);
44   PWR :=EXP(A);
45 END;          (* COMPUTE X**E *)
46
47
48
49 FUNCTION MAJOF2(N01,N02 REAL) REAL;
50 BEGIN          (* DETERMINES THE LARGEST OF THE TWO GIVEN NUMBERS *)
51   IF N01>N02 THEN
52     IF N01=N02 THEN
53       MAJOF2 :=N01;
54     ELSE
55       MAJOF2 :=N02;
56     ELSE
57       MAJOF2 :=N01;
58 END;          (* DETERMINES THE LARGEST OF THE TWO GIVEN NUMBERS *)
59

```

```
60
61
62 FUNCTION MINOF2(N01,N02:REAL):REAL;
63 BEGIN          (* DETERMINES THE SMALLEST OF THE TWO GIVEN NUMBERS *)
64   IF N01<N02 THEN
65     IF N01>N02 THEN
66       MINOF2:=N02
67     ELSE
68       MINOF2:=N01
69     ELSE
70       MINOF2:=N01
71   END;           (* DETERMINES THE SMALLEST OF THE TWO GIVEN NUMBERS *)
72
73
74
75
76
77
78
79   (* MAIN PROGRAM BODY *)
80
81 BEGIN
82   PEGH;
83   READLN;
84   READLN(PEGH);
85   WHILE PEGH=1 DO
86   BEGIN
87
88     (* THIS BLOCK IS USED TO INPUT THE INSULATION THERMAL CONDUCTIVITY, NUMBER *)
89     (* OF SHIELDS, HFG/(CP*THOT) AND COLD WALL / HOT WALL TEMPERATURE RATIO *)
90
91     INPUTH;
92     READLN;
93     READLN(NS,BETA,TCH);
94     SINGLESPACE;
95     WRITELN('   THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**',M 3 1),
96     WRITELN('   HFG / (CP*THOT) = ',BETA,' S');
97     SINGLESPACE;
98     SINGLESPACE;
99
100
101   MFL :=M+1 0;
102   MM1 :=M+1 0;
103
104   (* INITIAL GUESSED VALUES FOR TSHG(J)'S ARE ENTERED *)
105
106   DELTATC :=(1 0-TCH)/(NS+1 0);
107   FOR J :=1 TO NS DO TSHG(J):=J*DELTATC+TCH;
108
109   (* VARIABLE USED TO CHECK CONVERGENCE CRITERION IS SET AND THE ITERATIVE PROCEDURE *)
110   (* OF NEWTON-RAPHSON METHOD IS STARTED *)
111
112   EES :=1 0E-10;
113   COUNT :=0;
114   ITERMN :=0;
115   REPEAT
116     COUNT :=COUNT+1;
117     FOR I :=1 TO NS DO
118     BEGIN
119       D1 :=TSHG(I);
120       IF NS<1 THEN
121         IF I<1 THEN
122           IF I<NS THEN
123             BEGIN
124               C1M1 :=TSHG(I-1);
125               C1P1 :=TSHG(I+1);
126             END;
127           ELSE
128             BEGIN
129               C1M1 :=TSHG(I-1);
130               C1P1 :=1 0;
131             END;
132           ELSE
133             BEGIN
134               C1M1 :=TCH;
135               C1P1 :=TSHG(I+1);
136             END;
137           ELSE
138             BEGIN
139               C1M1 :=TCH;
```

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```

20      TIM1=TCH
21      ELSE
22          TIM1=TCH;
23          IR111=(MPI*PWR(T1,M)*(T1-TIM1))/(PWR(T1,MPI)-PWR(TIM1,MPI));
24      END.
25      DEN=1.0;
26      FOR I=1 TO NS DO DEN=DEN*IR111-I+1.0;
27      NSP1=NS+1;
28
29          (* FINALLY, SPACINGS BETWEEN SHIELDS AND OTHER QUANTITIES OF INTEREST ARE CALCULATED *)
30
31      X111=1.0/DEN;
32      XPL111=X111;
33      ITOTAL=X111;
34      FOR I=2 TO NSP1 DO
35          BEGIN
36              X111=X111-IR111;
37              IF I>NSP1 THEN XPL111=XPL111*X111;
38              ITOTAL=ITOTAL*X111
39          END.
40      IF (ABS(ITOTAL-1.0) > 1.0E-5) THEN GOTO 100.
41      Q111=(PWR(TSH111,MPI)-PWR(TCH,MPI))/(X111*MPI);
42      Q1NSP11=(1.0-PWR(TSH1NS,MPI))/(X1NSP11*MPI);
43      FOR I=2 TO NS DO Q111=(PWR(TSH111,MPI)-PWR(TSH111-1,MPI))/(X111*MPI);
44      SINGLESPACE.
45      WRITEIN:   NUMBER OF SHIELDS  = ',NS 2,
46      WRITEIN:   NUMBER OF ITERATIONS = ',COUNT 2);
47      SINGLESPACE.
48      WRITEIN:
49      WRITEIN:           HEAT REMOVAL      ENTROPY PRODUCTION      OPTIMUM      OPTIMUM
50      WRITEIN:           RATE          RATE          LOCATION      TEMPERATURE
51      WRITEIN:           -----          -----          -----          -----
52      SINGLESPACE.
53      FOR I=1 TO NS DO
54          BEGIN
55              Q111=Q111+1.0-Q111;
56              SISH111=Q111/TSH111;
57              WRITEIN:   SHIELD ',I,2,'  = $,000.0 5.1' ',1,5,SH111 9.5,' '9,XPL111 9.5,' '5,TSH111 9.5)
58          END.
59      SINGLESPACE.
60      SINGLESPACE.
61      QHOT=Q1NSP11;
62      QCOLD=Q111;
63      SCOLD=QCOLD/TCH;
64      STOTAL=SCOLD-QHOT;
65      FOR J=1 TO NS DO STOTAL=STOTAL+SISH111;
66      IF MDOO 0 THEN
67          SMIN=SQR((1.0-PWR(TCH,(M/2.0)))/(M/2.0))
68      ELSE
69          SMIN=SQR((1.0/TCH));
70      STOTHIN=STOTAL/SMIN;
71      SMAX=(1.0-PWR(TCH,MPI))*(1.0/TCH-1.0)/MPI;
72      SMAIN=SMAX/SMIN;
73      SINGLESPACE.
74      WRITEIN:   COLD WALL / HOT WALL TEMPERATURE RATIO  = ',TCH 14.6),
75      WRITEIN:   HEAT OUT AT COLD WALL  = ',QCOLD 14.6),
76      WRITEIN:   HEAT IN AT HOT WALL  = ',QHOT 14.6),
77      WRITEIN:   ENTROPY PRODUCTION RATE AT COLD WALL  = ',SCOLD 14.6),
78      WRITEIN:   ENTROPY PRODUCTION RATE AT HOT WALL  = ',QHOT 14.6),
79      WRITEIN:   MINIMUM ENTROPY PRODUCTION RATE  = ',SHIN 14.6),
80      WRITEIN:   MAXIMUM ENTROPY PRODUCTION RATE  = ',SMAX 14.6),
81      WRITEIN:   TOTAL ENTROPY PROD. RATE WITH ',NS 2,' SHIELDS  = ',STOTAL 14.6),
82      WRITEIN:   MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO  = ',SMAIN 14.6),
83      WRITEIN:   TOTAL / MINIMUM ENTROPY PRODUCTION RATIO  = ',STOTHIN 14.6);
84      100 SINGLESPACE;
85      IF (DIV=0 0) OR (B11=0 0) THEN
86          BEGIN
87              SINGLESPACE.
88              WRITEIN:   ---) CHECK THE ASSEMBLY OF COEFFICIENTS TO BE USED IN TRIDIAGONAL MATRIX  (---),
89              WRITEIN:   ---) CHECK THE TRIDIAGONAL MATRIX SOLVER  (---)
90          END.
91      IF (ABS(ITOTAL-1.0) > 1.0E-5) THEN
92          BEGIN
93              SINGLESPACE.
94              WRITEIN:   ---) ITOTAL IS NOT EQUAL TO 1.0  (---);
95              WRITEIN:   ---) COMPUTATIONS ARE NOT CORRECT  (---)
96          END.
97      SINGLESPACE.
98      SINGLESPACE.
99

```

00 PFCH.  
01 READLN.  
02 READ(PFC)  
03 END  
04 END  
05 /EOF.

CONTINUE FROM PAGE  
OF INPUT

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M NS BETA TCH -----

WHERE: M ----- POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 NS ----- NUMBER OF SHIELDS  
 BETA -- HFG / (CP\*THOT)  
 HFG --- HEAT OF VAPORIZATION [J/KG]  
 CP ----- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K]  
 THOT -- HOT WALL TEMPERATURE [K]  
 TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS < 1

? 1.0 3 0.0145 0.001

Thermal Conductivity of the insulation is  $K = K1*T^{1.0}$   
 $HFG / (CP*THOT) = 0.01450$

NUMBER OF SHIELDS = 3  
 NUMBER OF ITERATIONS = 9

	HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1	0.10438	1.56143	0.09719	0.06685
SHIELD 2	0.25983	1.12595	0.28870	0.23076
SHIELD 3	0.47781	0.89782	0.58568	0.53219

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.001000
HEAT OUT AT COLD WALL	=	0.022985
HEAT IN AT HOT WALL	=	0.864998
ENTROPY PRODUCTION RATE AT COLD WALL	=	22.984544
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.864998
MINIMUM ENTROPY PRODUCTION RATE	=	3.751018
MAXIMUM ENTROPY PRODUCTION RATE	=	499.499501
TOTAL ENTROPY PROD. RATE WITH 3 SHIELDS	=	25.704743
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	133.163725
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	6.852738

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M NS BETA TCH -----

WHERE: M ----- POWER IN THE THERMAL CONDUCTIVITY EQUATION  
 NS ----- NUMBER OF SHIELDS  
 BETA -- HFG / (CP\*THOT)  
 HFG --- HEAT OF VAPORIZATION [J/KG]  
 CP ----- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K]  
 THOT -- HOT WALL TEMPERATURE [K]  
 TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS < 1

? 1.0 2 0.0154 0.000806

THERMAL CONDUCTIVITY OF THE INSULATION IS  $K = K1*T^{1.0}$   
 MFG / (CP\*THOT) = 0.01540

NUMBER OF SHIELDS = 2  
 NUMBER OF ITERATIONS = 8

	HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
	-----	-----	-----	-----
SHIELD 1	0.19732	1.97595	0.16252	0.09986
SHIELD 2	0.59037	1.48999	0.48495	0.39623

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.000806
HEAT OUT AT COLD WALL	=	0.030677
HEAT IN AT HOT WALL	=	0.818366
ENTROPY PRODUCTION RATE AT COLD WALL	=	38.061092
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.818366
MINIMUM ENTROPY PRODUCTION RATE	=	3.776103
MAXIMUM ENTROPY PRODUCTION RATE	=	619.846992
TOTAL ENTROPY PROD. RATE WITH 2 SHIELDS	=	40.708665
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	164.149921
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	10.780603

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0  
 0.072 CP SECs, 11471B CM USED.

/BYE:

3KMUFTC COSTS: 255.028 SRUS AT \$.0059 = \$1.50

## DESINS

This program optimizes the characteristics of a single cooled shield with different insulations on the two sides. Only one-term thermal conductivity functions are considered.

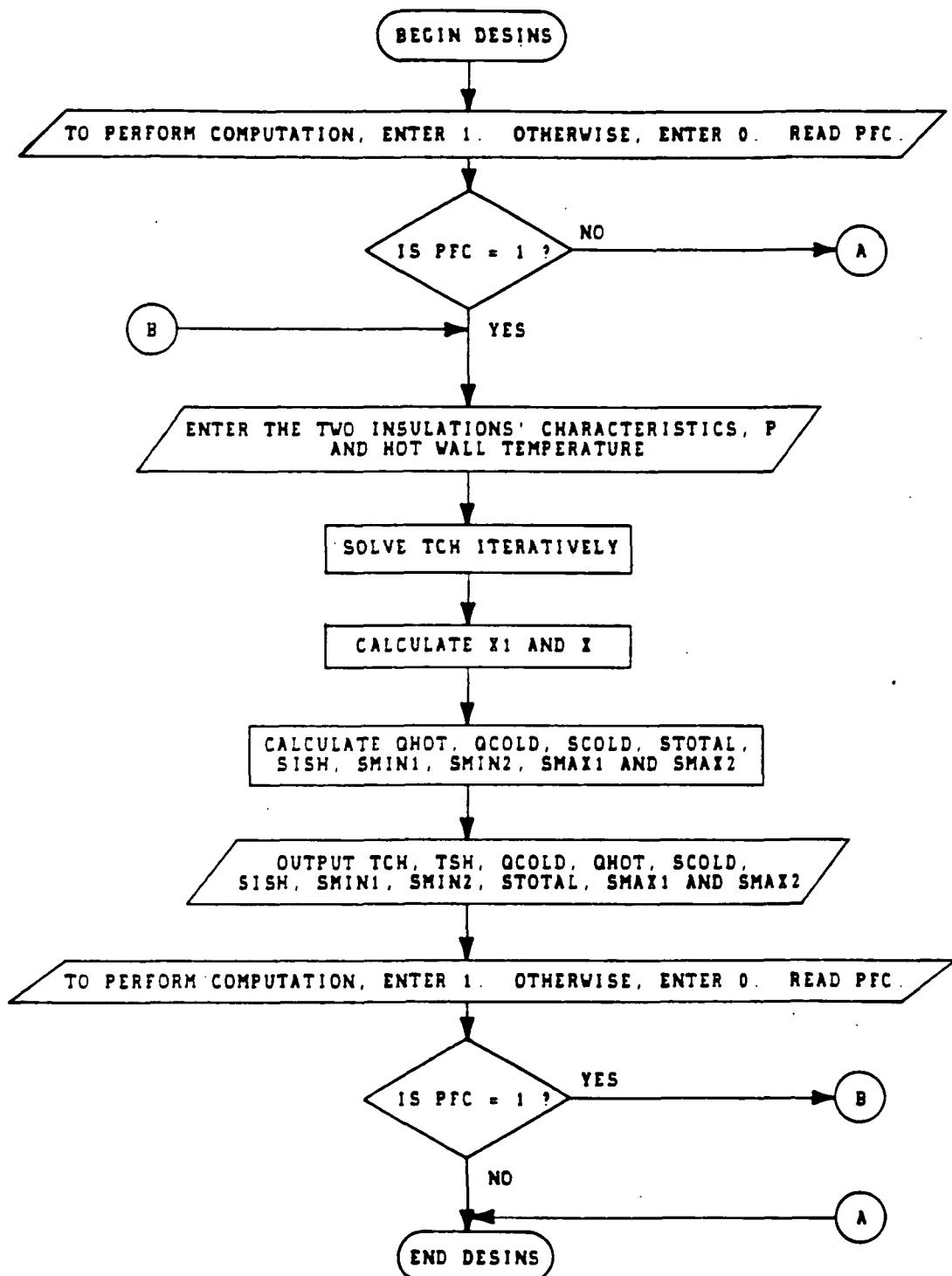
This program also recycles to the starting point; thus the first input is 1, if a calculation is to be performed, or 0 if no more work is to be done.

Next inputs are the characteristics of the two insulations, specifically, the exponents of temperature in the thermal conductivity functions on the hot and cold sides of the shield, a coefficient ratio ALFA (defined in the program), the shield to cold wall temperature ratio,  $P = T_S/T_C$ , and the hot wall temperature,  $T_H$ .

The output specifies the optimal characteristics of the cooled shield as well as other, related information.

The flow diagram and a program sample follows.

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5 (*****)
6 (*****)
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9 (*****)
10 (*****) ----- DESINS (*****)
11 (*****)
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16 (*****) URBANA, IL 61801
17 (*****)
18 (*****) JULY 1983
19 (*****)
20 (*****)
21 (*****)
22 (*****)
23 (*****)
24 (*****)
25 (*)
26 (* THIS PASCAL PROGRAM WAS DEVELOPED TO OPTIMIZE THE *)
27 (* LOCATION, TEMPERATURE AND HEAT DISSIPATION RATE *)
28 (* FOR A COOLED SHIELD IN A CRYOGENIC INSULATION *)
29 (* SYSTEM WHOSE THERMAL CONDUCTIVITY HAS THE FORM. *)
30 (*)
31 (* K = K1*(T**M)      ON THE HOT SIDE. *)
32 (* K = K2*(T**N)      ON THE COLD SIDE *)
33 (*)
34 (* THE METHOD IS BASED ON THE MINIMIZATION OF THE *)
35 (* ENTROPY PRODUCTION RATE WHICH IS PROPORTINAL TO *)
36 (* THE HEAT LEAK ACROSS THE INSULATION. *)
37 (*)
38 (*****)
39 (*****)
40 (*****)
41
42 LABEL 100.
43 LABEL 200.
44 LABEL 300.
45
46 VAR
47
48
49 P      REAL.          (* SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS 1 *)
50 SMA1:  REAL.          (* MAXIMUM ENTROPY PRODUCTION RATE BASED ON K1*T**M *)
51 SMA2:  REAL.          (* MAXIMUM ENTROPY PRODUCTION RATE BASED ON K2*T**N *)
52 SMIN:  REAL.          (* MINIMUM ENTROPY PRODUCTION RATE BASED ON K1*T**M *)
53 SMIN2: REAL.          (* MINIMUM ENTROPY PRODUCTION RATE BASED ON K2*T**N *)
54 STOTAL: REAL.          (* TOTAL DIMENSIONLESS ENTROPY PRODUCTION RATE *)
55 S1SH:  REAL.          (* DIMENSIONLESS ENTROPY PRODUCTION RATE AT SHIELD *)
56 TCH:   REAL.          (* COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 *)
57 TSH:   REAL.          (* SHIELD / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 *)
58 I:     REAL.          (* DISTANCE FROM COLD WALL / THICKNESS RATIO *)
59 I1:    REAL.          (* I / (1.0-I) *)
60
61
62 CC     REAL.          (* DUMMY VARIABLE *)
63 COUNT: INTEGER.        (* NUMBER OF ITERATIONS NEEDED TO DETERMINE TCH *)
64 DD     REAL.          (* DUMMY VARIABLE *)
65 ALFA:  REAL.          (* (K2*(N+1))/(K1*(M+1)) *)
66 S,C1:  REAL.          (* DUMMY VARIABLES *)
67 IND:   INTEGER.        (* INDEX TO TERMINATE THE SEARCH FOR TCH *)
68 M:     REAL.          (* POWER OF THE THERMAL CONDUCTIVITY ON HOT SIDE *)
69 MP1:   REAL.          (* EQUALS M+1 *)
70 N:     REAL.          (* POWER OF THE THERMAL CONDUCTIVITY ON COLD SIDE *)
71 NP1:   REAL.          (* EQUALS N+1 *)
72 PFC:   INTEGER.        (* PROGRAM FLOW CONTROLLER *)
73 OCOLD: REAL.          (* HEAT OUT AT COLD WALL *)
74 QHOT:  REAL.          (* HEAT IN AT HOT WALL *)
75 SCOLD: REAL.          (* ENTROPY PRODUCTION RATE AT COLD WALL *)
76 SCKM:  TEXT.          (* OUTPUT FILE TO BE USED IF DESIRED *)
77 THOT:  REAL.          (* HOT WALL TEMPERATURE (K) *)
78
79

```

```

80
81
82 PROCEDURE INPUTH;
83   BEGIN          (* INPUT OF DATA HEADING *)
84     WRITELN;
85     WRITELN('  ENTER ----) M  N  ALFA  P  THOT  (----)');
86     WRITELN('  ');
87     WRITELN('  WHERE: M ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE HOT SIDE');
88     WRITELN('  R ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE COLD SIDE');
89     WRITELN('  ALFA --  $(K2^M \cdot (M+1)) / (K1^N \cdot (N+1))$  ');
90     WRITELN('  P ----- SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1');
91     WRITELN('  THOT -- HOT WALL TEMPERATURE (K)');
92     WRITELN('  ');
93   END;          (* INPUT OF DATA HEADING *)
94
95
96
97 PROCEDURE PFCN;
98   BEGIN          (* PFCN *)
99     WRITELN;
100    WRITELN('  TO PERFORM COMPUTATION, ENTER 1 OTHERWISE, ENTER 0 ');
101    WRITELN;
102   END;          (* PFCN *)
103
104
105
106 PROCEDURE SINGLESPACE;
107   BEGIN          (* SINGLE SPACE IN OUTPUT *)
108     WRITELN('  ');
109   END;          (* SINGLE SPACE IN OUTPUT *)
110
111
112
113 FUNCTION PWR(X,E) REAL; REAL;
114   VAR
115     A;           REAL;
116   BEGIN          (* COMPUTE X^E *)
117     A=E*LN(X);
118     PWR=E*PI(A);
119   END;          (* COMPUTE X^E *)
120
121
122
123 FUNCTION D(E,X) REAL; REAL;
124   BEGIN          (* FUNCTIONAL D *)
125     D=(E+1.0)*PWR(X,E)-E/(PWR(X,(1.0-E)))-(1.0/SQR(X));
126   END;          (* FUNCTIONAL D *)
127
128
129
130 FUNCTION F(E,X) REAL; REAL;
131   BEGIN          (* FUNCTIONAL F *)
132     F=(PWR(X,(E+1.0))-PWR(X,E)-1.0+(1.0/X));
133   END;          (* FUNCTIONAL F *)
134
135
136
137
138
139
140
141   (* MAIN PROGRAM BODY *)
142
143 BEGIN
144   PFCN;
145   READLN;
146   READ(PFC);
147   WHILE PFC=1 DO
148   BEGIN
149
150     (* THIS BLOCK IS USED TO INPUT THE TWO INSULATION THERMAL CONDUCTIVITIES. *)
151     (* SHIELD / COLD WALL TEMPERATURE RATIO AND HOT WALL TEMPERATURE *)
152
153   INPUTH;
154   READLN;
155   READ(M,N,ALFA,P,THOT);
156   SINGLESPACE;
157   WRITELN('  THERMAL CONDUCTIVITY OF THE INSULATION ON THE HOT SIDE IS K =  $K1^M \cdot (M+1)^{-1}$  ');
158   WRITELN('  THERMAL CONDUCTIVITY OF THE INSULATION ON THE COLD SIDE IS K =  $K2^N \cdot (N+1)^{-1}$  ');
159   WRITELN('   $(K2^M \cdot (M+1)) / (K1^N \cdot (N+1)) = P$ , ALFA =  $P \cdot 2$  ');

```

160

WRITELN('  
SINGLESPEC  
SINGLESPEC

HOT WALL TEMPERATURE = ',THOT, ' K'),

82

161

MP1 = M+1.0;  
MP1 = M+1.0;  
TCH = 0.000001;  
CC = 0.1;  
DD = 1.0;  
COUNT = 0;ORIGINAL PAGE IS  
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171

(\* THIS BLOCK CALCULATES TCH ITERATIVELY \*)

173

REPEAT  
TSH = P\*TCH;  
G = D(N,P)\*D(N,P)/E(N,P) - PWR(TCH,(1.0-N))\*D(M,TSH)\*D(M,TSH)/E(M,TSH)/ALFA;  
G1 = G\*DD;  
IF G1<0.0 THEN GOTO 100;  
IF G1>0.0 THEN GOTO 200;  
CC = (-0.1)\*CC;  
IF ABS(CC)<0.000001 THEN GOTO 200;  
DD = -DD;  
100 TCH = TCH+CC;  
IF (TCH>0.99999) OR (TCH<0.00001) THEN  
BEGIN  
TCH = TCH-0.9\*CC;  
CC = 0.1\*CC;  
IF ABS(CC)<0.000001 THEN IND = 1  
END;  
200 COUNT = COUNT+1;  
UNTIL (G1=0.0) OR (ABS(CC)<0.000001) OR (IND=1);

192

193

IF IND=1 THEN  
BEGIN  
SINGLESPEC;  
SINGLESPEC;  
SINGLESPEC;  
WRITELN(' --- ) OPTIMUM CRITERION CANNOT BE SATISFIED (--- ),  
WRITELN(' --- ) USE SINGLE INSULATION WITH THE LOWER CONDUCTIVITY (--- ),  
GOTO 300  
END

203

204

(\* OTHER QUANTITIES OF INTEREST ARE COMPUTED IN THIS SECTION \*)

205

X = -ALFA\*PWR(TCH,(N-1.0))\*D(N,P)/D(M,TSH);  
I = X/(1.0+X);  
QHOT = (1.0-PWR(TSH,MP1))/((1.0-I)\*MP1);  
QCOLD = ALFA\*PWR(TCH,MP1)\*(PWR(P,MP1)-1.0)/(PWR(THOT,(M-N))\*I\*MP1);  
SCOLD = QCOLD/TCH;  
STOTAL = (F(M,TSH)\*(1.0-I)+ALFA\*PWR(TCH,N)\*E(N,P)/I)/MP1;  
SISH = QHOT-QCOLD/TSH;  
IF M=0.0 THEN  
SMIN1 = SQRT(N\*1.0/TCH);  
ELSE  
SMIN1 = SQRT((1.0-PWR(TCH,(M/2.0)))/(M/2.0));  
IF N=0.0 THEN  
SMIN2 = SQRT(N\*1.0/TCH);  
ELSE  
SMIN2 = SQRT((1.0-PWR(TCH,(N/2.0)))/(N/2.0));  
SMAX1 = F(M,TCH)/MP1;  
SMAX2 = F(N,TCH)/MP1;

223

224

SINGLESPEC;

226

WRITELN(' NUMBER OF ITERATIONS = ',COUNT,0);  
WRITELN(' COLD WALL / HOT WALL TEMPERATURE RATIO = ',TCH,14,6);  
WRITELN(' SHIELD / HOT WALL TEMPERATURE RATIO = ',TSH,14,6);  
WRITELN(' SHIELD LOCATION = ',I,14,6);  
WRITELN(' HEAT OUT AT SHIELD = ',QHOT-QCOLD,14,6);  
WRITELN(' HEAT OUT AT COLD WALL = ',QCOLD,14,6);  
WRITELN(' HEAT IN AT HOT WALL = ',QHOT,14,6);  
WRITELN(' ENTROPY PRODUCTION RATE AT COLD WALL = ',SCOLD,14,6);  
WRITELN(' ENTROPY PRODUCTION RATE AT HOT WALL = ',-QHOT,14,6);  
WRITELN(' ENTROPY PRODUCTION RATE AT SHIELD = ',SISH,14,6);  
WRITELN(' MINIMUM ENTROPY PRODUCTION RATE BASED ON K1\*T\*\*N = ',SMIN1,14,6);  
WRITELN(' MINIMUM ENTROPY PRODUCTION RATE BASED ON K2\*T\*\*N = ',SMIN2,14,6);  
WRITELN(' TOTAL ENTROPY PRODUCTION RATE = ',STOTAL,14,6);  
WRITELN(' ENTROPY PROD. W/O SHIELD BASED ON K1\*T\*\*N = ',SMAX1,14,6);

240        WRITEIN('        ENTROPY PROD W/O SHIELD BASED ON X2:T0:N        \*1,SWAZI 14-6).  
241        300 SINGLESPACE.  
242        SINGLESPACE.  
243        SINGLESPACE.  
244        PFCH.  
245        READIN.  
246        READ(PFC)  
247        END  
248        END

83

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TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----&gt; M N ALFA P THOT &lt;----

WHERE: M ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE HOT SIDE  
N ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE COLD SIDE  
ALFA --  $[K2^{(M+1)}]/[K1^{(N+1)}]$   
P ----- SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS  $\geq 1$   
THOT -- HOT WALL TEMPERATURE [K]

? 1.0 0.0 20.0 4.5 300.0

THERMAL CONDUCTIVITY OF THE INSULATION ON THE HOT SIDE IS  $K = K1^{(T^{**1.0})}$ .  
THERMAL CONDUCTIVITY OF THE INSULATION ON THE COLD SIDE IS  $K = K2^{(T^{**0.0})}$ .  
 $[K2^{(M+1)}]/[K1^{(N+1)}] = 20.00$   
HOT WALL TEMPERATURE = 300.00 [K]

NUMBER OF ITERATIONS	=	36
COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.001666
SHIELD / HOT WALL TEMPERATURE RATIO	=	0.007497
SHIELD LOCATION	=	0.390755
HEAT OUT AT SHIELD	=	0.820144
HEAT OUT AT COLD WALL	=	0.000497
HEAT IN AT HOT WALL	=	0.820641
ENTROPY PRODUCTION RATE AT COLD WALL	=	0.298568
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.820641
ENTROPY PRODUCTION RATE AT SHIELD	=	109.396253
MINIMUM ENTROPY PRODUCTION RATE BASED ON $K1^{(T^{**M})}$	=	3.680131
MINIMUM ENTROPY PRODUCTION RATE BASED ON $K2^{(T^{**N})}$	=	40.925828
TOTAL ENTROPY PRODUCTION RATE	=	178.307751
ENTROPY PROD. W/O SHIELD BASED ON $K1^{(T^{**M})}$	=	299.619216
ENTROPY PROD. W/O SHIELD BASED ON $K2^{(T^{**N})}$	=	598.241762

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0

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16. Abstract  <p>A relatively simple method has been developed to optimize the location, temperature, and heat dissipation rate of each cooled shield inside an insulation layer. The method is based on the minimization of the entropy production rate which is proportional to the heat leak across the insulation. The results show that the maximum number of shields to be used in most practical applications is three. However, cooled shields are useful only at low values of the overall, cold wall to hot wall absolute temperature ratio. The performance of the insulation system is relatively insensitive to deviations from the optimum values of the temperature and location of the cooling shields.</p> <p>Design curves are presented for rapid estimates of the locations and temperatures of cooling shields in various types of insulations, and an equation is given for calculating the cooling loads for the shields.</p>			
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